



Second Quarter FY 2026 Quarterly Update

Infineon Technologies AG
Investor Relations



Infineon at a glance

Addressing long-term high-growth trends



Energy
green and efficient

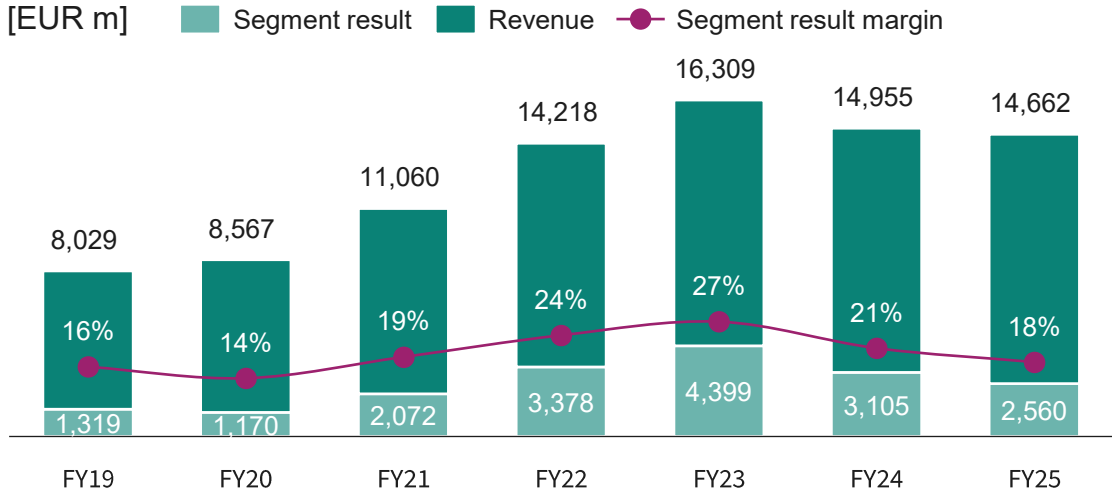


Mobility
clean and safe



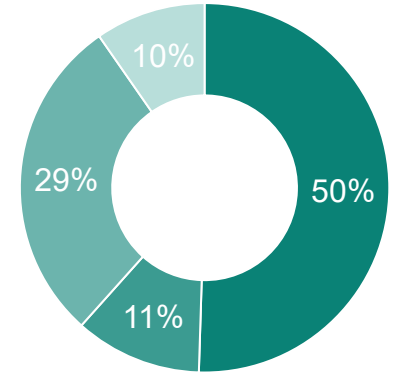
IoT
smart and secure

Financials

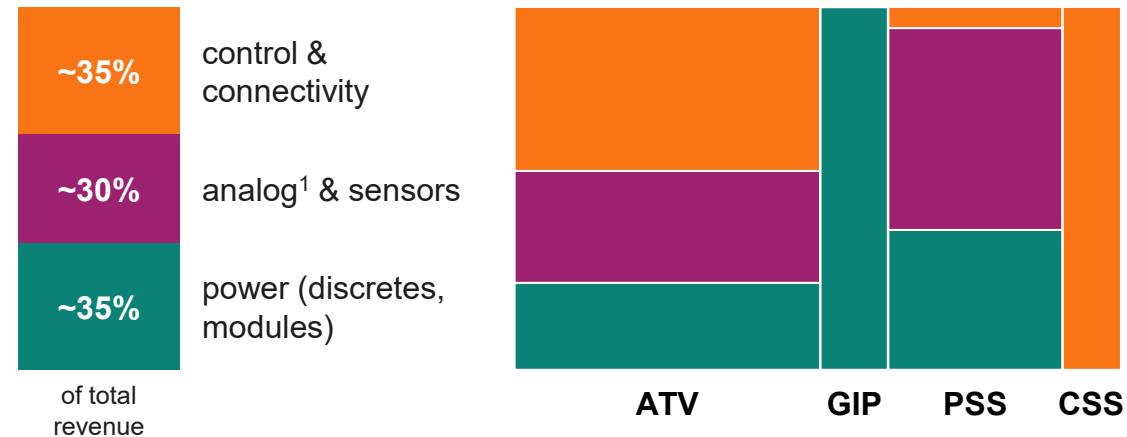


FY25 revenue by segment

- Automotive (ATV)
- Green Industrial Power (GIP)
- Power & Sensor Systems (PSS)
- Connected Secure Systems (CSS)



FY25 revenue by product category

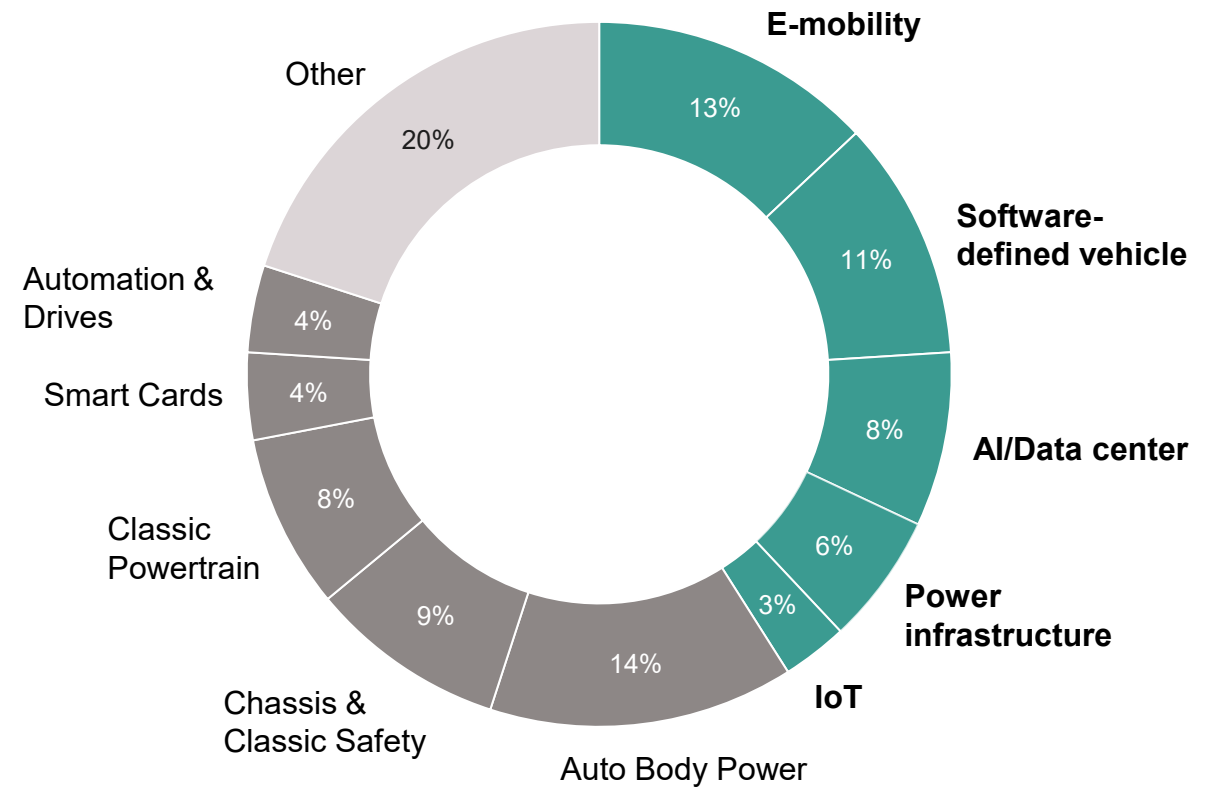
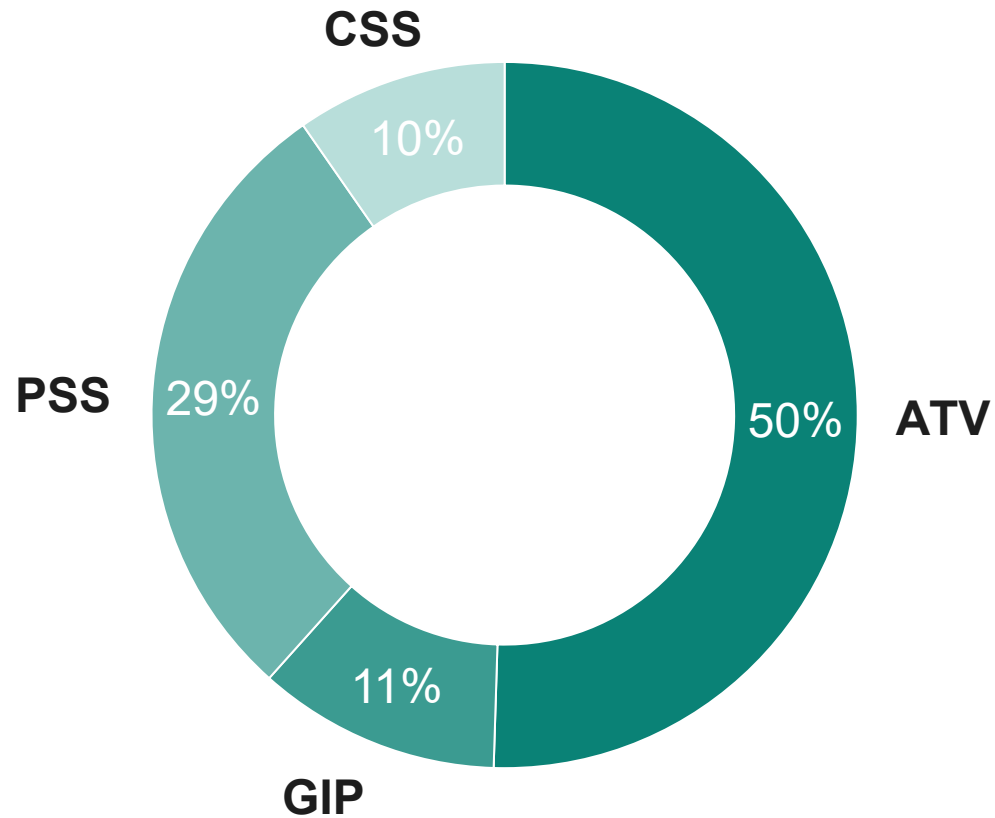


¹ including <5% of differentiating memory technologies

Well-balanced portfolio among segments and key applications, highest growth coming from Decarbonization and Digitalization



FY25 revenue of €14,662m by segment and key application



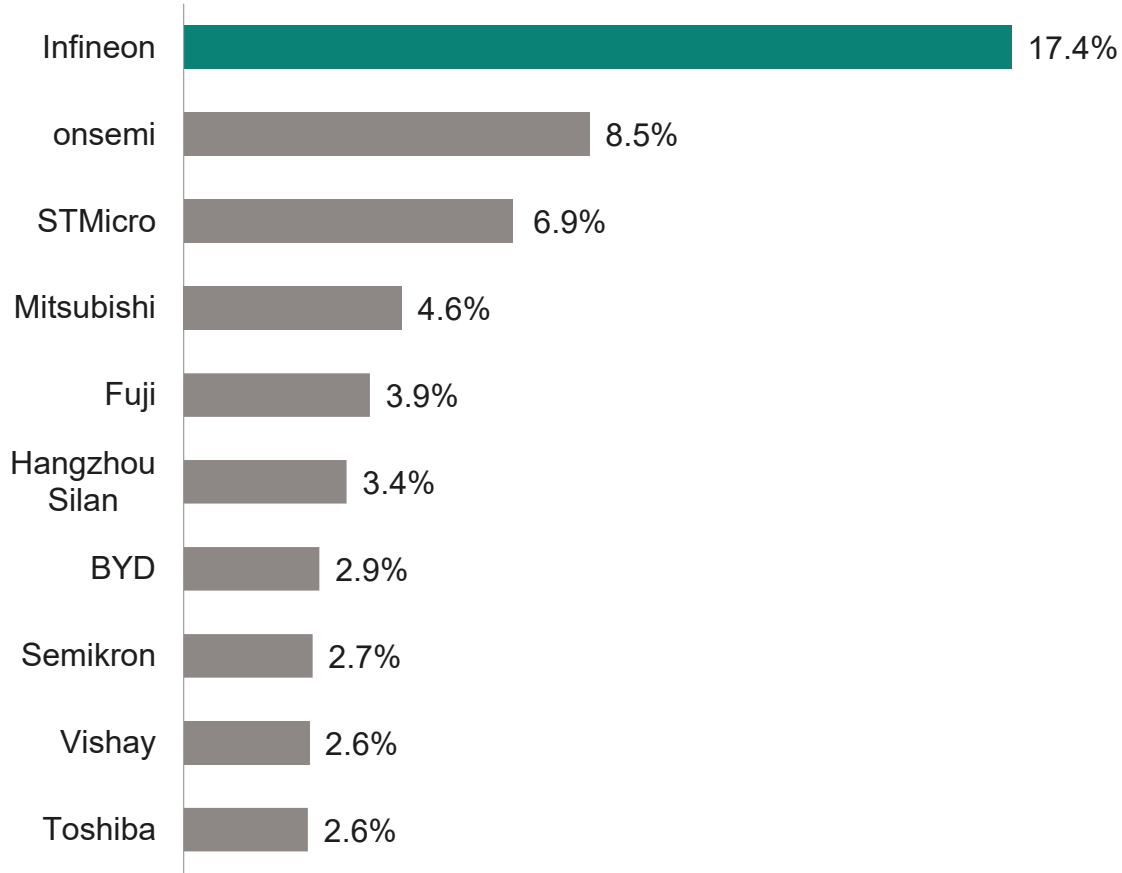
- Main growth contributors (addressed by multiple segments)
- Further major applications

Infineon is a global player, clear #1 in power semiconductors, Automotive semis and automotive microcontroller markets



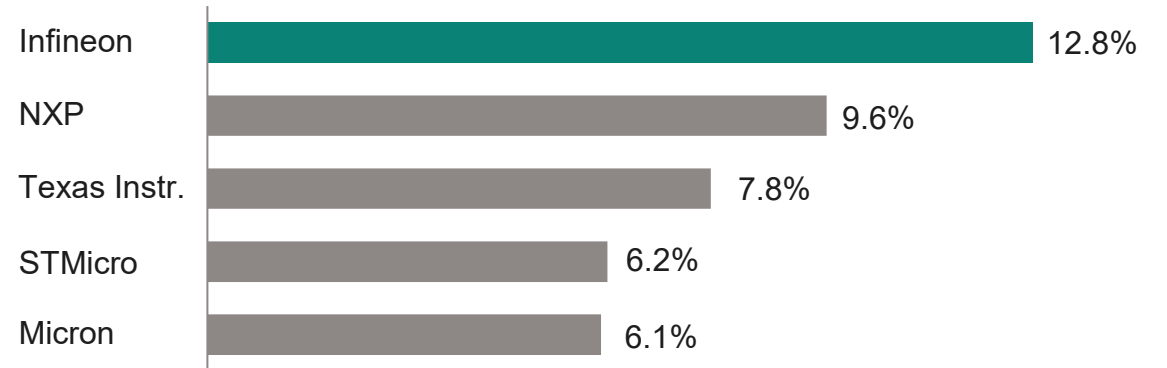
Power discretes and modules

2024 total global market: \$32.8bn¹



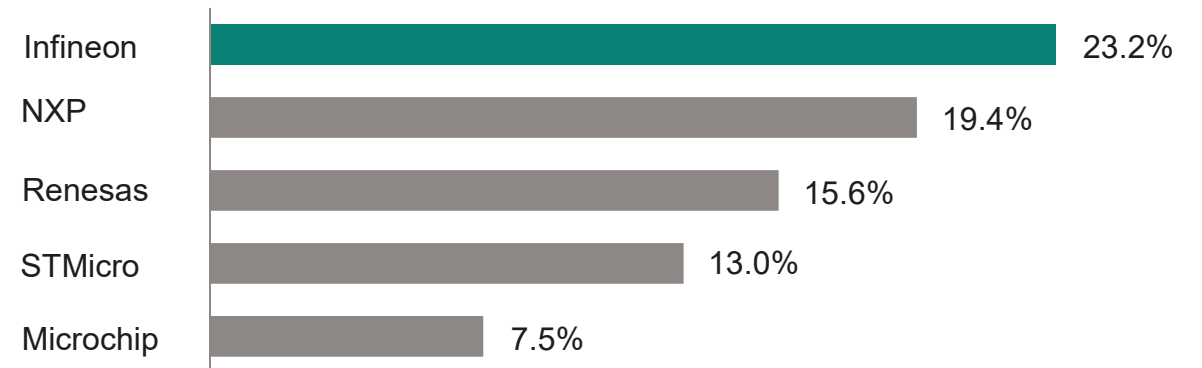
Automotive semiconductors

2025 total market: \$74.4bn²



Microcontroller

2025 total market: \$22.2bn²



¹ Based on or includes research from Omdia: Annual 2001-2025 Semiconductor Market Share Competitive Landscaping Tool – 4Q25. March 2026. Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk. ² Based on TechInsights: *Automotive Semiconductor Vendor Market Shares*. April 2026.

Our Target Operating Model: committing to ambitious financial goals and being the sustainability leader

Target Operating Model through cycle



Revenue growth

>10%



Segment Result Margin

25%



Adj. Free Cash
Flow Margin¹

10-15%

Sustainability leader
CO₂ neutrality 2030

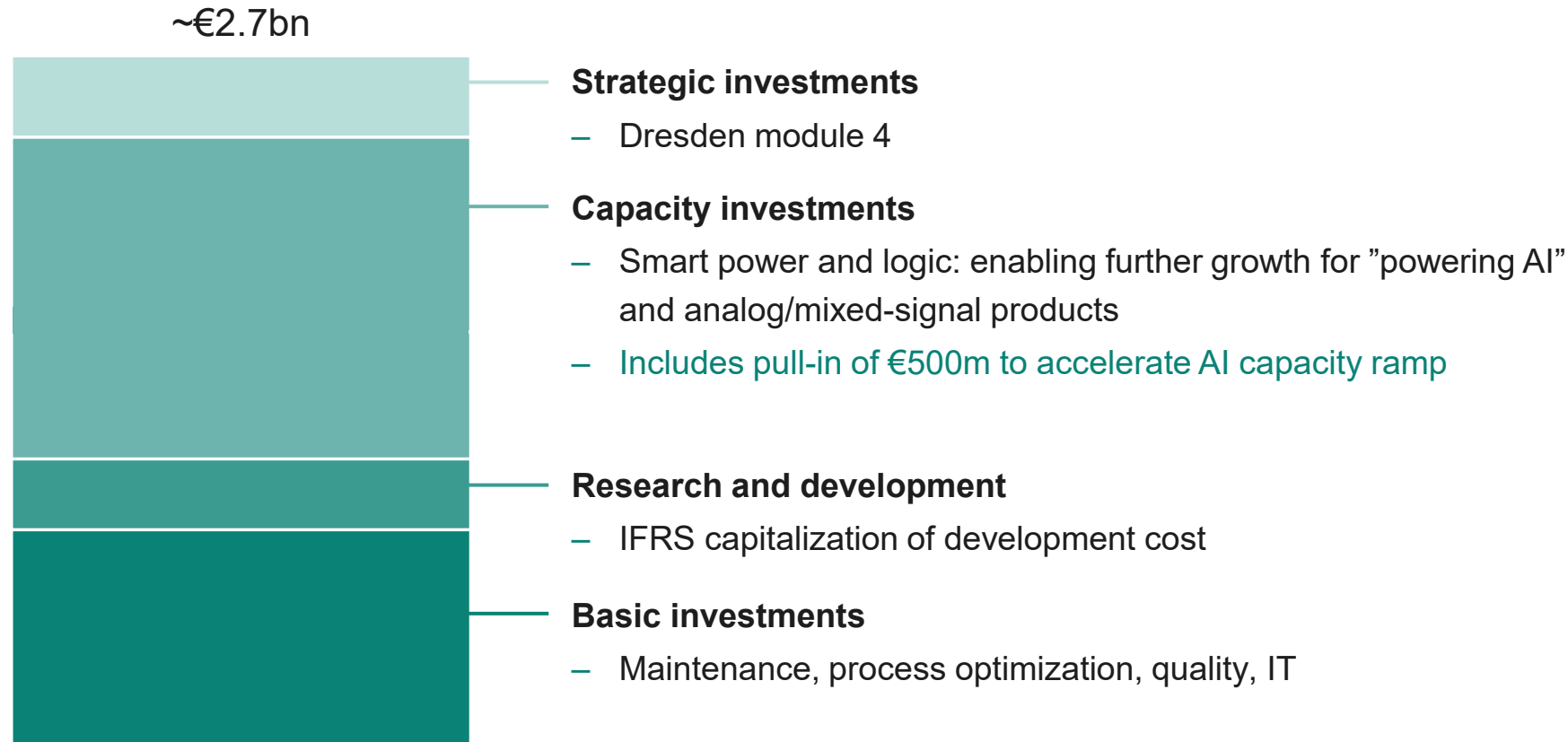


¹ See notes for definition

Modular investment approach for long-term value creation – pull-in of AI related investments for faster ramp



Infineon investments¹ FY26



¹ Investments are defined as the total amount invested in property, plant and equipment and in other intangible assets, including capitalized development costs

Outlook for Q3 FY26 and FY26

	Outlook Q3 FY26 ¹	Outlook FY26 ¹
Revenue	~€4.1bn	significantly up vs. prior year
Adj. Gross Margin		low-to-mid 40s %
Segment Result Margin	high-teens %	~20%
FCF		~€1.25bn/ ~€1.65bn
Adj. FCF		
Investments		~€2.7bn
D&A		~€2.0bn ²

¹ Based on an assumed average exchange rate of \$1.17 for €1.00

² Including the amortization of approximately 400 million Euros from purchase price allocations

From 4 to 3 divisions: New organizational structure to bring innovative system-level solutions to customers faster



From...



...to:



Focus applications (examples)

- SDV
- E-mobility



- Power infrastructure
- AI Datacenter



- Robotics & Edge AI
- Smart home

Clearer ownership
of focus applications

Reduced complexity
streamlines decision-making

Further accelerate
innovation-to-customer value

Well-balanced and simplified business setup

FY25 revenue of €14.7bn as reported and pro forma



Infineon strengthens its sensor leadership with the acquisition of ams OSRAM's non-optical analog/mixed-signal sensor portfolio



ams OSRAM
analog / mixed-signal
sensor business

Transaction overview

CY26e revenue

~€230 m

Purchase price

€570 m

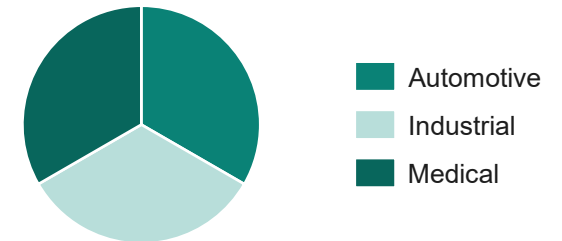
Employees

~230 employees, thereof ~150 in R&D
fabless asset-deal

Financial impact

EPS accretive from day 1

End market split



Strategic rationale

1

Strengthening our global sensor leadership position

- Acquisition of a top European sensor portfolio with complementary products in automotive and industrial end markets
- Expands footprint in high-value medical market

2

Accelerating growth and innovation

- Acceleration of innovation through synergetic R&D
- Acceleration of growth via established Infineon go-to-market channels

A unique opportunity to reinforce our leadership in analog/mixed-signal sensor solutions

Infineon serves all markets with a broad sensor portfolio to provide best solutions in Auto and Industrial



Automotive

- Radar sensors
- Magnetic position sensors
- Magnetic speed sensors
- Magnetic current sensors
- Inductive sensors
- Pressure sensors
- Gas/leakage sensors
- Silicon microphones
- CAPSENSE™ μC



- Magnetic position sensors
- Capacitive sensors
- Battery sensors



Complementing Infineon's leading sensor and sensor IC portfolio across automotive and industrial applications

Industrial

- Radar sensors
- Magnetic position sensors
- Current sensors
- Pressure sensors
- Vibration sensors
- Gas/leakage sensors
- 3D ToF sensors
- CAPSENSE™ μC



- Inductive position sensors
- Sensor interface IC
- X-ray sensor IC



Medical

- Temperature sensors
- Conventional and photon counting IC
- X-ray sensor IC



ams OSRAM
analog / mixed-signal
sensor business



Expanding our portfolio in medical applications

Compelling financial profile of the transaction

Financial value creation through:

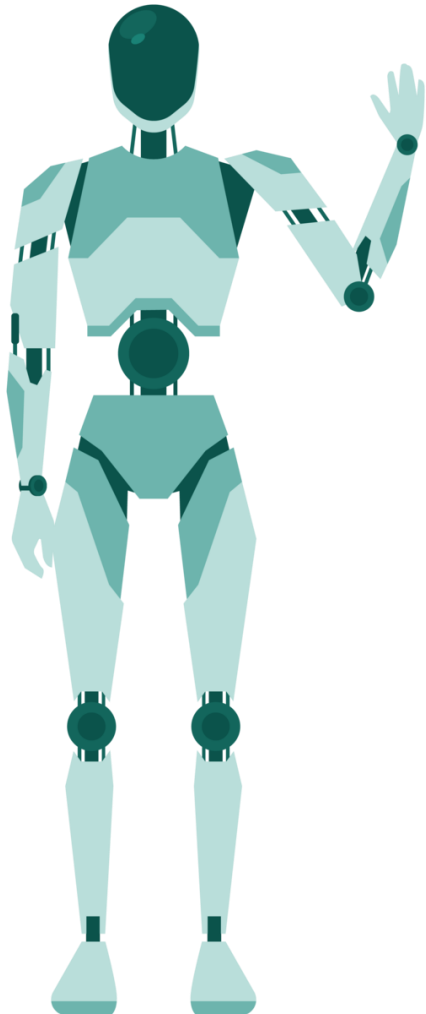
- 1 | Growth and margin profile in line with Infineon TOM
- 2 | EPS accretive from day 1
- 3 | Additional cost synergies within the next 3 years
- 4 | Advanced roadmap leveraging Infineon analog/mixed-signal products with ams OSRAM's

Transaction outline:

- 570m EUR purchase price, all-cash transaction
- Financed through additional debt
- PMI will follow proven script, integration into PSS Division
- Customary regulatory approvals, closing expected by Q2 calendar year 2026

TOM: Target Operating Model

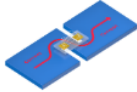
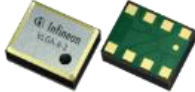

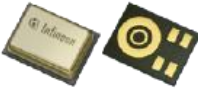

Strengthening of Infineon's leading robotics sensor solutions with acquired portfolio – addressing around 200 sensors



Humanoid sensor usage

- Broad range of **environmental sensors** (pressure, vibration, SiMiC, ToF, radar)
- Capacitive sensing for dexterous hands, **>100 position sensors**, e.g. for joints
- **Current sensors** for battery management

Infineon's current & environmental sensors portfolio

 Current sensors	 Pressure sensors	 Radar systems	 Microphones	 3D time of flight
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Infineon's combined position sensor portfolio

 3D sensor	 Angle sensors	 Linear sensors	 Magnetic switches	 Inductive sensors
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 acquired portfolio

Undisputed power systems leadership mastering all three key materials



- » Reliable multi sourcing of raw materials
- » World-scale fabs



- » Application understanding
- » Packaging know-how and hybridization competence

Leadership in Power Systems across all materials and technologies

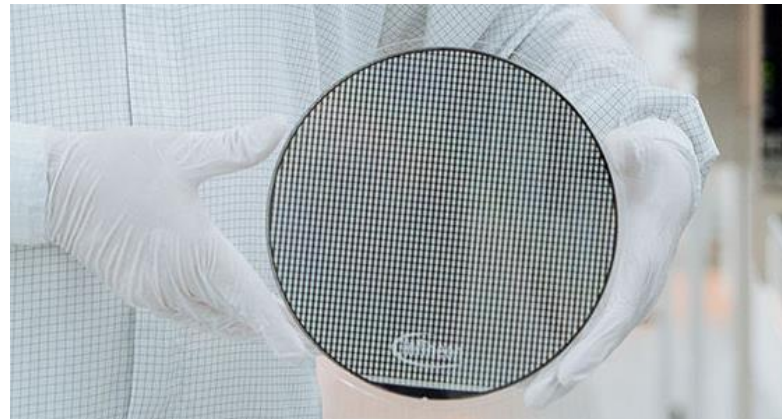
Silicon

Diode – MOSFET – IGBT – Driver – Controller



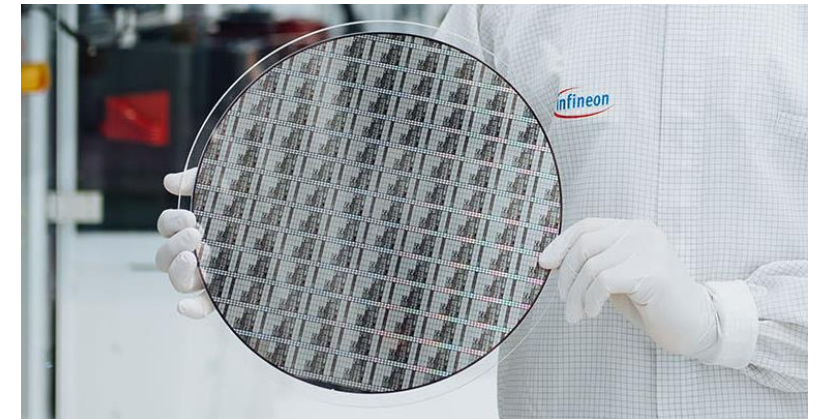
Silicon carbide

Diode – MOSFET



Gallium nitride

HEMT – Driver



Infineon is the leader across all power semiconductor technologies – unparalleled portfolio and know-how



World's thinnest silicon power wafer with 20 μm on 300 mm

- Broadest Si-power portfolio in the market
- Unmatched quality and leading in all figures of merit (FOM)
- Best price/performance ratio



World's most competitive 200 mm silicon carbide power fab

- Broadest portfolio covering auto and industrial applications
- Leading trench performance
- High reliability and robustness in extreme conditions
- Smaller system size



World's first 300 mm gallium nitride power wafer

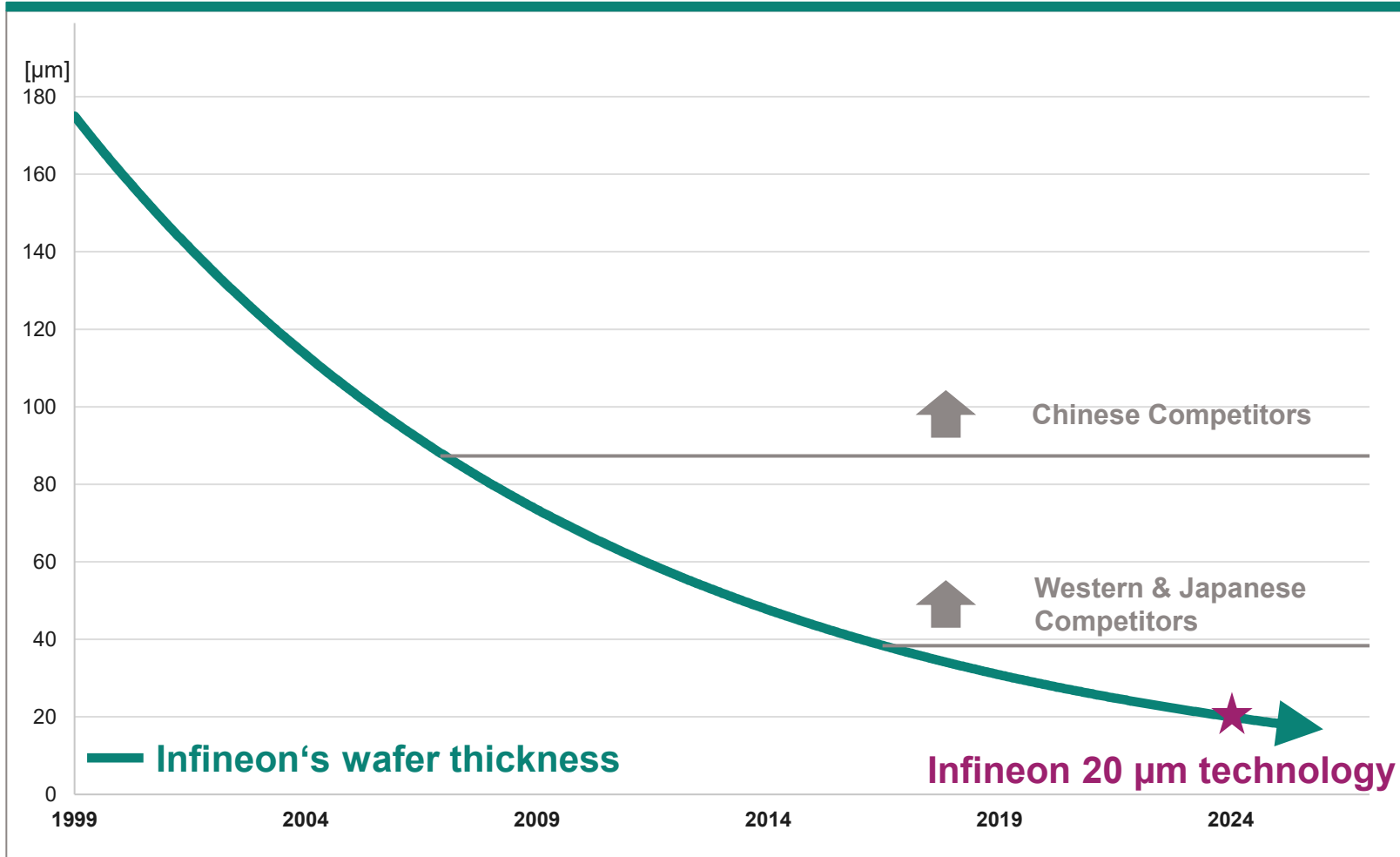
- Enabling cost parity with silicon
- Highest efficiency at the highest frequency enabling smallest system size
- Allow functional integration



Infineon is strengthening its position as the industry's innovation leader leading the way in all three power semiconductor materials

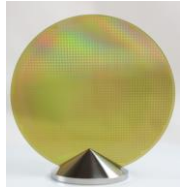
Infineon presents the world's thinnest silicon power wafer paving the way for more energy efficient power systems

Infineon reduces wafer thickness from 40 μm to 20 μm



- Infineon pioneers 20 μm process at high-scale production
- Halving thickness also halves resistance, reducing power loss by >15%
- Enables easy and robust signal routing from front to backside
- Technology qualified by customers and applied in Infineon's Integrated Smart Power Stages for DC-DC converter in AI servers

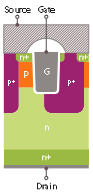
With Kulim 3, Infineon is on track to becoming the industry's most competitive provider of SiC technology



SiC raw material supplier network



- More than 6 qualified SiC wafer and boule suppliers
- Globally diversified and resilient



Superior trench technology



- 30% more chips per wafer than planar
- Unmatched reliability with zero field returns



Packaging portfolio



- Best-in-class in-house packaging solutions
- .XT technology for highest power density



Deep system understanding

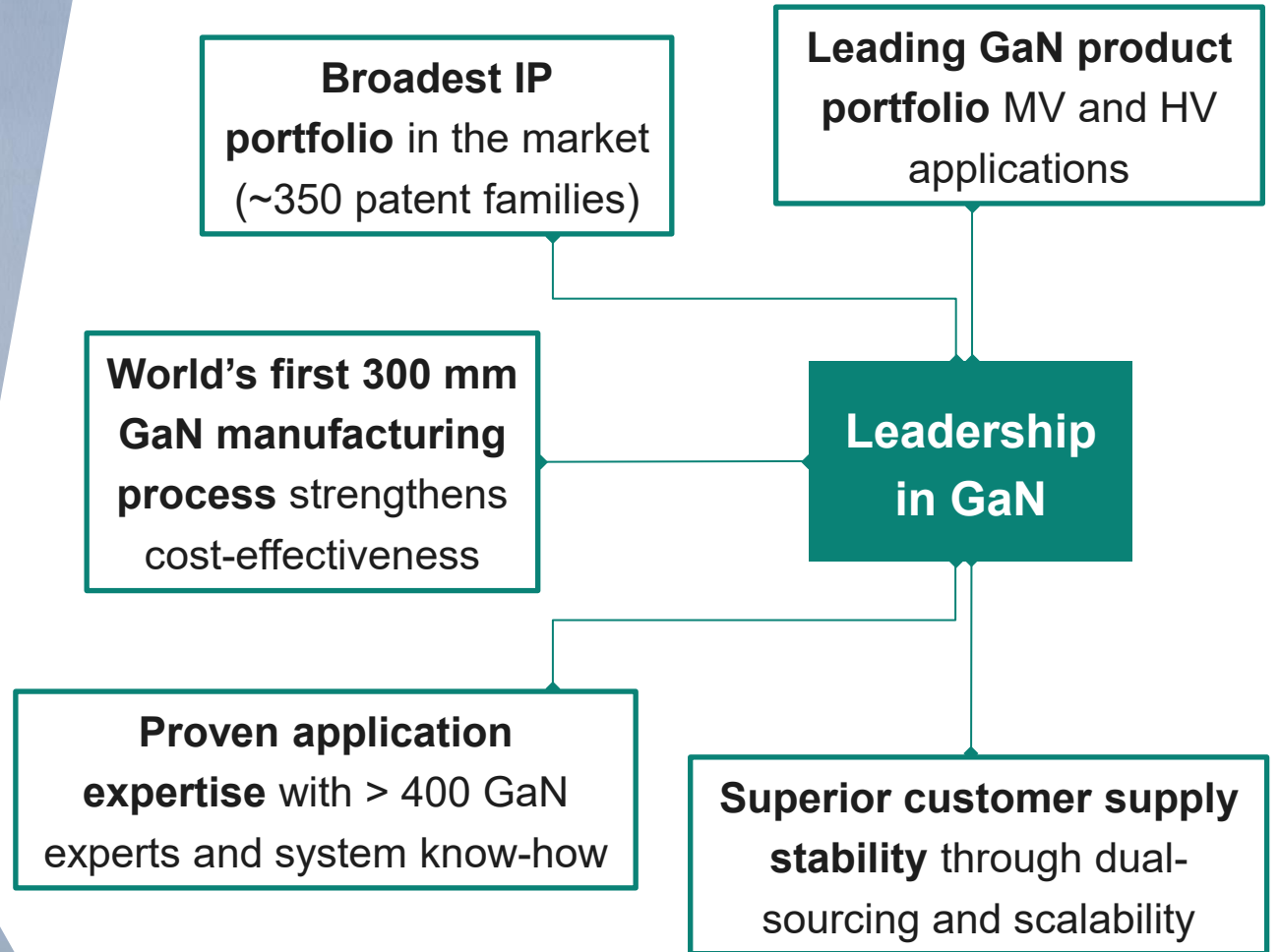
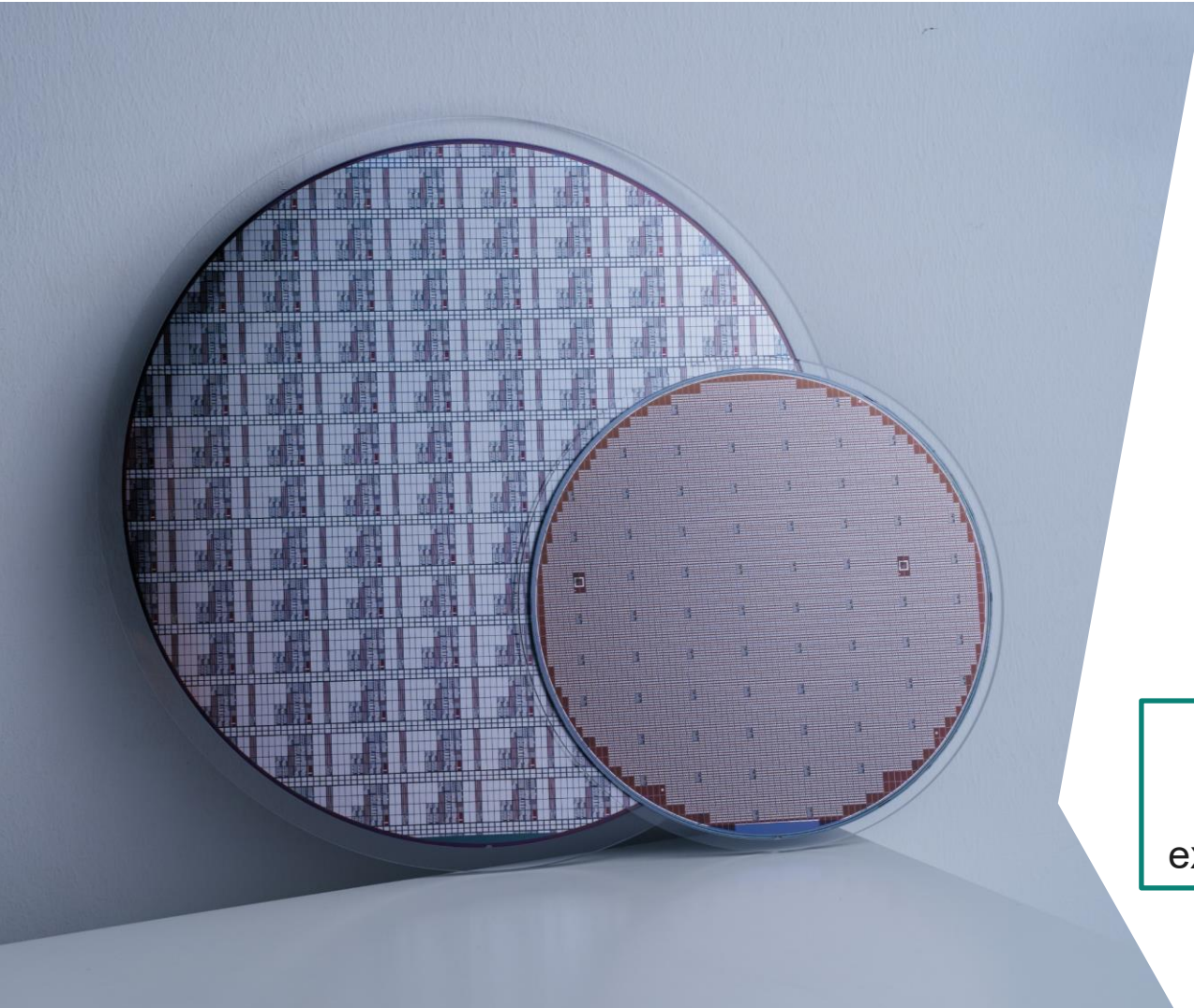


- Decades of experience
- Broadest portfolio: off-the-shelf plus customized solutions

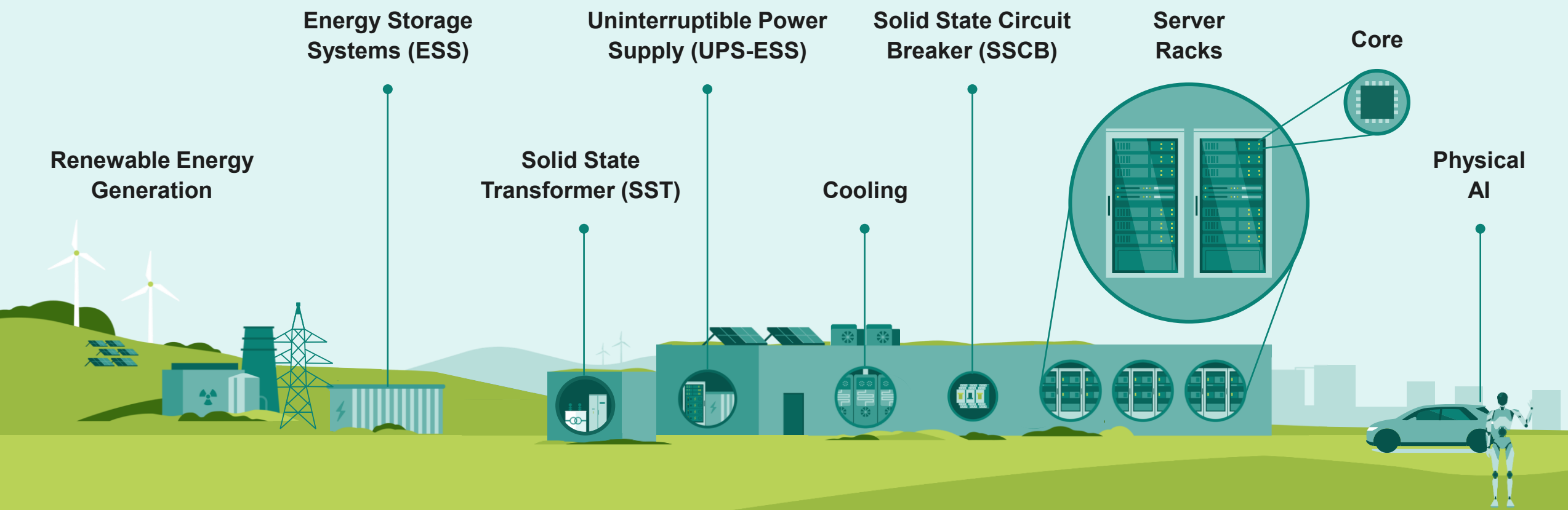


Most competitive 200 mm fab with industry-leading cost position.
Resilient setup together with Villach plant

Infiniteon is a leader in GaN technology and can build on the industry's broadest IP portfolio and application expertise



Infineon products are essential for AI power supply and secure operation of data centers – from grid to core and beyond



Infineon at the core of IoT – driving digitalization by serving strongly growing multi-application markets



Consumer IoT



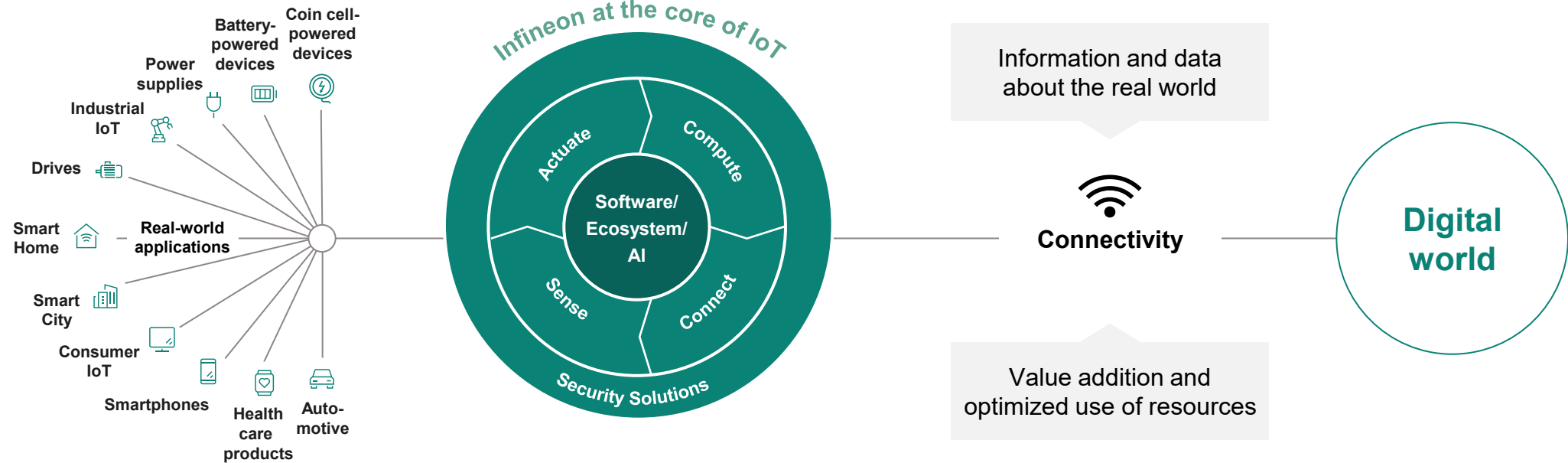
Industrial IoT



Automotive IoT



Products: MCU – Connectivity (Wi-Fi, BLE, NFC) – Sensors – Security – Power supply & switches



ESG: Targets and achievements



Important milestone achieved: The Science Based Targets initiative (SBTi) has approved our CO₂ emission reduction targets

SBTi validation of Infineon's 2030 CO₂ reduction targets marks a major step in our decarbonization journey

- **Scope 1 and 2 targets align with the Paris Agreement, limiting global warming to 1.5°C**
Specifically, Infineon has committed towards SBTi to **reduce** absolute Scope 1 and 2 greenhouse gas (GHG) emissions by 72.5% by 2030 versus the base year 2019.
- **New Scope 3 commitment:** 72.5% of supplier emissions to be covered by science-based targets by 2029.
- **Key reduction measures** include green electricity, energy efficiency, and voluntary GHG abatement.
- Infineon remains **committed to 100% CO₂ neutrality** goal in Scope 1 and 2 by 2030, as announced back in 2020
This will include compensation for the smaller part that cannot be reduced



Our 2030 carbon neutrality goal is aligned with the Paris Climate Agreement's 1.5°C target



CO₂ burden¹

2.7 million tons of CO₂ equivalents



Ratio
~1:53
previously 1:45

CO₂ savings²

143 million tons of CO₂ equivalents

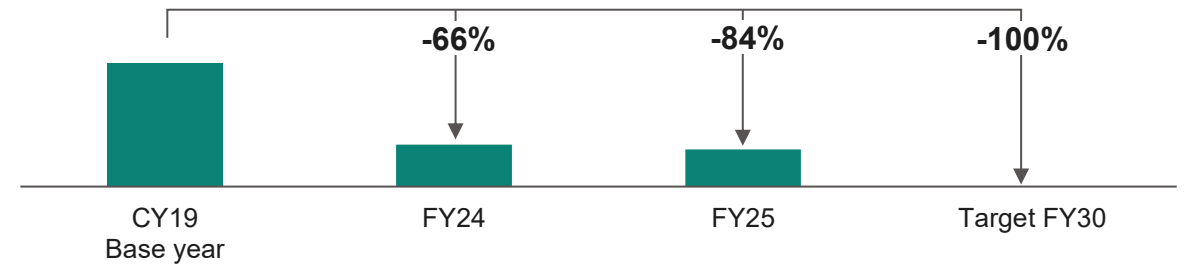


On the road to carbon neutrality³ we achieved significant milestones

- Overachievement of our 70% reduction target for FY2025
- Usage of green electricity in all our sites

Infineon's CO₂ target³ by 2025 and 2030

Net CO₂ emissions in million tons of CO₂ equivalents



» Net ecological benefit: CO₂ emissions reduction of more than 140 million tons

^{1, 2, 3} For further explanation see "ESG footnotes" in the appendix

External recognitions confirm our engagement in contributing to a sustainable society



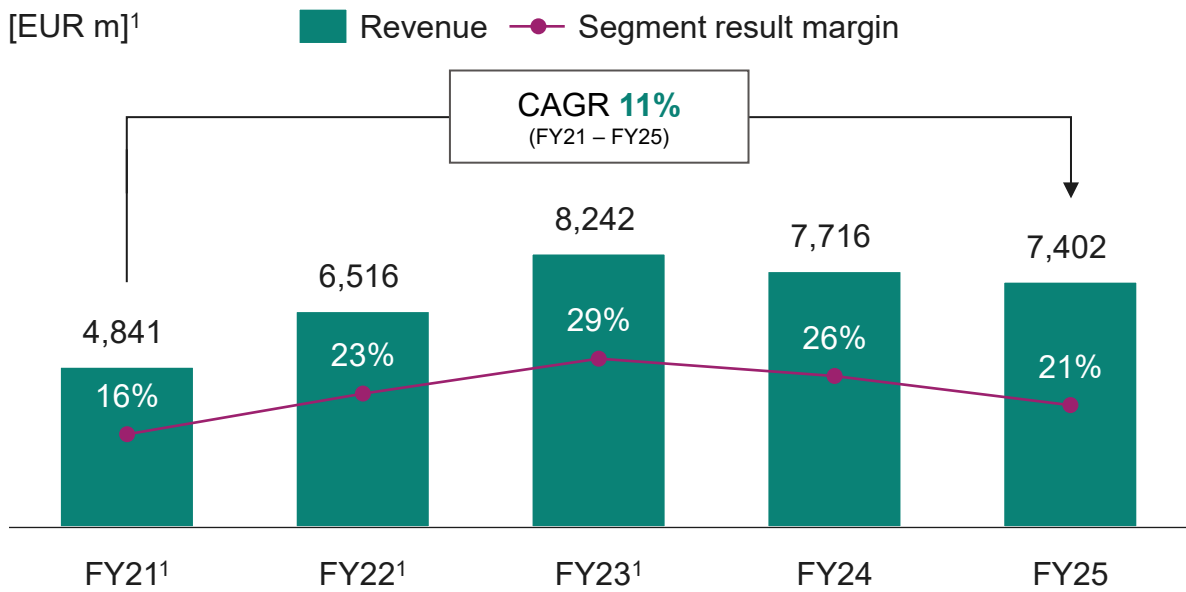
	Rating/Score	Scale	Date
MSCI ESG	AA	CCC to AAA	04/2026
CDP	B climate scoring B water scoring	F to A	01/2026
Ecovadis	99th percentile "Platinum" award	0 to 100	09/2025
Dow Jones Best-in-Class Index	Dow Jones Best-in-Class World & Europe Index listing	-	04/2026
ISS ESG Corporate Rating	Prime Status	-	04/2026
FTSE4Good Index	Index member	-	07/2025
Sustainalytics	ESG low risk	-	01/2026

Automotive



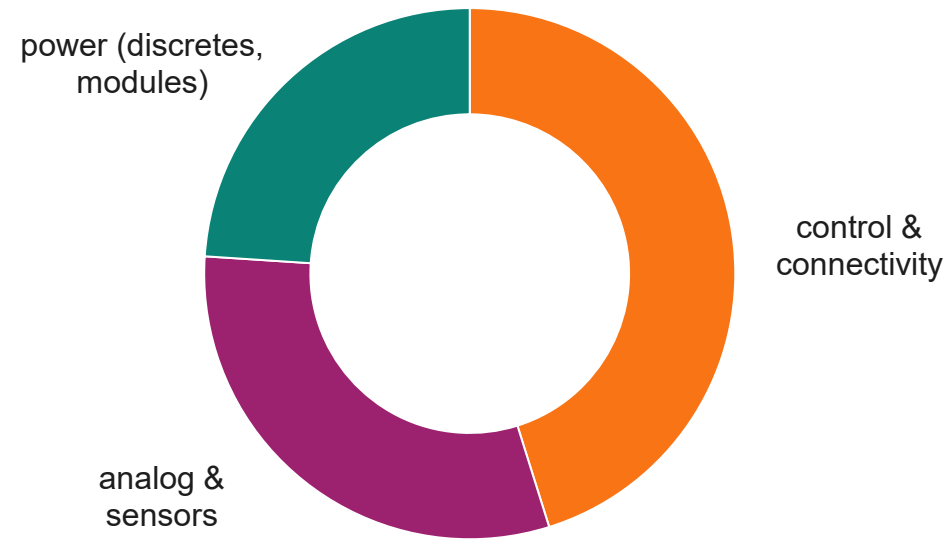
ATV at a glance

ATV revenue and segment result margin

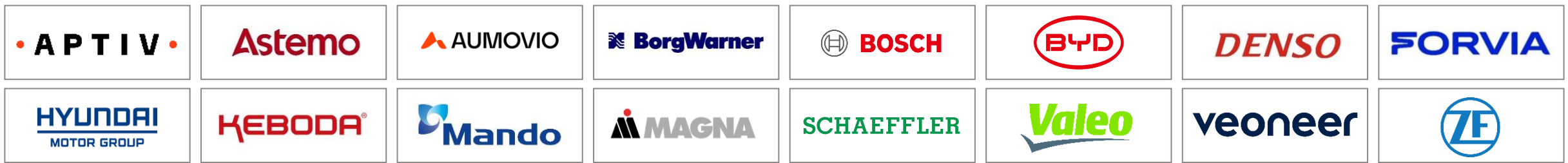


¹ Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

FY25 revenue split by product group



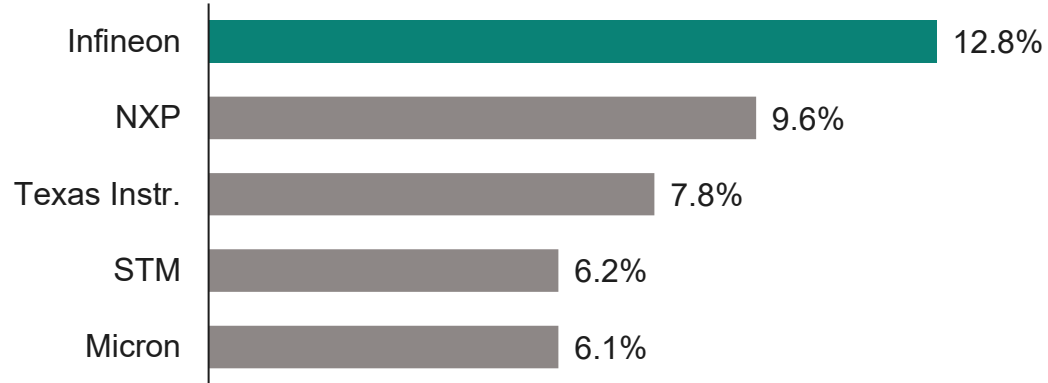
Key customers



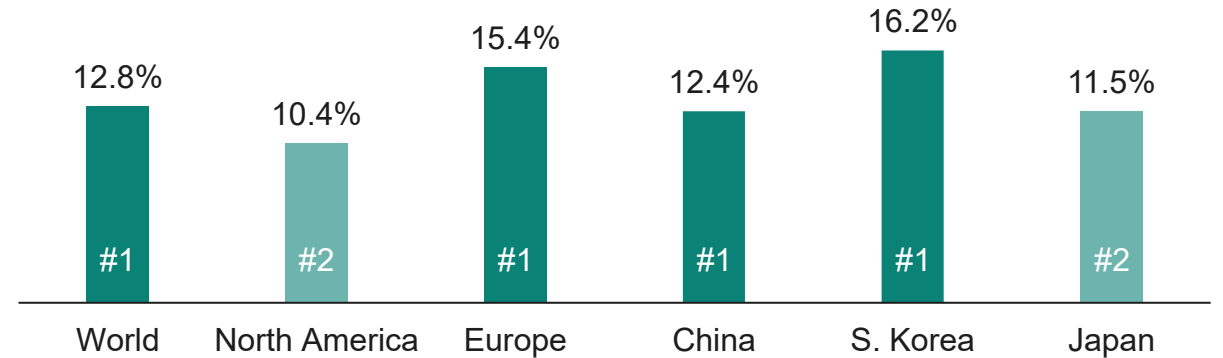
Infineon's undisputed automotive MCU leadership further expanded, overall number one position clearly confirmed



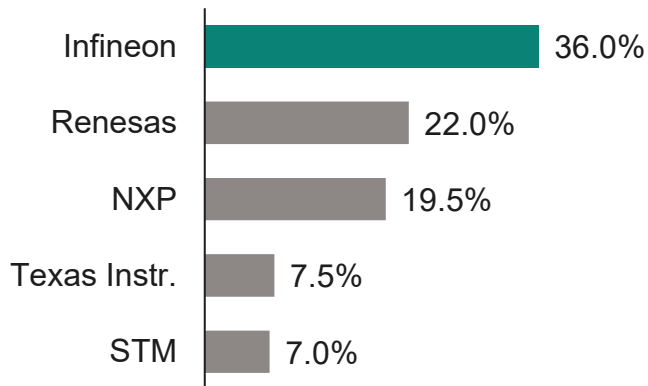
Automotive semiconductors (2025 total market: \$74,408m; +6.4% y-y)



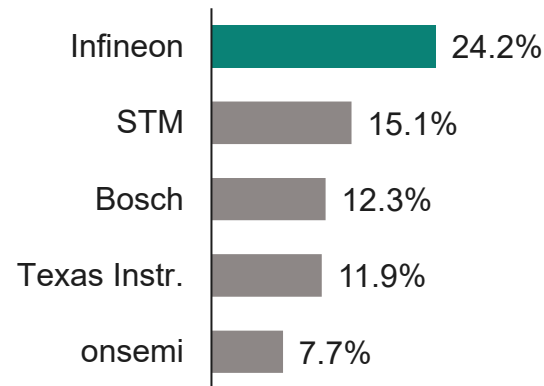
Infineon's 2025 market share and position by region



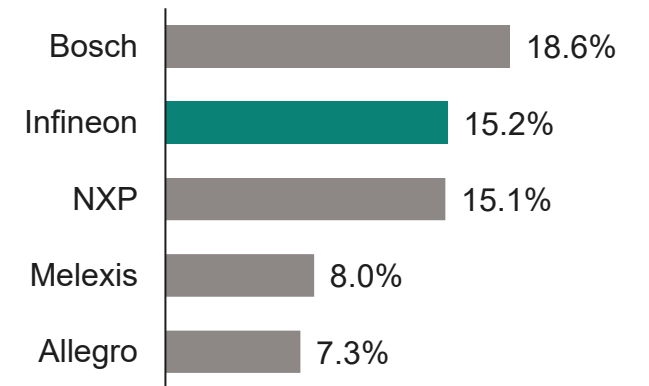
MCUs



Power



Sensors¹



TechInsights: *Automotive Semiconductor Vendor Market Shares*. April 2026. ¹ Sensors: S&P Global: *Automotive Semiconductor Market Shares 2025*. April 2026.

Several strong content growth drivers for Infineon in xEV and software-defined vehicles, even at flat LV production



Structural trends fueling our growth

xEV

- Strong volume growth of BEVs and PHEVs
- Increasing share of SiC in traction inverters
- More kW per vehicle lead to higher BoM in inverter

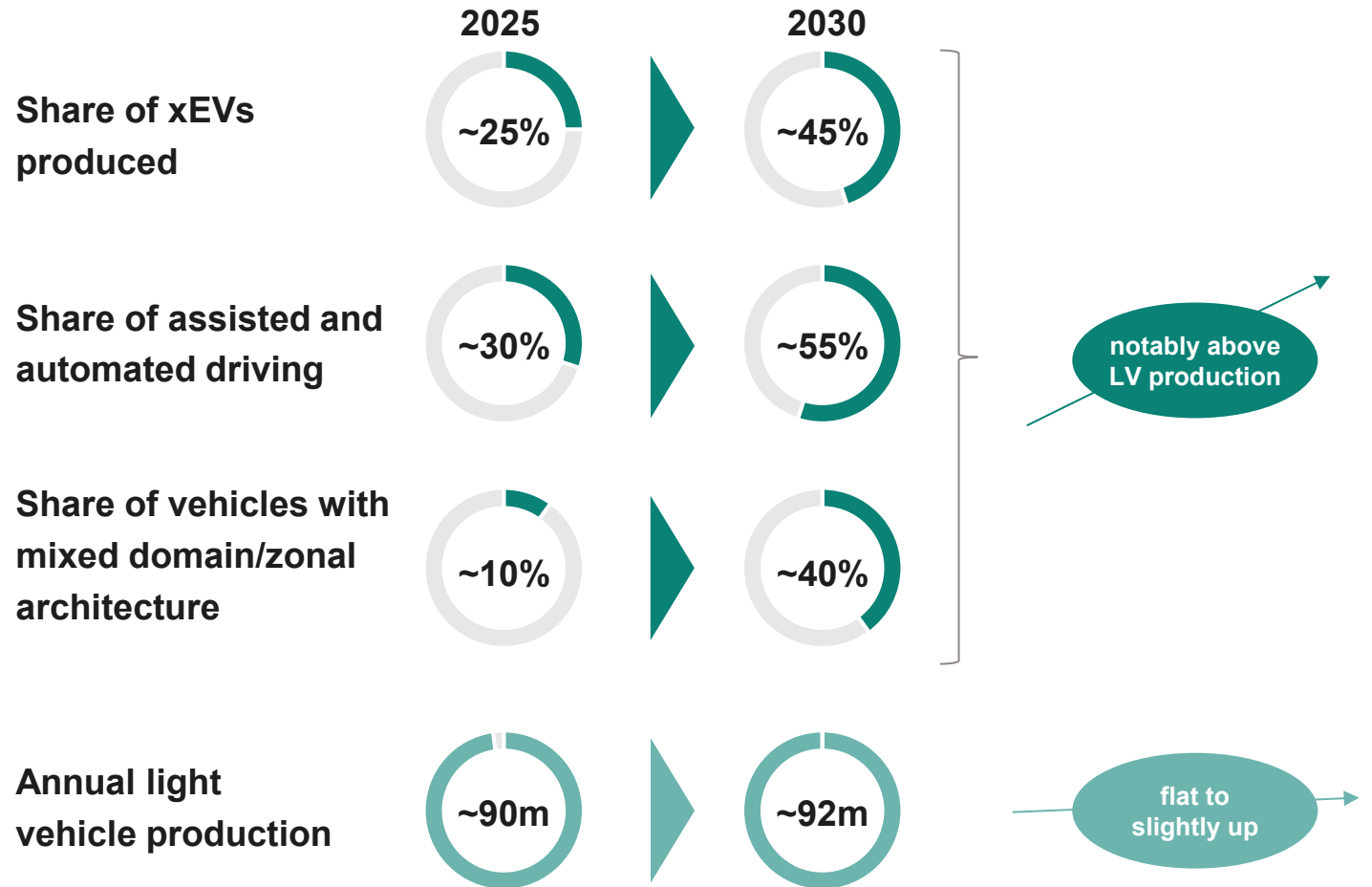
SDV

- Transformation of E/E architecture towards central computing with zonal controllers
- Smart switches for decentralized power distribution
- Software over the air
- Secure connectivity, cybersecurity indispensable
- Functional safety, dependable electronics, redundancy
- ADAS/AD: More sensors, more computing performance

Comfort and premium features

- More loads (motors, heating, cooling etc.)
- More elaborate lighting, both exterior (matrix light) and interior (instruments and ceiling)

Overview of growth vectors until 2030

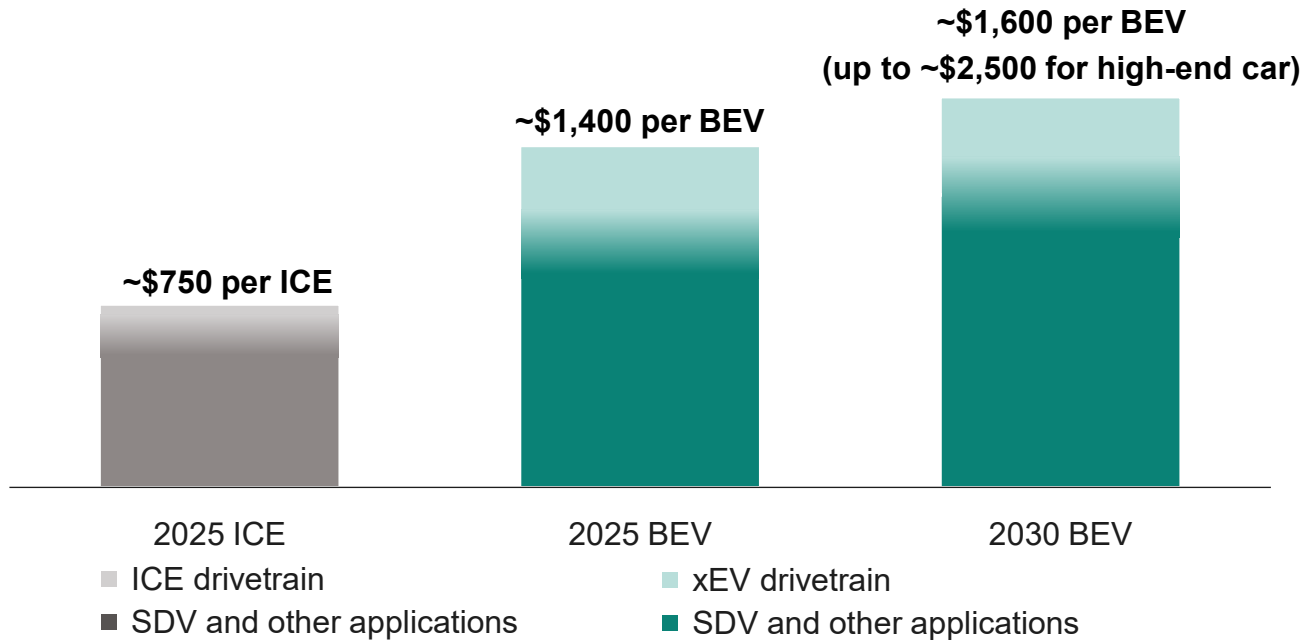


Infineon estimates

Infineon is the world leader in automotive semis, serving all key applications and benefiting strongly from content growth



Average semiconductor bill-of-material per car in 2025 and 2030



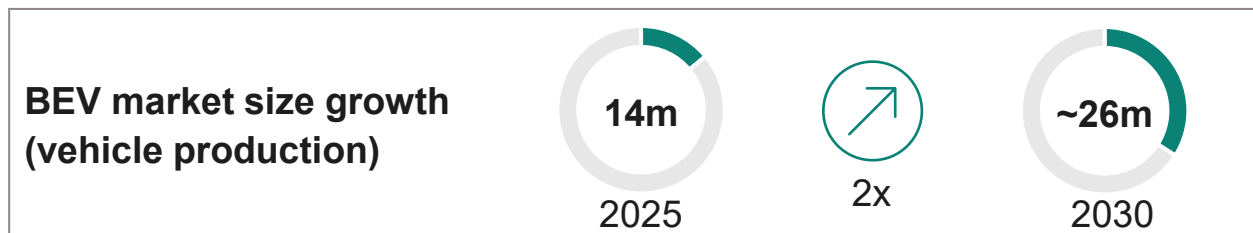
Semiconductors covered by Infineon

Drivetrain applications:

- Traction inverter, OBC, DC-DC, BMS, auxiliaries
- Drivers for BoM increase:
 - SiC and GaN replacing Si
 - more motors and stronger motors per car
 - slight increase in kW per car

SDV and other non-drivetrain applications:

- Domain/Zone
- SDV, incl. E/E architecture and ADAS
- Safety and advanced security
- Comfort and premium
- Connectivity and infotainment



With a growing xEV market and growing non-drivetrain BoM, Infineon profits twice

Infineon estimate based on S&P E/E & Semiconductor Service dataset – October 2025; November 2025

Number of power MOSFETs per car continues to increase, and drives accelerated growth for the leading portfolio



Examples of MOSFET applications


Power door	Power lift gate	Brake booster	Electric power steering	HV-LV DC-DC conversion	BMS	Transmission control	Windshield wiper
Electric parking brake	HVAC blower	Sunroof	Side mirror	Seat adjustment	Thermal management	12 V battery switch	Power supply protection

Latest portfolio with constant innovation

Technologies, packages and voltages

OptiMOS™ 7		40 V
OptiMOS™ 6		60 V
OptiMOS™ 5		80 V
OptiMOS™ T, T2, Gen 12.7		100 V
		120 V

... ..



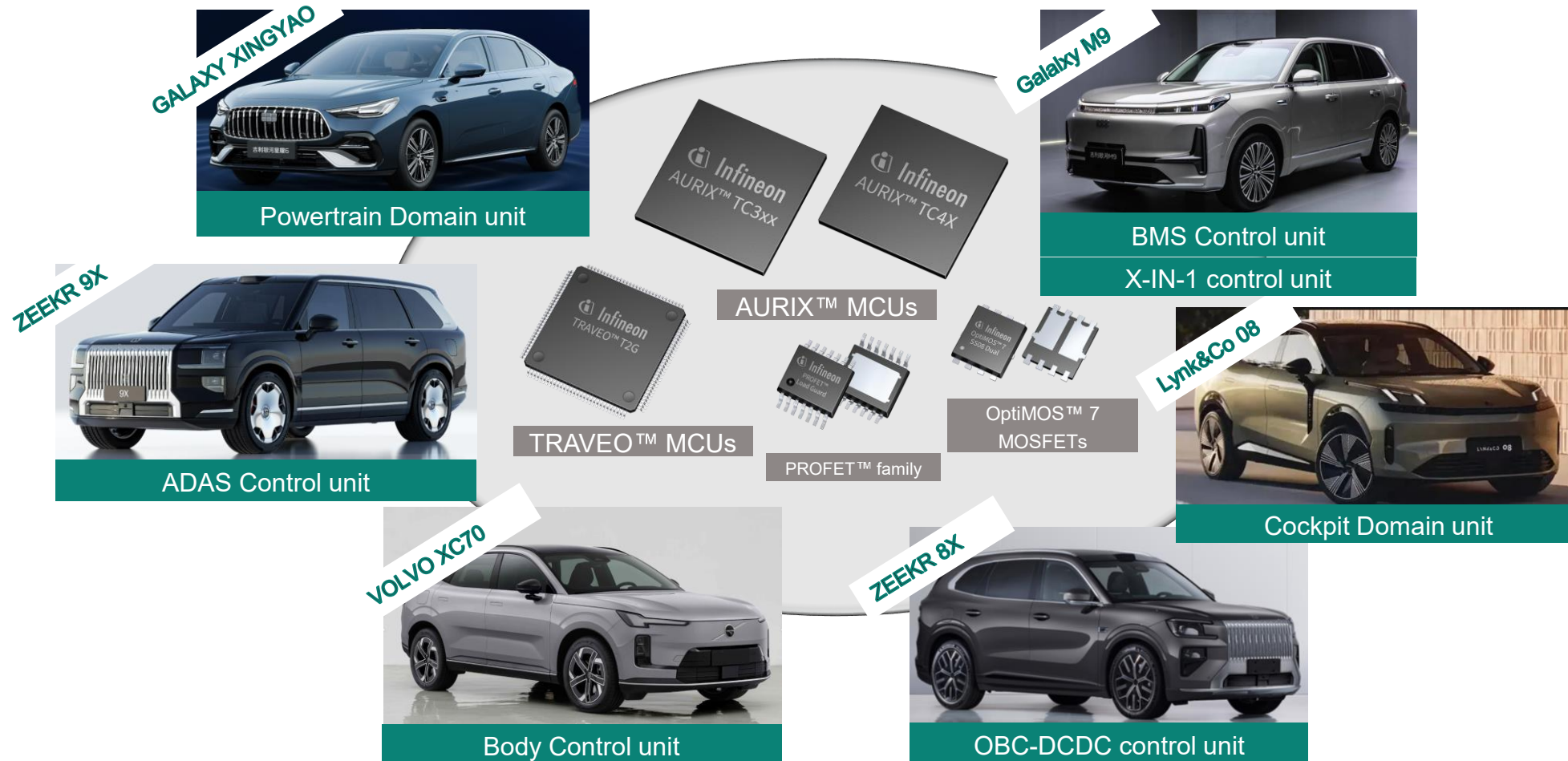
New **OptiMOS™ 7** family with outstanding technical performance

- 100 to 180 MOSFETs are used per vehicle in ~90 different applications in all segments: body, chassis, safety, ADAS/AD, powertrain
- Infineon offers broadest portfolio (>600 products) and eco-system to address specific and high-margin applications:
 - embedded control, gate driver, MOSFETs, software, P2S
 - entire eco-system with digital twins
 - simulation environment (esp. for motor control)

Several design-wins at Geely – Infineon’s leading solutions covering all-ranges of vehicle models



Geely has adopted AURIX™ for Powertrain, BMS, ZCU, ADAS, Cockpit, etc., and highly recognized AURIX’s outstanding performance in functional safety, real-time processing and automotive-grade stability.



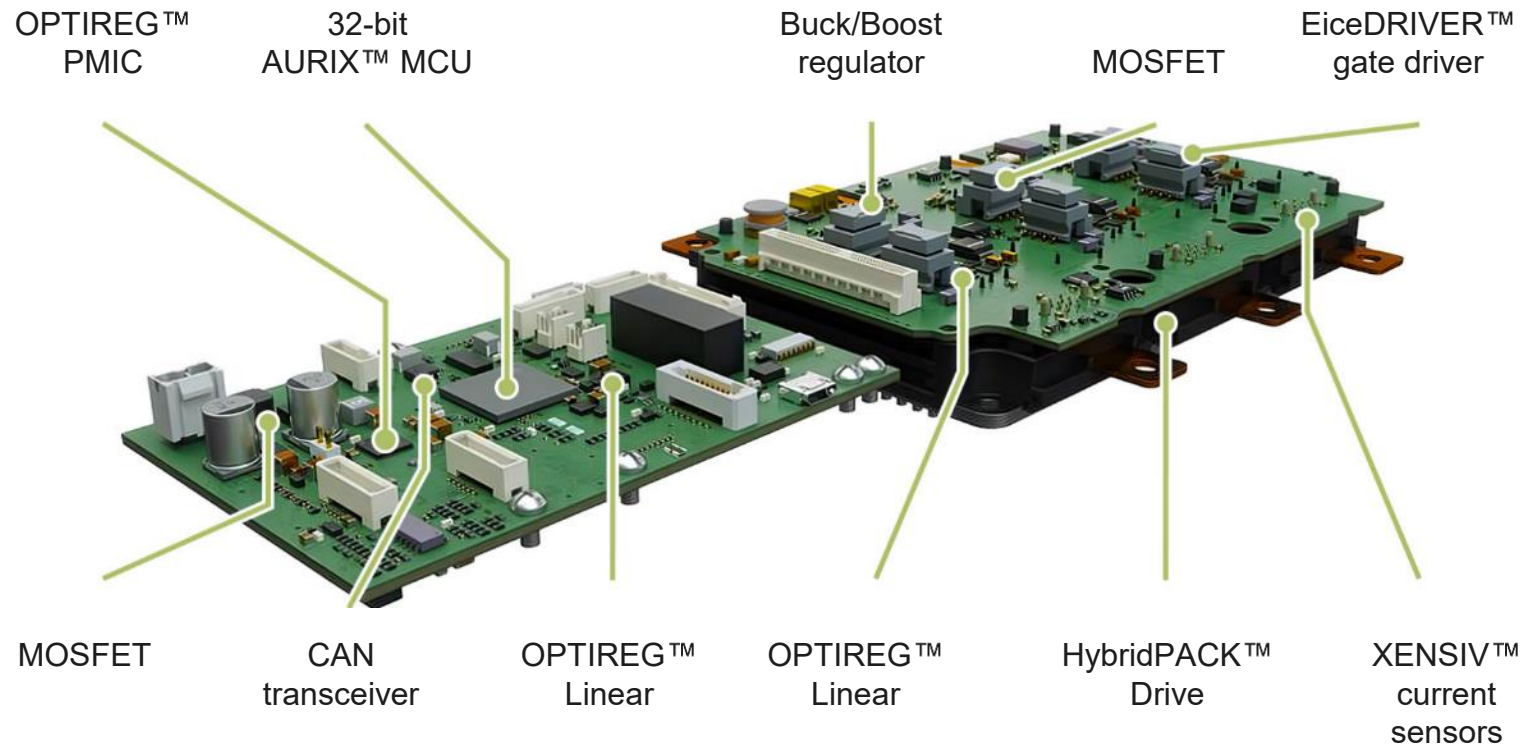
Electromobility



Infineon's broad product portfolio and system understanding enable higher BoM and allow compact designs and fast T2M



Infineon inverter reference design, covering up to 95% of value



P2S (product-to-system approach)

- Reference design for up to 300 kW, further customization possible
- System solution for easy implementation
- Fast time-to-market (T2M)

Freedom of choice

- IGBT and SiC in 750/1,200 V scale up to preferred power class
- HybridPACK™ Drive CoolSiC™ Gen2 continuous operation at 175°C
- EiceDRIVER™ gate driver Gen3 optimized for CoolSiC™
- Optimized 32-bit AURIX™ MCU

Competitive setup, unmatched portfolio breadth and our worldwide customer base lead to sustained growth in SiC



Leading SiC technology and production efficiency

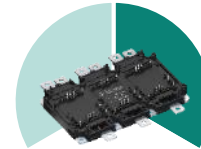
- Unrivaled productivity with most competitive fab and most diversified supplier network
- Superior trench technology and highest reliability
- Extensive packaging portfolio and complete system competence

Most scalable SiC auto portfolio

650 V

750 V

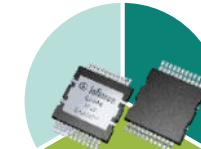
1,200 V



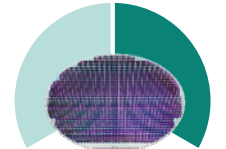
Module



DSC/SSC module



Discrete



Bare die

Continued strong SiC design-win momentum



Infineon AURIX™ TC4x with integrated PPU brings AI-on-the-edge to the battery



Battery cost

Battery health

Charging speed

Safety concerns

Range anxiety

**Resale value,
residual value**

**Cloud dependencies
(latency, cost, stability)**

AURIX™ TC4x

PPU

(parallel processing unit)



High computing performance with complex and accurate BMS algorithms

- AI-based battery diagnostic on-the-edge
- temperature model, electro-chemical model
- lithium plating detection
- remaining useful life prediction
- with and without cloud-based updates
- Product-to-System!

Efficient battery cell utilization

- Higher capacity
- Less cells
- Lower battery cost

Faster charging

- Higher user experience

Assure longevity, extended guarantee

- Longer lifetime (in years, in km)
- More charging cycles

Detect and prevent thermal runaway

Accurate battery, health prediction

» **Trust in resale market**

- Higher economic value (impacting insurances, fleets, OEMs, Tier1s, 2nd life market)

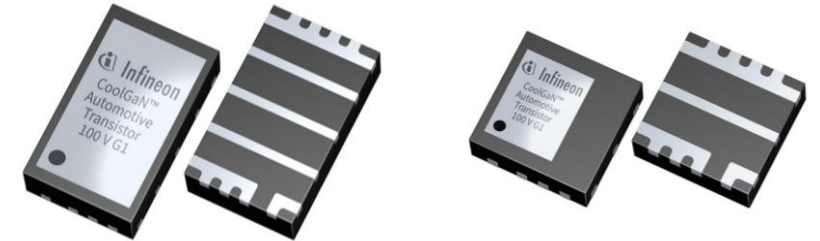
Open to partner up with further OEMs, Tier1s, insurance companies

Infineon strengthens its leading position in automotive semis – introducing the CoolGaN™ automotive transistor 100 V G1 family














CoolGaN™ automotive transistor 100 V G1 family

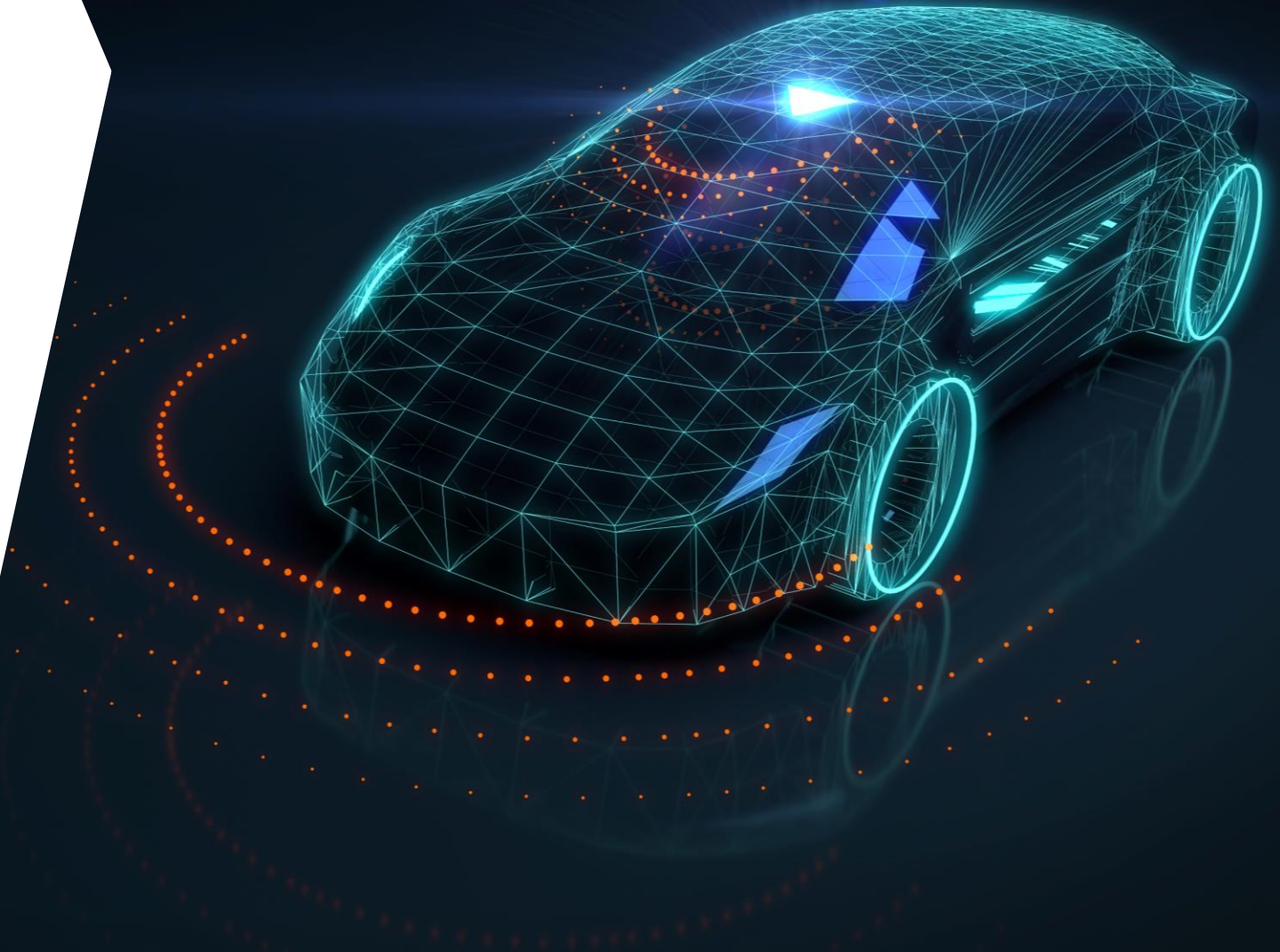
- First GaN transistor family qualified to AEC-Q101 for automotive applications
- Features CoolGaN™ transistors and bidirectional switches
- Enables higher energy efficiency and lower system cost
- Combines smaller form factor with higher power density
- Ideal for zone control, main DC-DC converters, high-performance auxiliary systems, and Class D audio amplifiers



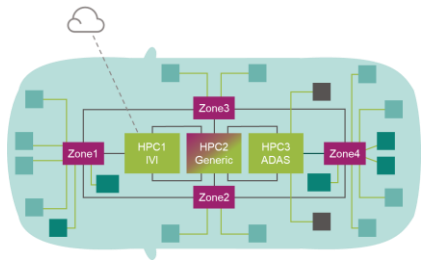
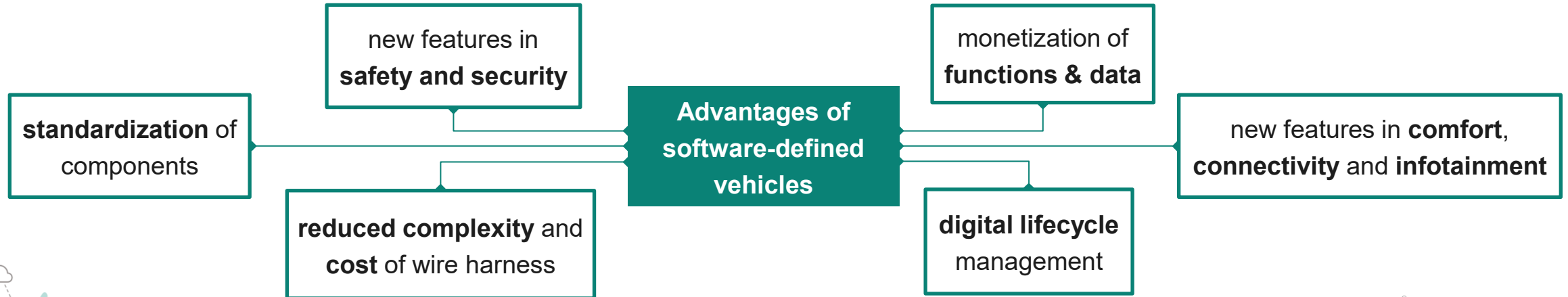
Main automotive target applications and the benefits of GaN

<p>On-board charger</p>  <p>HV/LV DC-DC</p> 	<p> Higher efficiency: energy savings</p> <p> Higher power density: less material & smaller size</p> <p> Lower system cost: more affordable</p>	<p>Traction inverter</p>  <p>48 V/12 V DC-DC</p> 	<p> GaN supports new inverter topologies</p> <p> Efficiency gain (more range or smaller battery)</p> <p> Power conversion for E/E architecture</p> <p> Less material, smaller size, and lower system cost</p>
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Software-defined vehicle

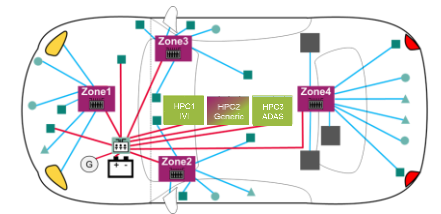


Software-defined vehicles are enabled by safe/secure computing, high-speed in-vehicle networks, and intelligent power distribution



Safe and secure computing and high-speed in-vehicle network

- Evolution to hierarchical/centralized
- Application software decoupled from hardware
- Management of real-time communication in each zone
- **Automotive Ethernet as key differentiator**



Intelligent power distribution

- Evolution from centralized to decentralized
- Power distribution safety element for
 - freedom from interference
 - system availability up to ASIL-C for ADAS
 - fail-operational of ASIL-D for AD and x-by-wire

The Automotive Ethernet portfolio strengthens our market leading MCU position and increases offering for zonal architectures



Infineon's unique portfolio of MCU and Ethernet

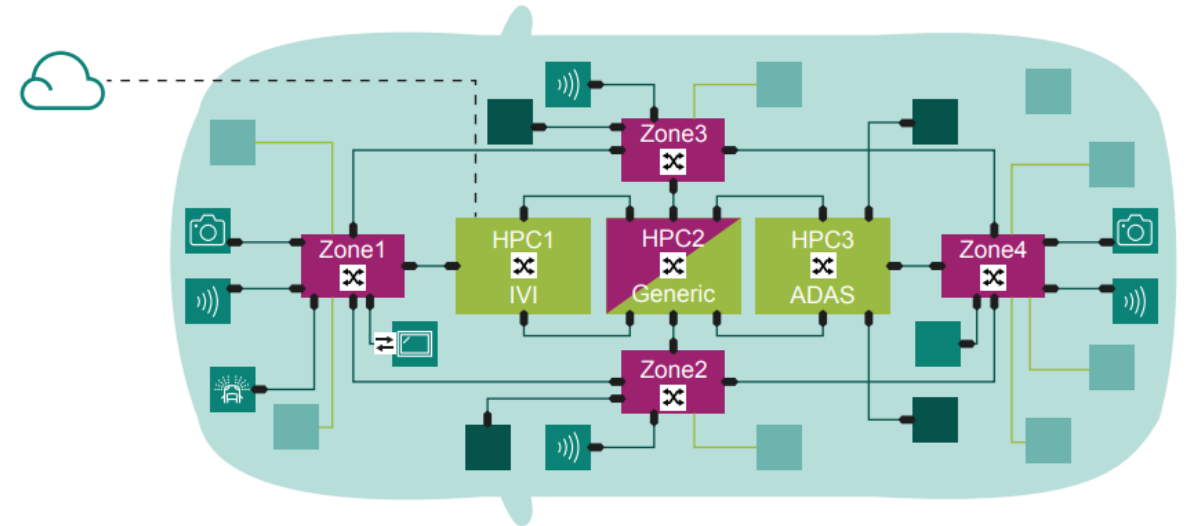
Automotive MCUs



Automotive Ethernet



Components of hierarchical E/E architectures:



High Performance Computing (HPC)
 Complex sensors & actuators

Simple sensors & actuators
 Zone controller
 Control ECU

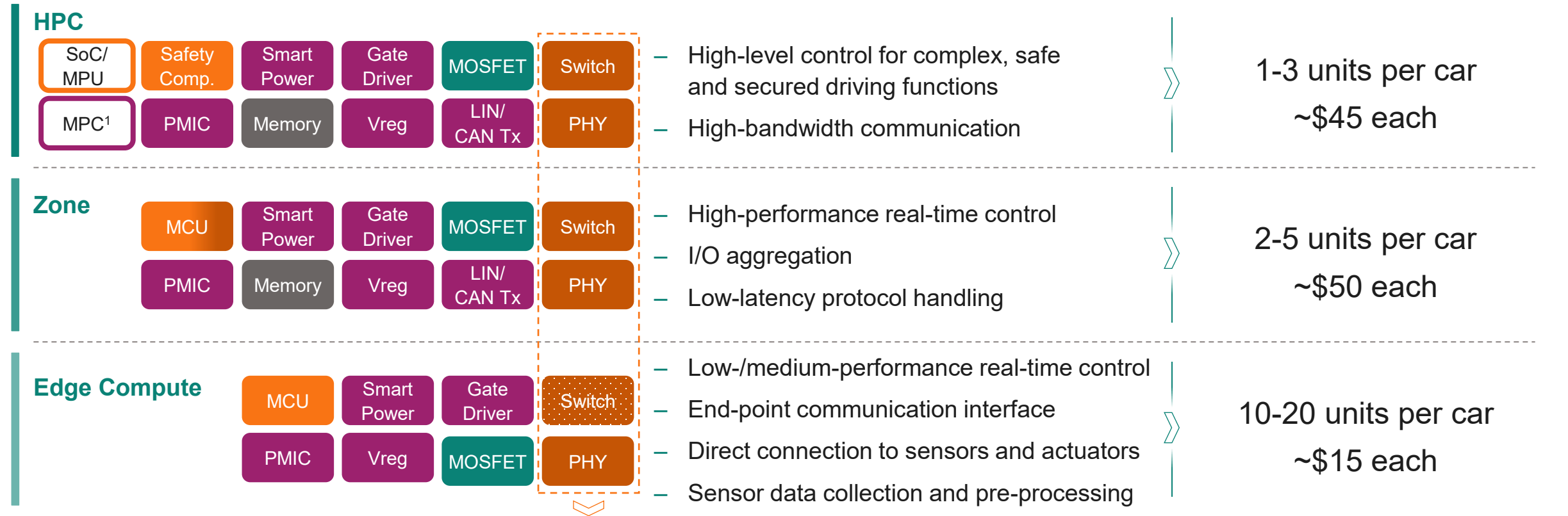


Infineon's extended portfolio contributes essentially to SDV as the second growth pillar alongside e-mobility



Infineon components for hierarchal computing E/E architecture

Infineon BoM potent.: ~\$500



Total BoM for Infineon increases by almost \$100 due to Ethernet

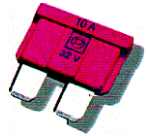
¹ Digital multi-phase controller for SoC/MPU Control Analog Memory Power Ethernet Component if needed Not part of Infineon portfolio

Smart semiconductors in power distribution systems are key enabler for SDV while ensuring high availability and resilience

Infineon PROFET™ Wire Guard enables SDV



Relay replacement



Fuse replacement



Load status diagnostics

Switch

Protect

Diagnose

e.g. PROFET™ Wire Guard



ISO 26262 compliant

Fast failure isolation (< 500 μs)

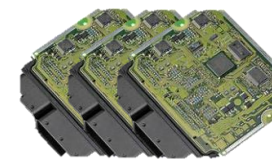
Central fuse box + many individual ECUs



- Big and heavy
- Complex wire harness
- High power loss
- Risk of interference



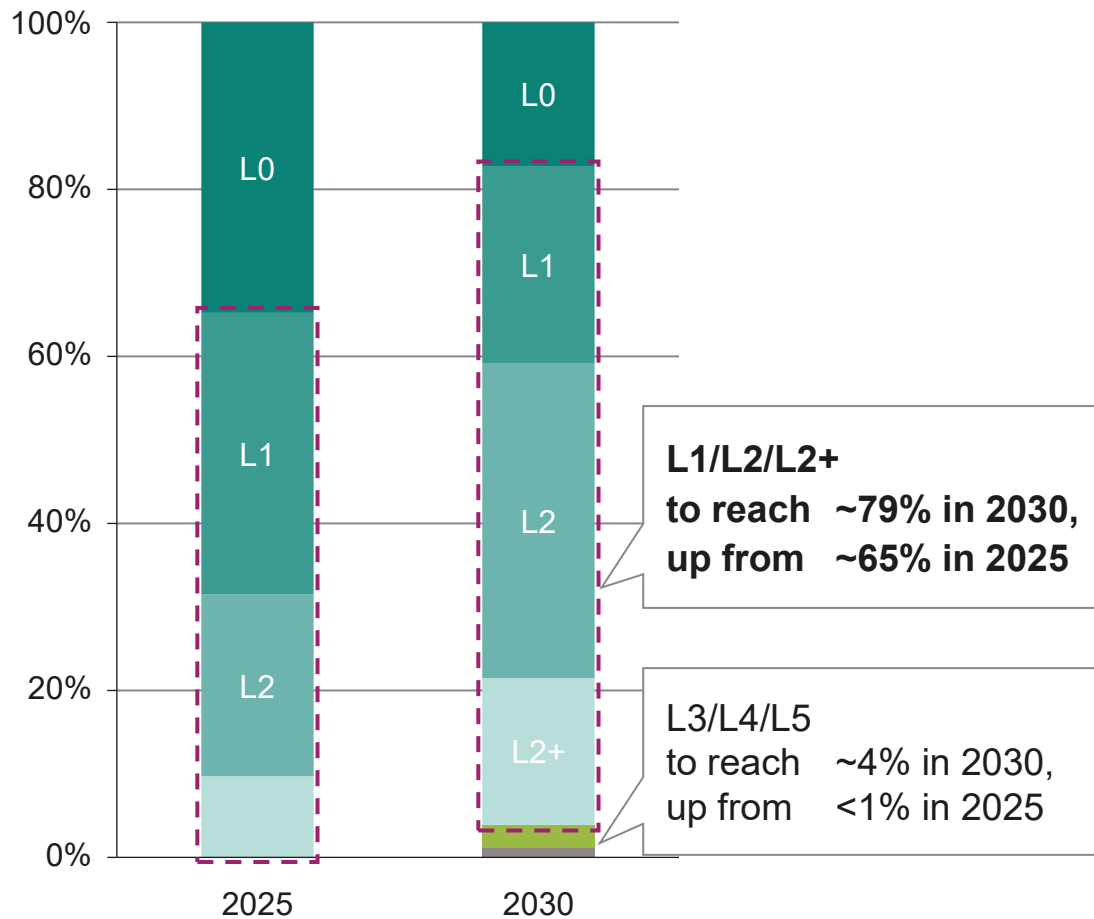
Decentral zone ECUs



- Light and small
- Simplified wire harness
- Power efficient
- Freedom from interference
- Design flexibility
- Enable ADAS/AD, x-by-wire

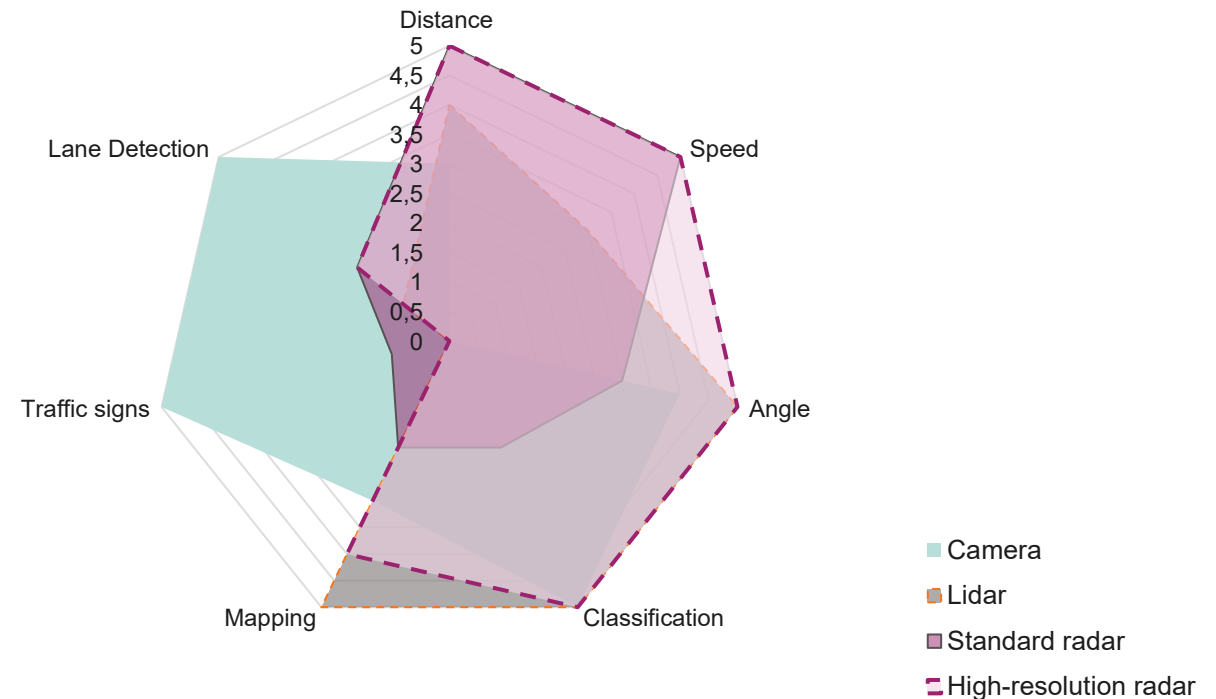
Growth of L1/L2/L2+ is the main driver of ADAS semiconductor content until 2030

Car production by degree of automation (SAE level)



Market research companies; Infineon

Radar is essential to meet decisive requirements of ADAS/AD



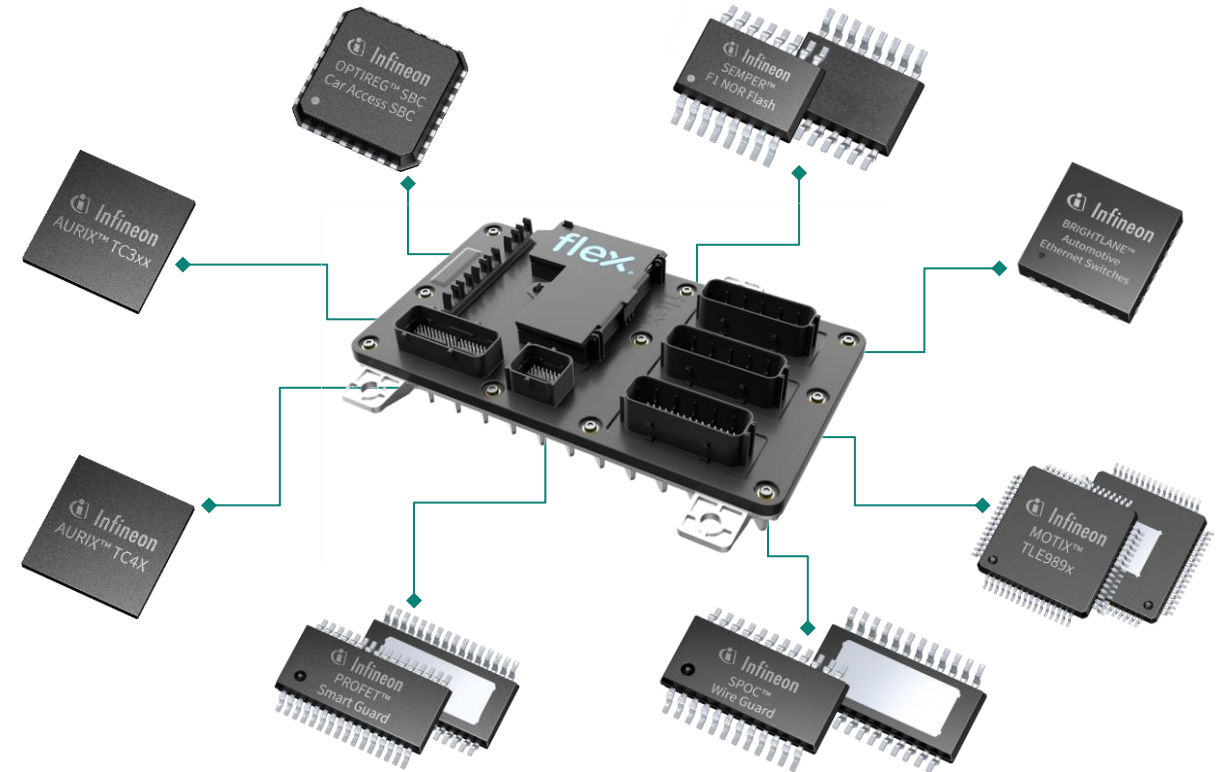
- Standard radar is the technology to detect distance and speed
- High-resolution radar significantly improves angle and classification

Infineon and Flex launch Zone Control Unit development kit for software-defined vehicles



Modular and scalable Zone Controller Unit platform to fast-track SDV-ready E/E architectures – from concept to series

- Joint ZCU development kit with Infineon and Flex hardware and Vector software to accelerate SDV development
- Modular and reusable, combining ~30 unique building blocks
- Flexible configuration enables short development cycles across ZCU variants
- Scalable approach to right-size designs for individual implementations
- Allows OEMs to realize >50 power distribution, >40 connectivity, and >10 load control channels for rapid evaluation and early application development
- Dual-MCU plug-on module for high-end ZCU implementations where high I/O density and computational power are paramount
- Infineon products account for ~70% of the ZCU platform BoM



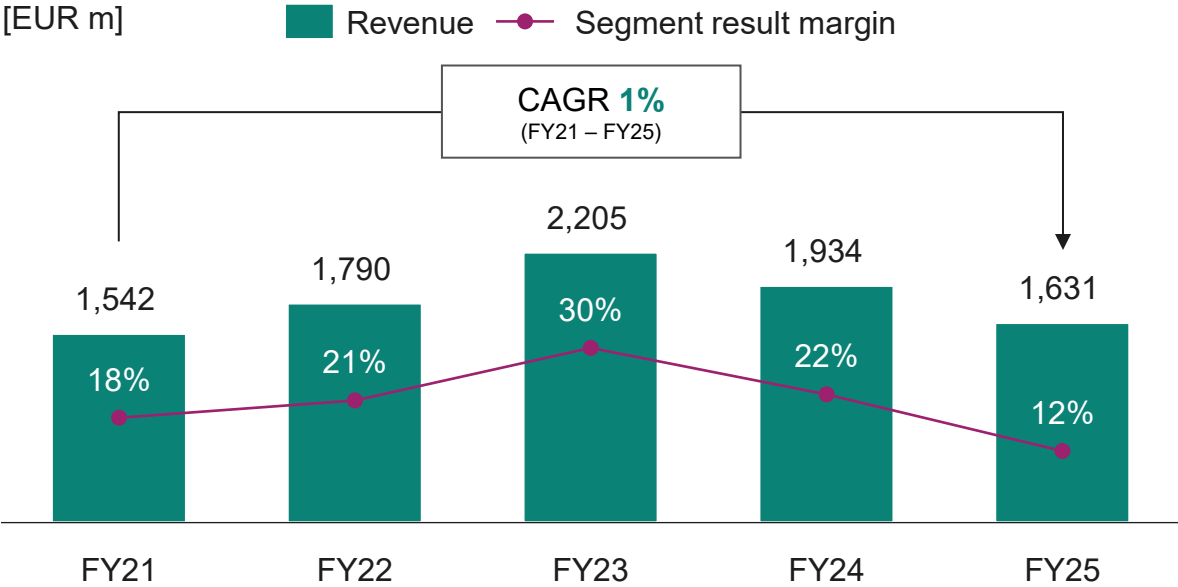
Infineon provides its best-in-class automotive semiconductor components, incl. AURIX™ MCUs, OPTIREG™ power supply, PROFET™ smart power switches, SPOC™ smart power switches, MOTIX™ motor control solutions

Green Industrial Power

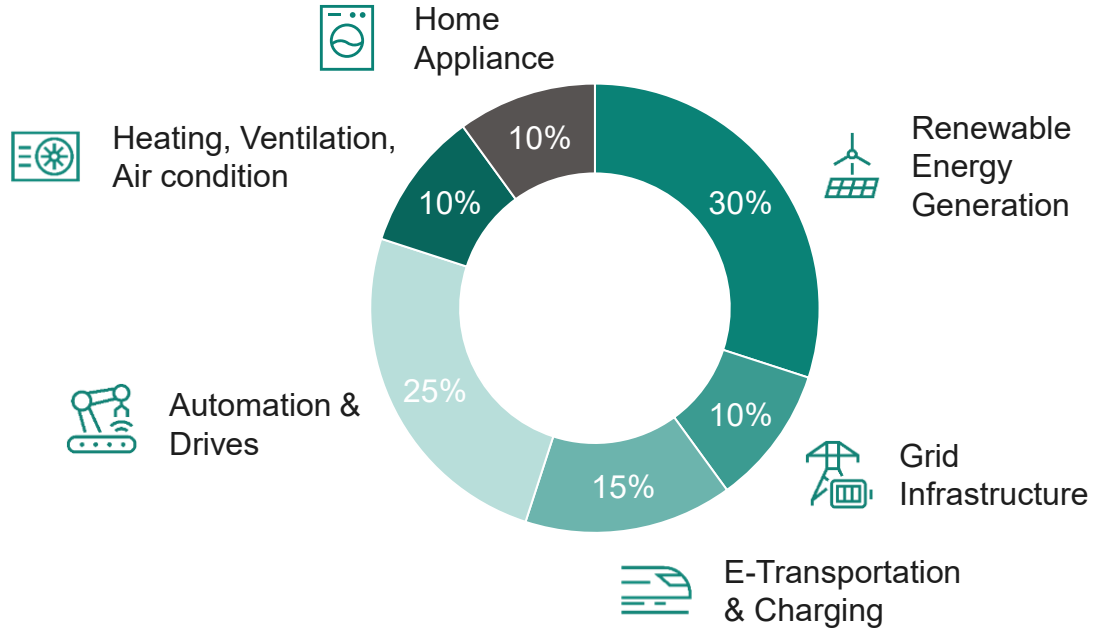


GIP at a glance

GIP revenue and segment result margin



FY25 revenue split by application





Key customers







Huge potential along entire green energy chain until 2030 according to IEA Net Zero scenario






Generation

	Photovoltaic	+ 10,300 GW
	Wind power	+3,300 GW

Infrastructure

	Grid network	\$600bn annual investments
	Grid storage	+2100 GW
	EV charging	+110m chargers (public and private)
	Electrolysis	+560 GW

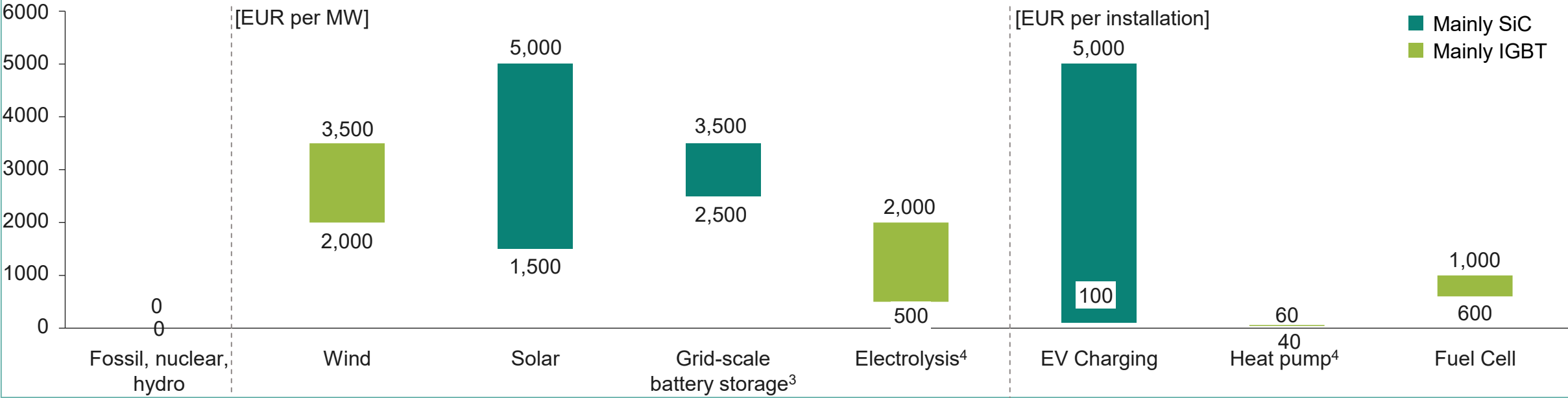
Consumption

	Heat pump	+420m units
	H ₂ Fuel cell ¹	+200k FC EV +200k FC Trucks
	eAviation eMarine	

Note: Based on Net Zero Scenario (IEA) | Source: IEA - World Energy Outlook, November 2025, OMDIA Power Semiconductors in EV Charging Infrastructure - 2025 ¹ Internal Analysis

Green energy generation provides large business opportunities

Power semiconductor content by application



Additions in 2024¹	115 GW	538 GW	62 GW	<1 GW	~6m inst.	22m inst.	5k inst.
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CAGR 2024-35	13%	17%	30%	92%²	31%	16%	42%
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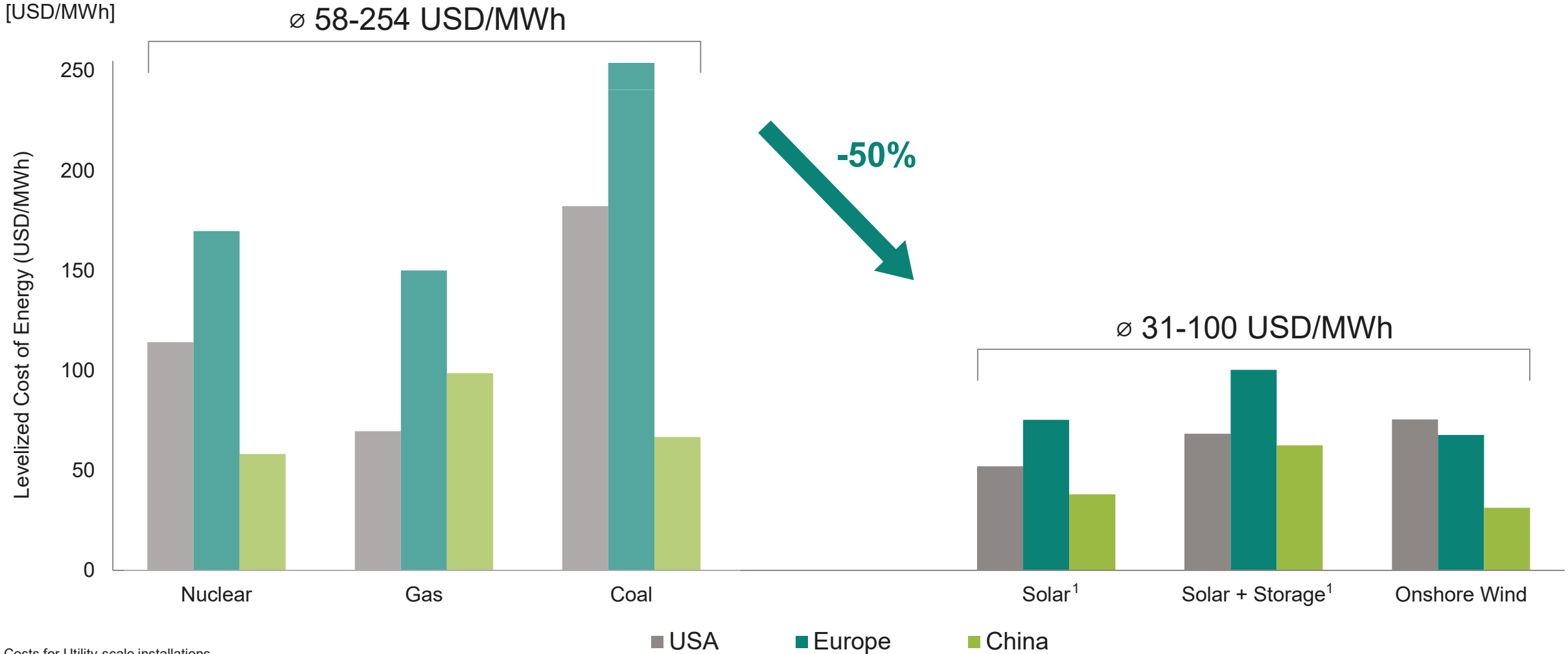
¹ IEA: World Energy Outlook, November 2025; Sector Tracking reports October 2023; internal Analysis

² Based on 270 GW pipeline (midpoint), >100% based on NZE requirements of 560GW

³ Based on assumption 80% of total battery storage equals Grid-scale battery storage

⁴ Additions in 2022, CAGR 2022-2030

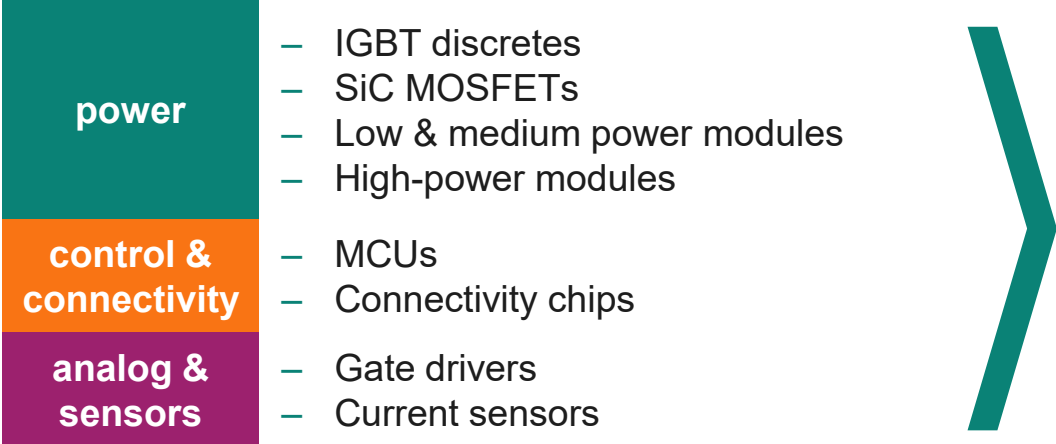
Renewables are on average the cheapest source of energy



¹ Costs for Utility-scale installations
Based on Wood Mackenzie LCOE Levelized Cost Of Energy dataset, 2024

Commercial and Utility Storage Solutions with strong growth potential

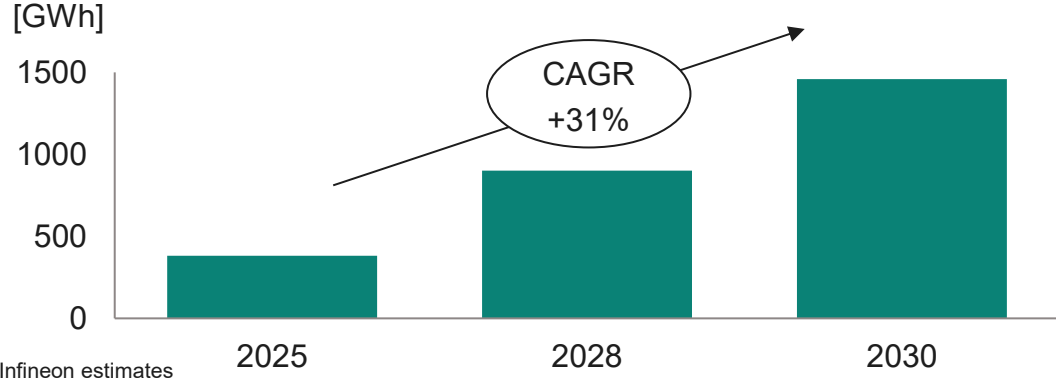
Infineon's semiconductor content for energy storage solutions (ESS)



>€2,500 per MW



Global ESS battery shipment forecast



Close engagement with key players

- ESS inverter companies
- System integrators
- Battery OEMs



Solid-state transformers: new application for semiconductors with significant additional market potential

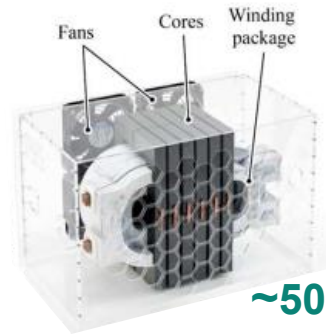
Conventional transformer



~20 t

Conventional transformer market
>USD 15bn

Solid-State transformer (SST)



~500 kg



~40x lighter¹
~14x smaller¹
~50% faster construction time



EasyPACK™



Infineon expects that **SST will replace a portion of the market**, specifically small power transformer with an expected market of **>USD 1bn in 2030**

Early involvement with leading electronics companies and hyperscalers on architecture & design in Europe, Americas and Asia, e.g:



¹ Comparison refers to multi modular inverter (dual stage with HFT) based on own estimations.

Solid-state circuit breakers: increased safety, energy efficiency and reliability in power distribution

Analog circuit breaker

Traditional electromechanical analog circuit breakers protect electrical circuits against overloads and short circuits



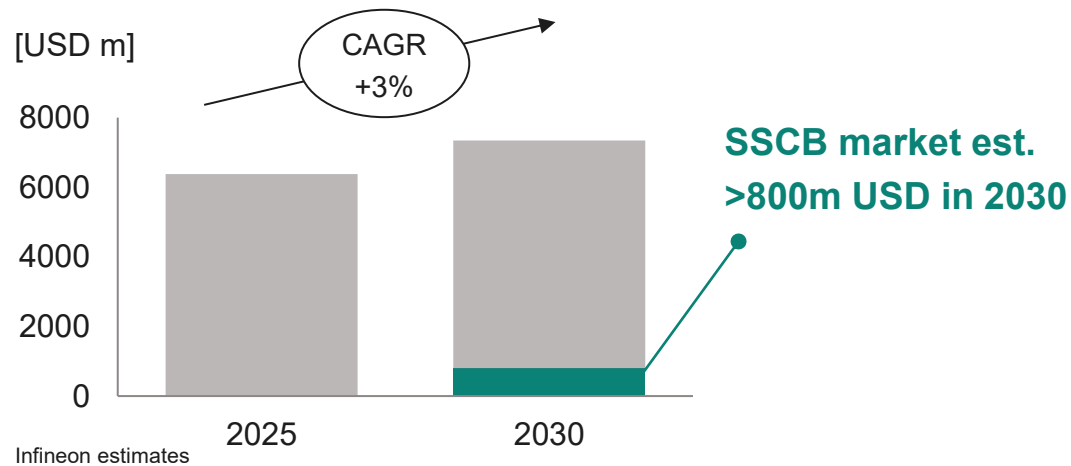
Digital solid-state circuit breaker

Enables **smart energy management**:

- Ultra-fast overload and short circuit **interruption**
- Integrated **monitoring**
- **Remote control**



Industrial electromechanical circuit breakers



ECPD, *Electronic Circuit Protection Device*



Courtesy of Siemens

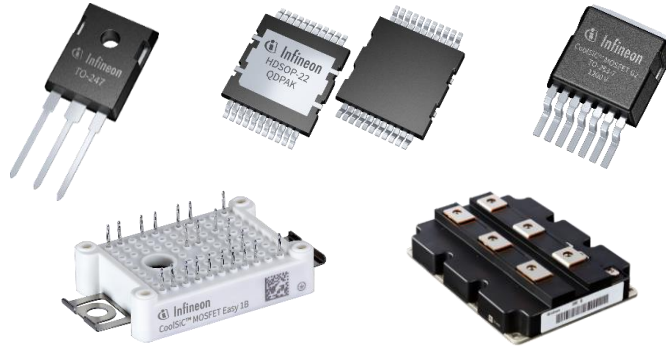
Adding CoolSiC™ JFET to MOSFETs: Infineon offers most comprehensive SSCB portfolio in the industry



Sampling now, start of
production in 2026



Q-PAK with CoolSiC™ JFET



More than 20 SSCB key
customers and
first Design-Wins
with CoolSiC™ JFET



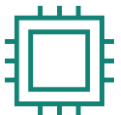
Energy savings

- ✓ Provides ground-breaking ultra-low $R_{DS(on)}$ 1.5m Ω at 750 V and 2.3 m Ω at 1200 V V_{BDss}



Robustness and reliability

- ✓ Designed and tested to handle extreme over-voltage, over-current and short-circuit conditions



Integration and scalability

- ✓ Developed for ease-of-integration, scalability and manufacturability for industrial and automotive applications



Low triple-digit million Euro design-win for Alpitronic's centralized megawatt charging system

Design win for Alpitronic's new HYC1000 centralized hub with charging points – one hub provides power to charge up to 8 EVs simultaneously.

Infineon products are enabling >97.5% system efficiency

- SiC power modules, gate driver ICs and PROFET™ providing 1MW of total power.
- SiC modules are based on highly differentiating M2.XT connection solution. Instead of using many bond wires, M2.XT uses large-area metal contacts, which reduce resistance and improve thermal performance and robustness – enabling 25% more power density.
- HYC1000 system already in production.

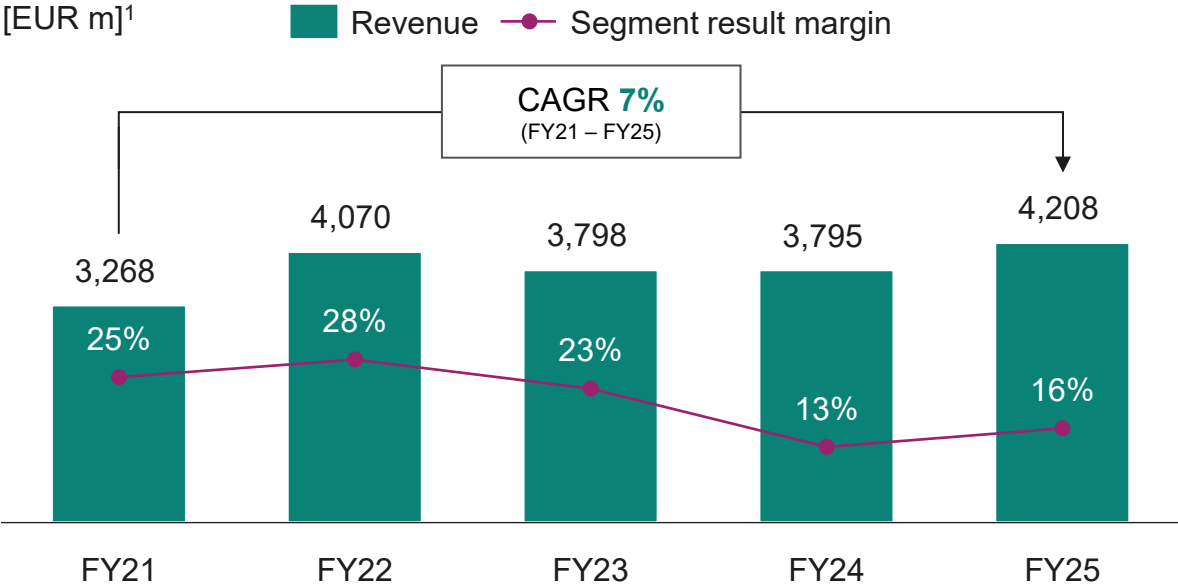


Power & Sensor Systems



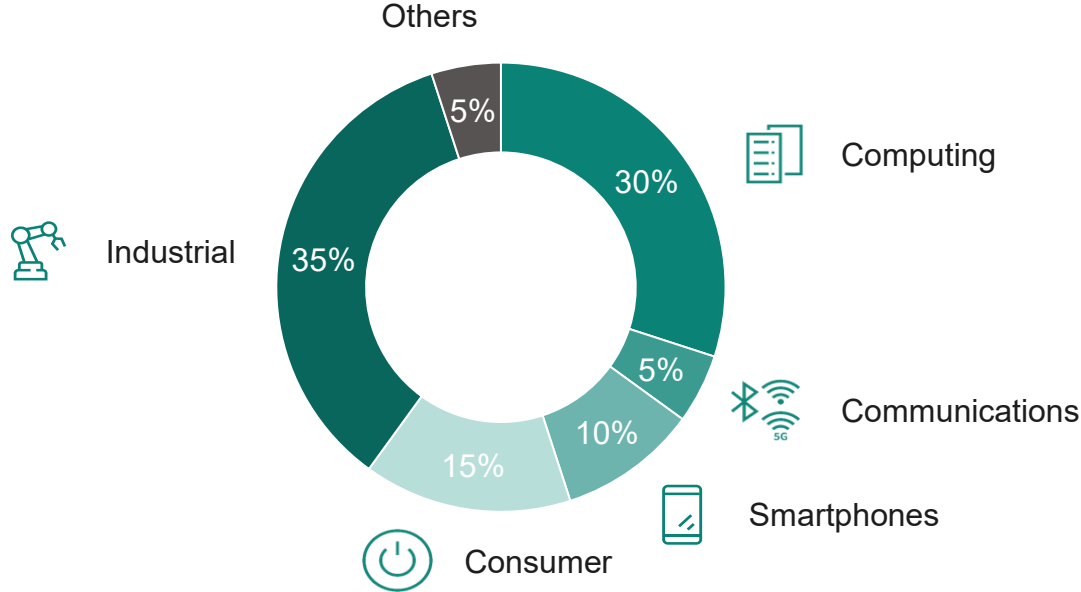
PSS at a glance

PSS revenue and segment result margin



¹ Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

FY25 revenue split by application



Key customers

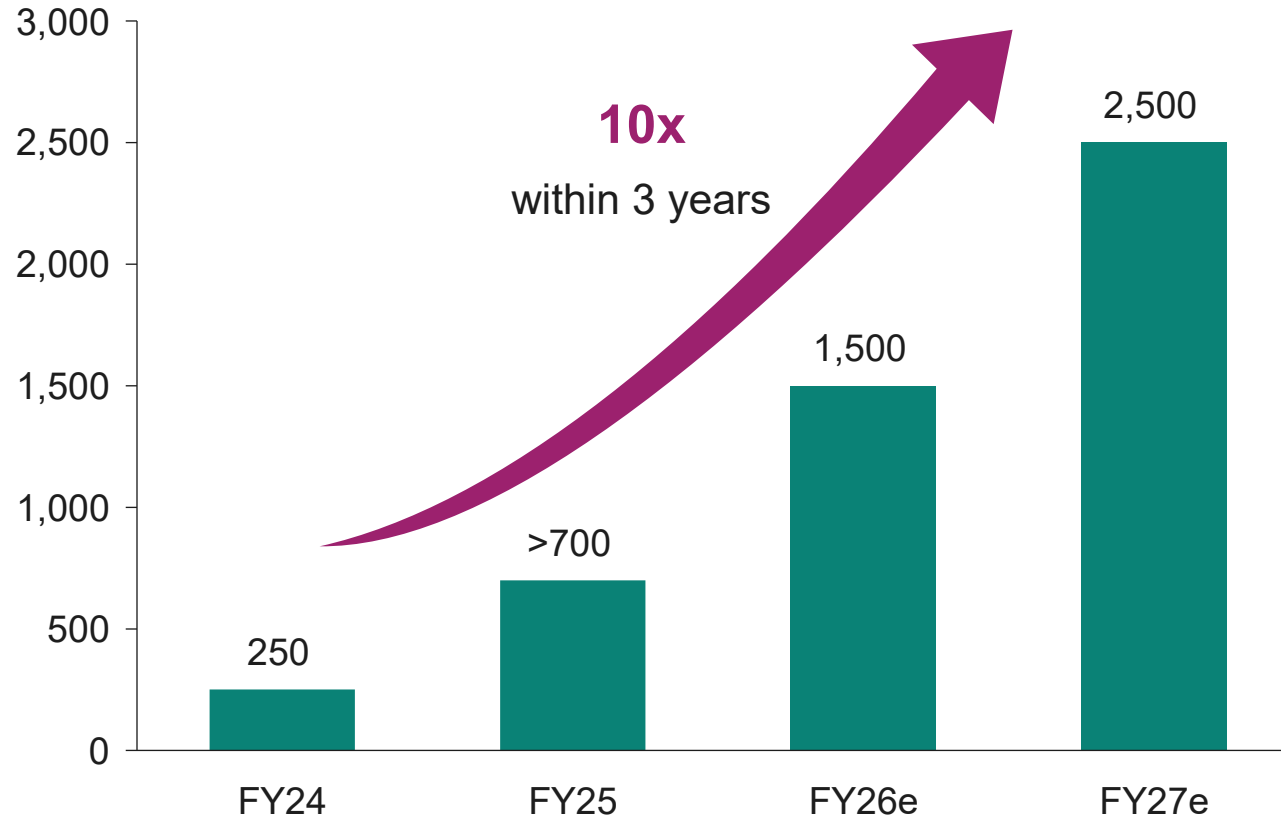
Significant acceleration of our AI revenues due to most advanced technology and broadest portfolio



Infineon is growing together with customers driven by significant AI investments

Revenues from powering AI datacenters

[EUR m]



In FY25, our AI server business achieved **>€700m** nearly tripling vs. FY24

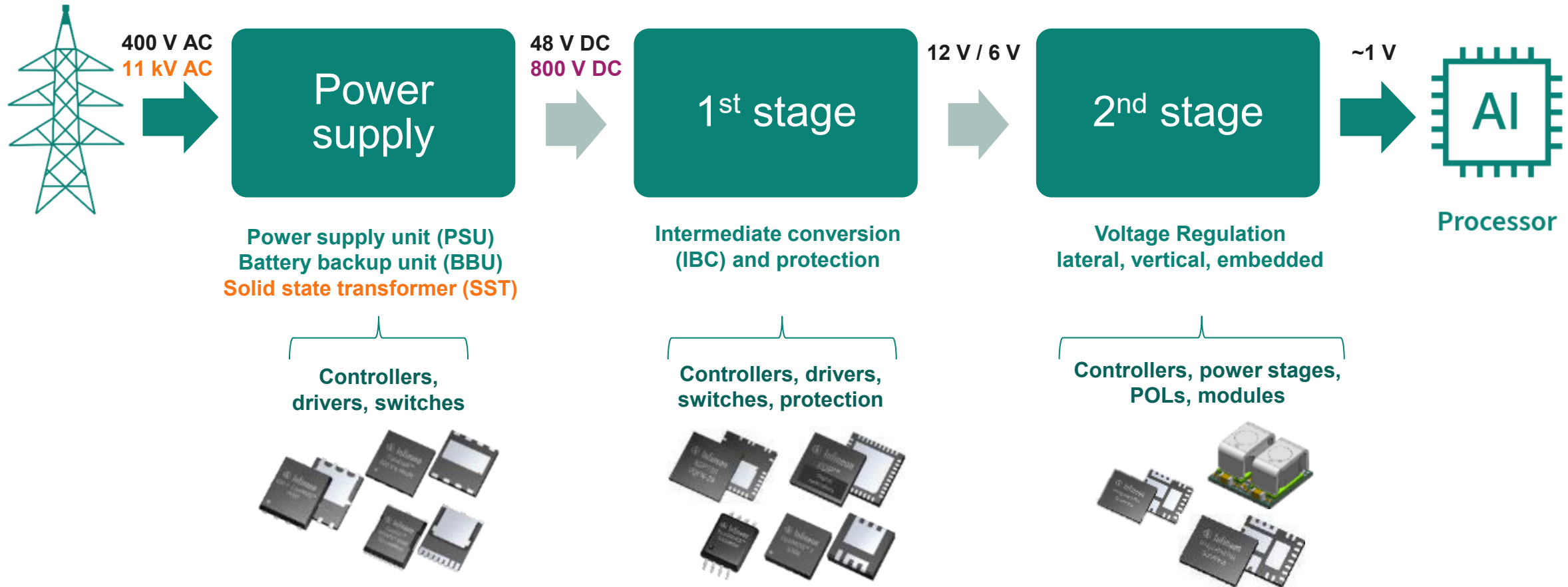
We expect to **more than double** our revenue to **~ €1.5bn** in FY26 and project to achieve **around €2.5bn** in our **2027** fiscal year

Infineon AI **power content per kilowatt** in the range of **\$100-250** **\$175/kW** average today

With its energy efficient power semiconductors Infineon is serving all AI-related power conversion from grid-to-core



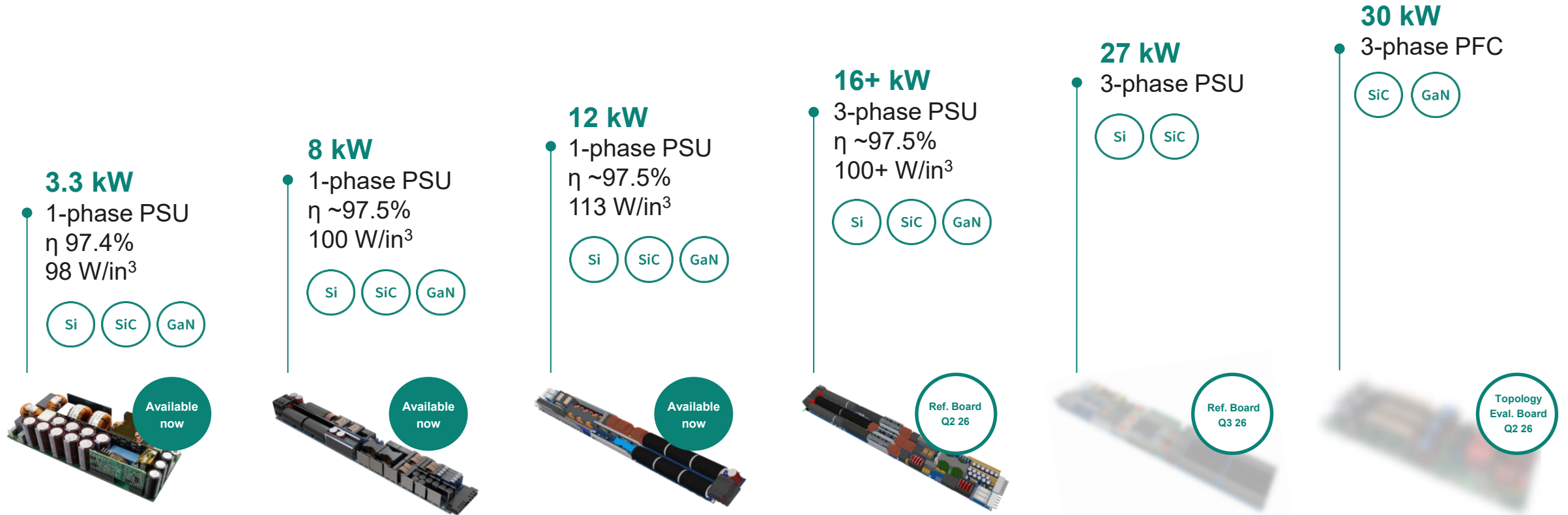
Server power flow for Gen 1 / Gen 2 / Gen 3 server rack architecture



Innovative 3-phase PSU system solutions leverage system expertise and IP to deliver industry-leading performance and efficiency



Infineon's solutions range from 3 kW to 30 kW



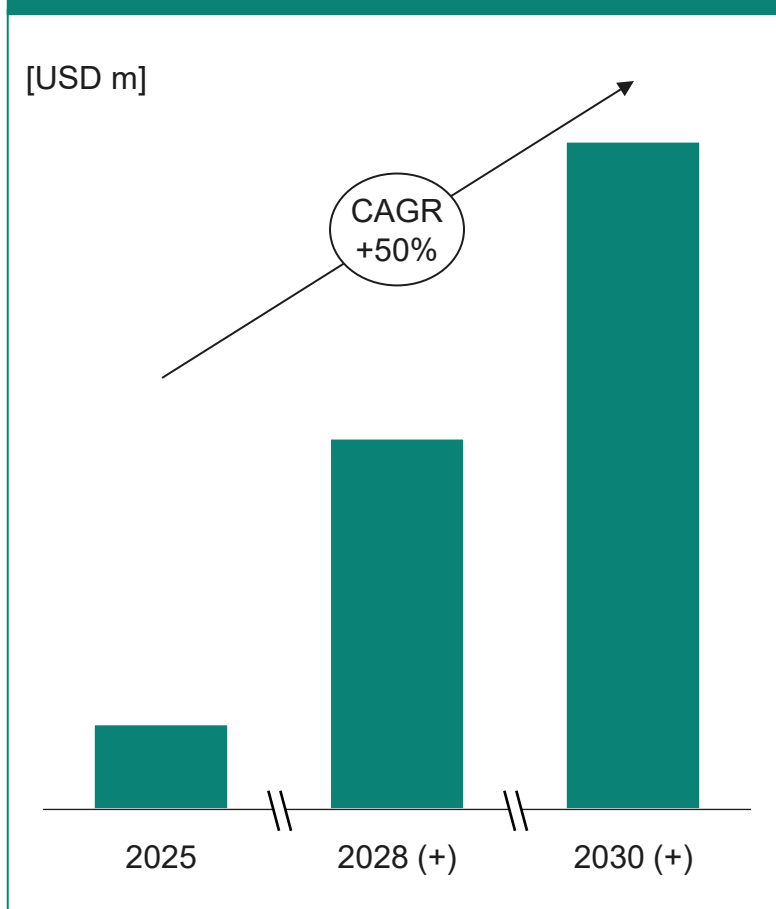
Rising power demands require the transition to advanced three-phase PSU architectures

1-phase PSU

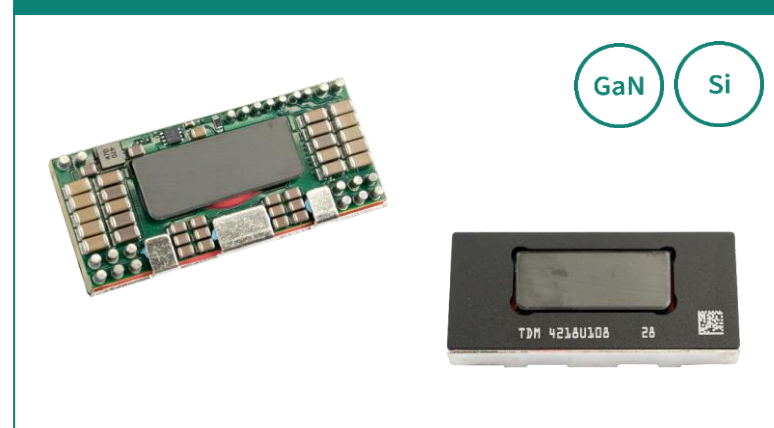
3-phase PSU

Infineon offers a broad portfolio of HV & MV IBCs for current and future AI server rack architectures

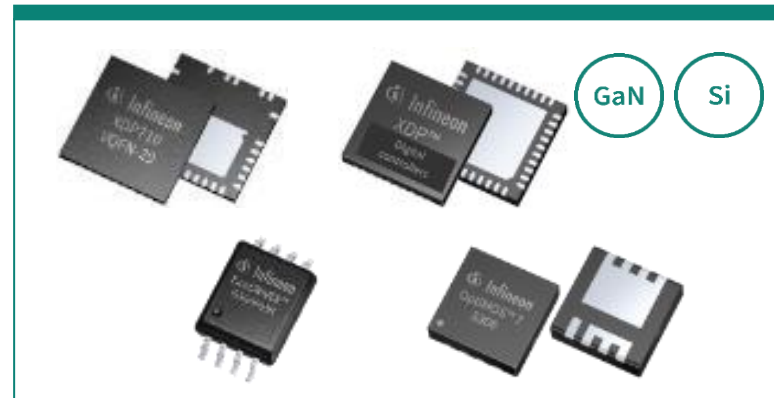
SAM IBC Market



Infineon IBC Module for AI



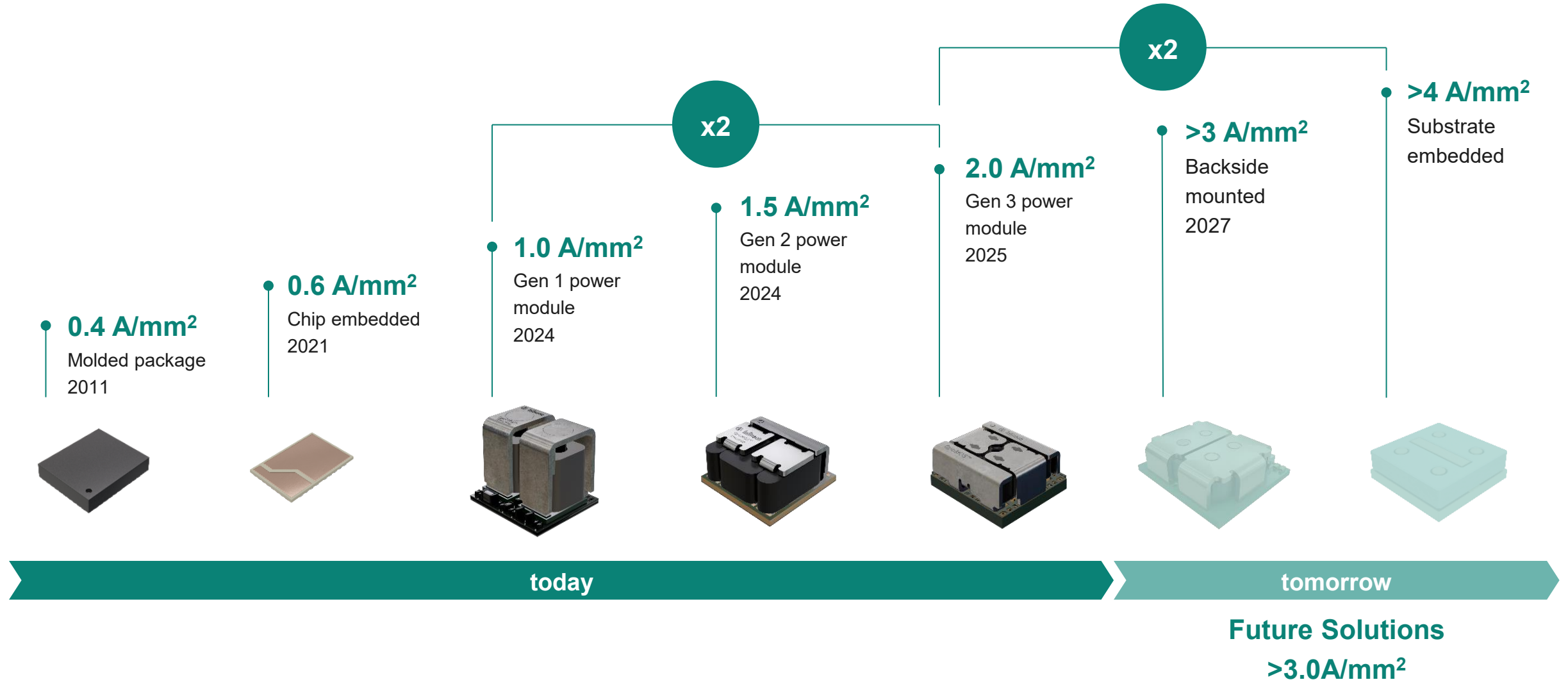
Discretes



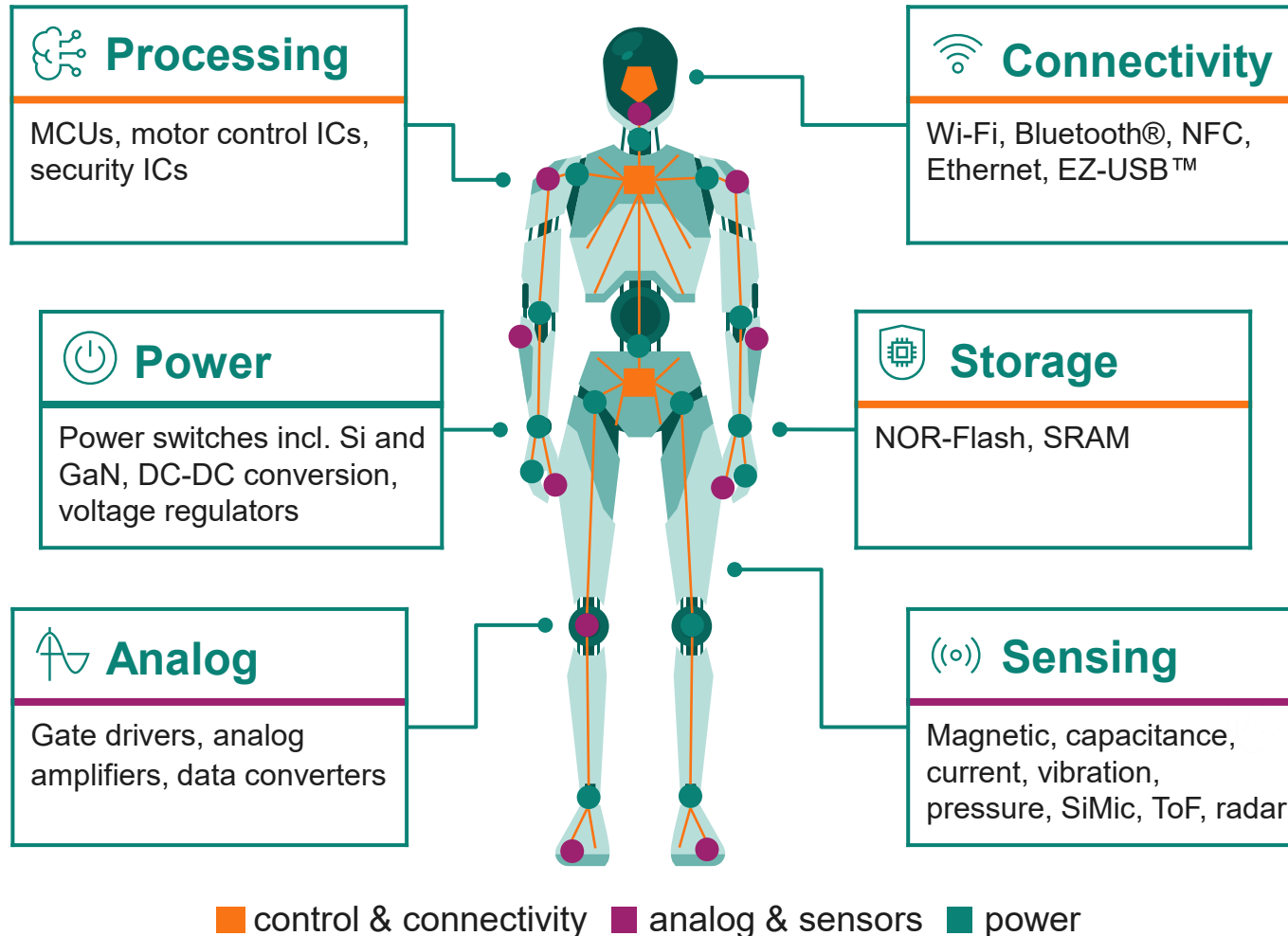
Meeting customer requirements

1. With a wide range of **IBC topologies**, Infineon is serving a multitude of data rack configurations while ensuring cost-effectiveness
2. **Quality and Reliability** to improve mean time between failures in complex systems
3. **Power density** as GPU power increases
4. **Efficiency** for total cost of ownership
5. **Thermal Management** in air / liquid cooled environments
6. **Supply security** with 2nd source and fast time to market

Highest-density VRM modules enable true vertical power delivery adjacent to the processor



We empower humanoids to sense, move, act and connect. Safe and secure.



~\$500

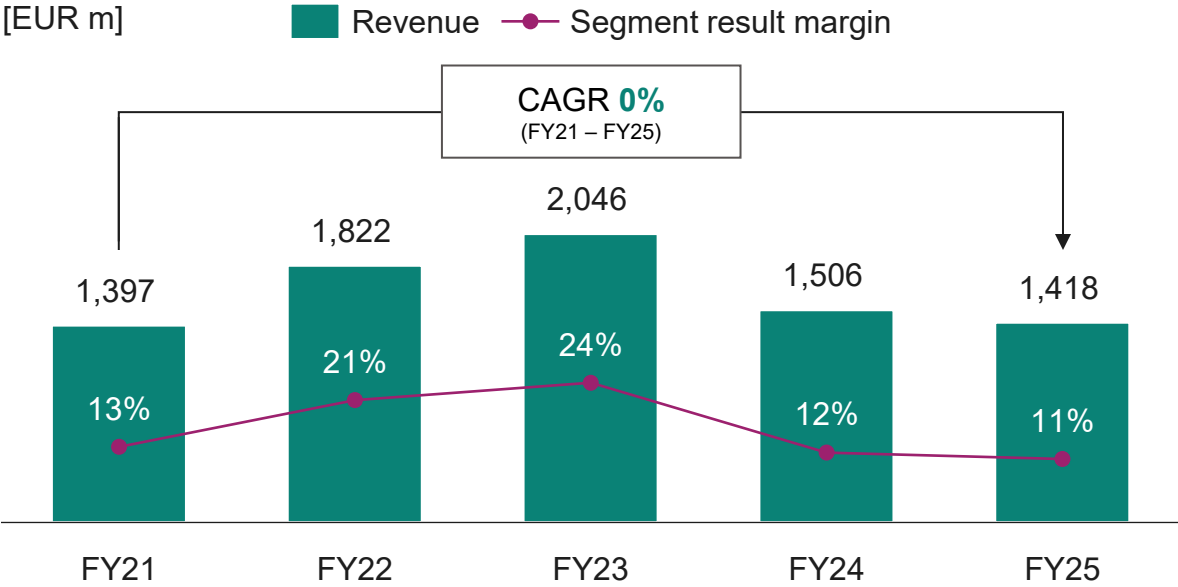
Infineon's addressable content
per humanoid robot

Connected Secure Systems

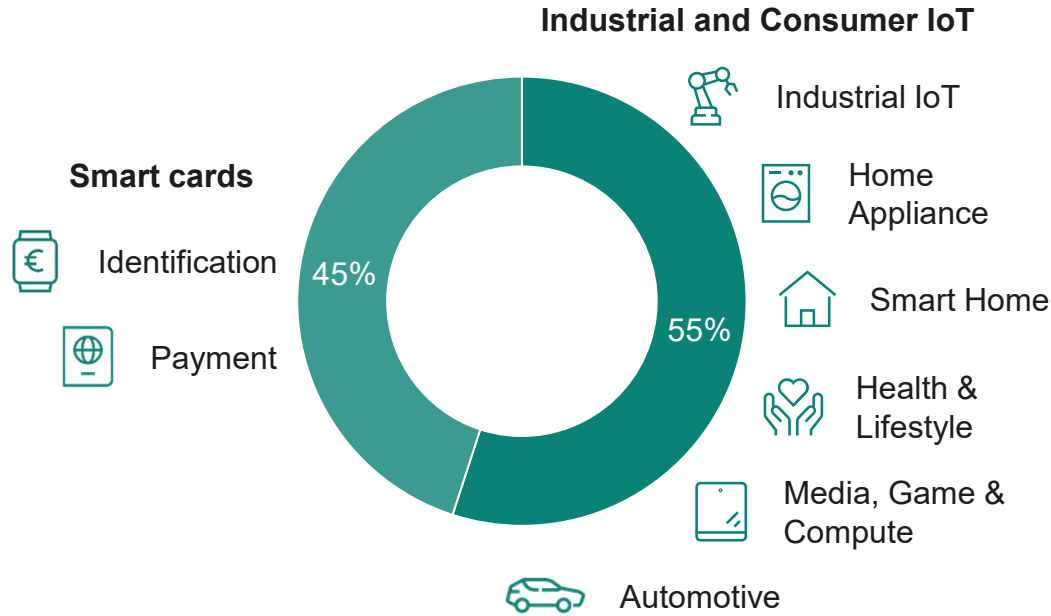


CSS at a glance

CSS revenue and segment result margin



FY25 revenue split by application



Key customers



Providing the essential building blocks compute, connectivity, security, and software



Consumer



Industrial



Automotive

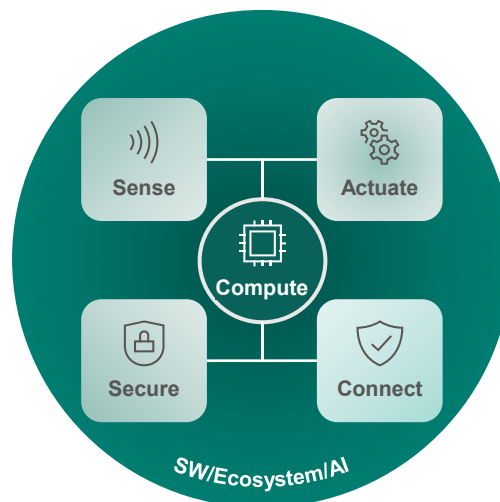


Compute

PSOC™ and **XMC™** micro-controllers allow customers to enable smart, connected products

Security

OPTIGA™, **SECORA™** and **TEGRION™** solutions provide robust embedded security for IoT devices, authentication, payments, identification, and access control



Software

DEEPCRAFT™ Studio and **ModusToolbox™** software simplifies and accelerates development for Infineon MCUs

Connectivity

AIROC™ Wi-Fi and **Bluetooth®** products provide ultra-robust, low-power wireless communications

CSS seamlessly interconnects **compute, connectivity, security, and software** - the essential building blocks of digitalization

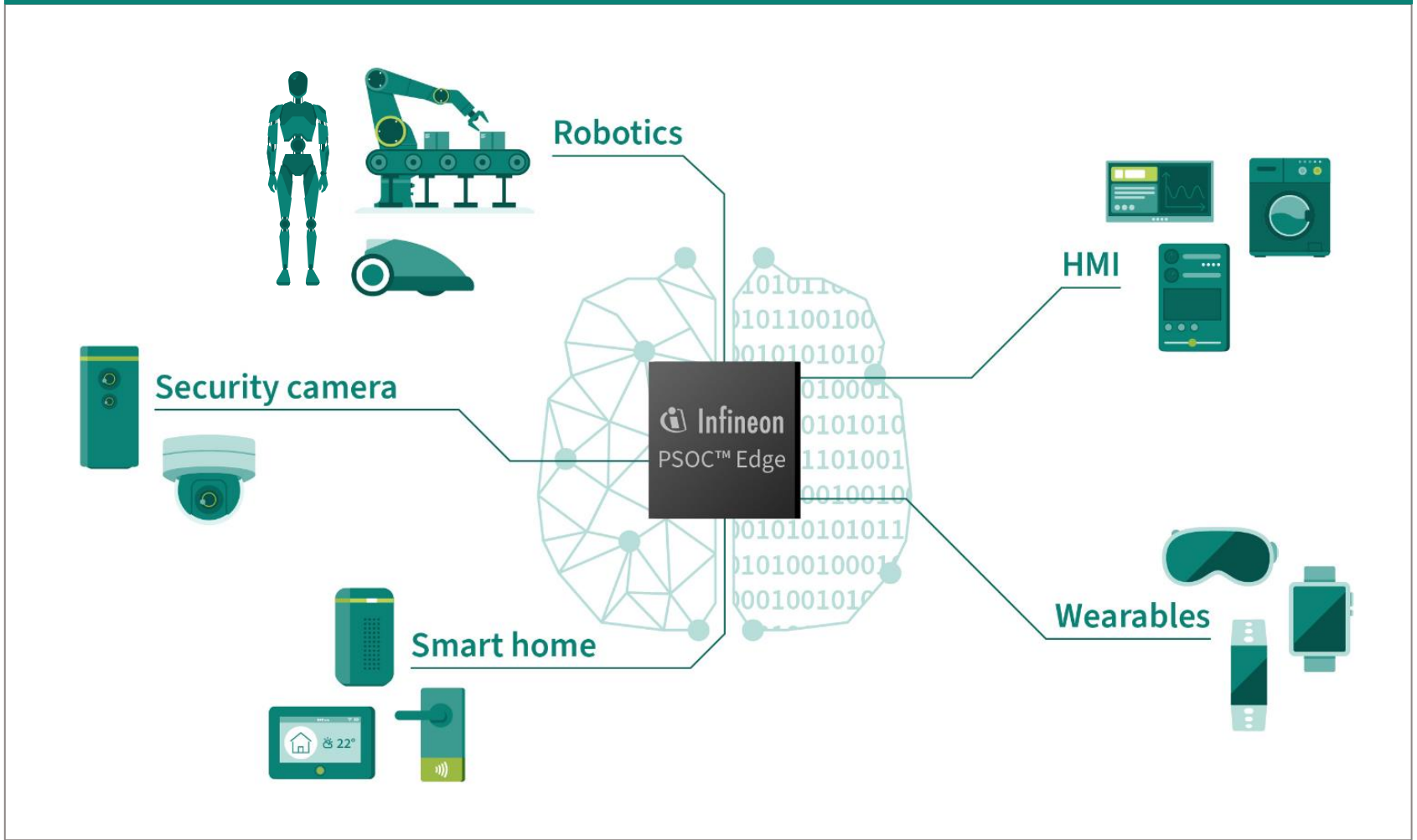
Infineon's MCUs at the heart of every IoT and Edge AI application

New compelling MCU platforms



- Broad application range in **Edge AI, IoT, Consumer, and Industrial**
- Strength in **low power, high performance, security, and reliability**
- Roadmap focus on **AI, security, and integrated connectivity**

PSOC™ Edge – Enables a new generation of responsive machine learning devices



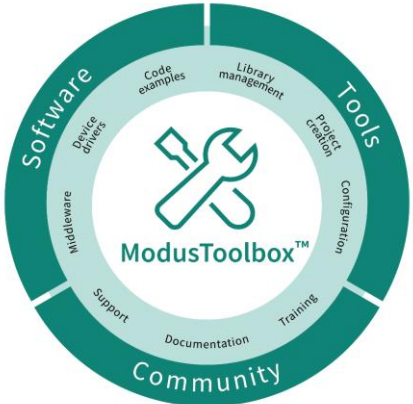
Software with maximal ease of use

DEEPCRAFT™ Studio



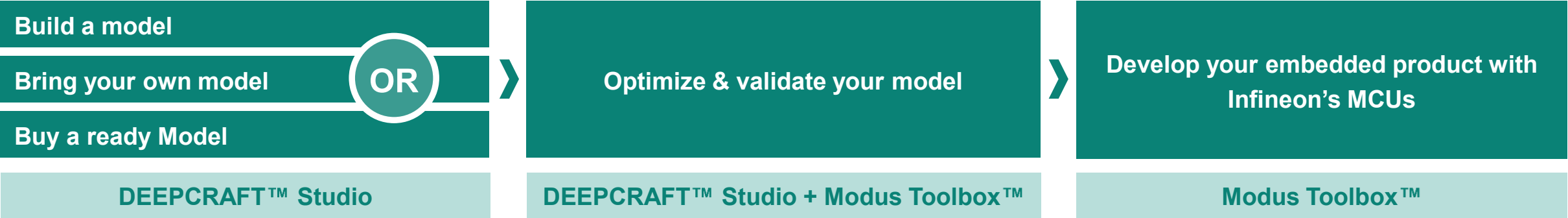
- Infineon’s Edge AI development platform
- Data collection & pre-processing, model training, model conversion & deployment
- Provides AI-models for a wide variety of applications

ModusToolbox™



- Infineon’s modern, extensible development system
- Collection of development tools, libraries, and embedded runtime assets

Full journey from Edge AI model development to embedded software with flexible entry



Enabling connectivity with Infineon's broad wireless portfolio for IoT, industrial, and automotive applications



Wireless connectivity portfolio & advancements in ultra-wideband

Wi-Fi AIROC™

- **Comprehensive Portfolio:** Wi-Fi 4,5,6/6E and connected MCUs
- **Ultra-low power** consumption
- **Integrated MCUs** for simplified IoT design
- Advanced Wi-Fi 6/6E with **future-ready Wi-Fi 7** capabilities



Bluetooth® AIROC™

- **Full-featured Bluetooth®** portfolio with SoCs and modules
- **Low-energy focus** for extended battery life
- **Long-range Bluetooth® Low Energy (LE)** for industrial and automotive applications



Wi-Fi- & Bluetooth® Combo AIROC™

- Combines Wi-Fi and Bluetooth® in one module for **dual-connectivity use cases**
- Pre-certified for **faster time to market**



UltraWideband

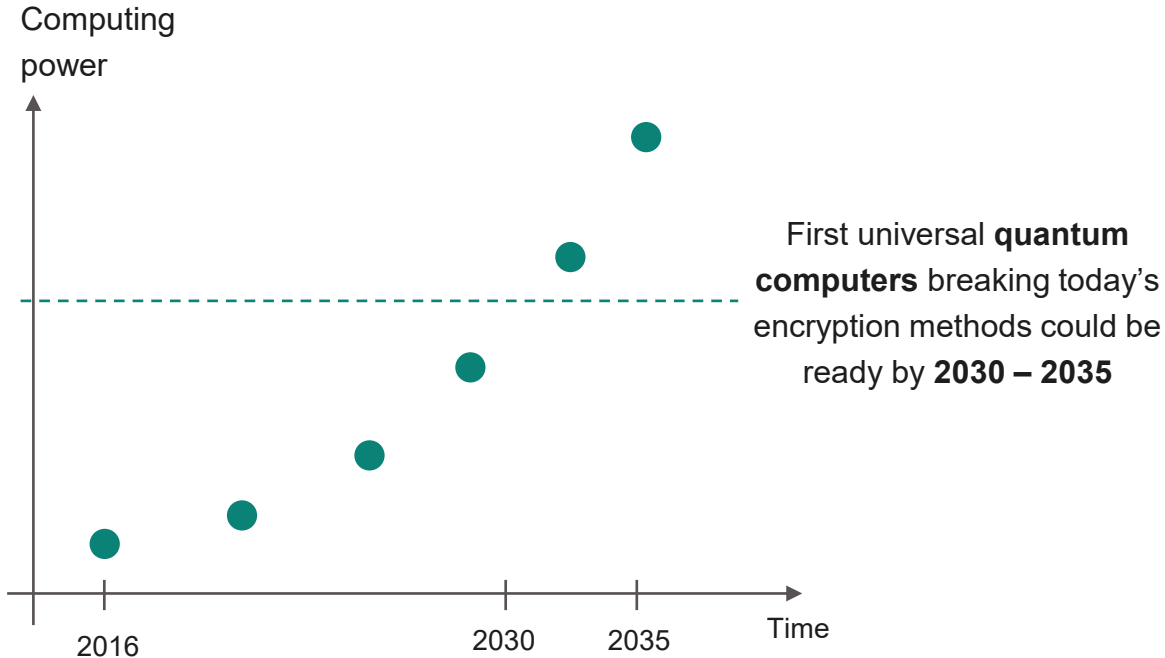
- Acquisition of UWB pioneer **3db**
- **Target applications:** Car access and fine ranging



As quantum computing rises and introduces high security risks, Infineon serves as a trusted advisor in the PQC landscape.



Computing power of quantum computers



Cybersecurity

- **Asymmetric** encryption algorithms (e.g. RSA, ECC) lose appropriate security
- **Symmetric** encryption algorithms are less affected

Threats

- To **sensitive data** from governments and public institutions
- To **products** with long R&D cycles

Legislations

- Government bodies are **working on legislations** to prepare for quantum-safe future

Infineon's post-quantum cryptography approach



Infineon is the **first company to receive the Common Criteria EAL6** for the implementation of a **PQC algorithm** in a security controller



Infineon **TEGRION™** product family of **next-gen security controllers** for long-lasting security and superior fault protection



Partnering with customers, partners, and the academic community to prepare for a post-quantum future



Global team of experts and researchers dedicated to the PQC field

Selected financial figures

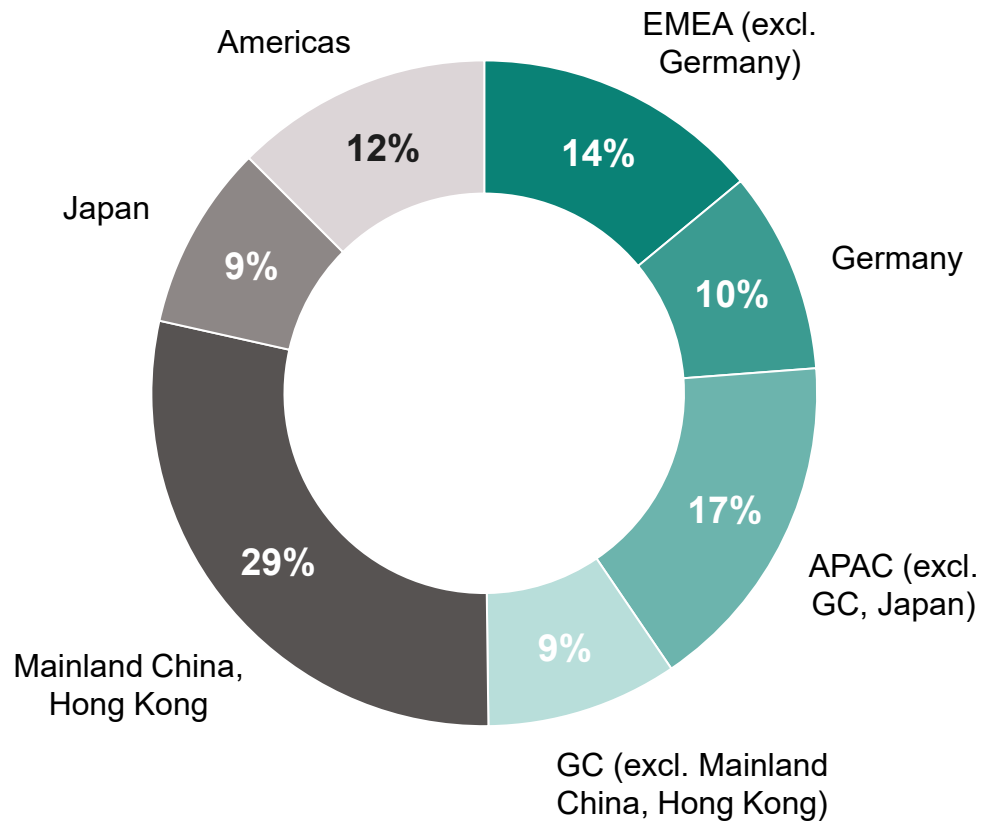
+0.72▲	634.270	3.984%	369,000
-0.51▼	538.014	2.416%	743,000
3.16▲	692.360	0.657%	405,000
.23▼	237.981	0.103%	882,000



Strong presence in all regions; well-balanced customer portfolio; no customer represents more than 10% of total sales

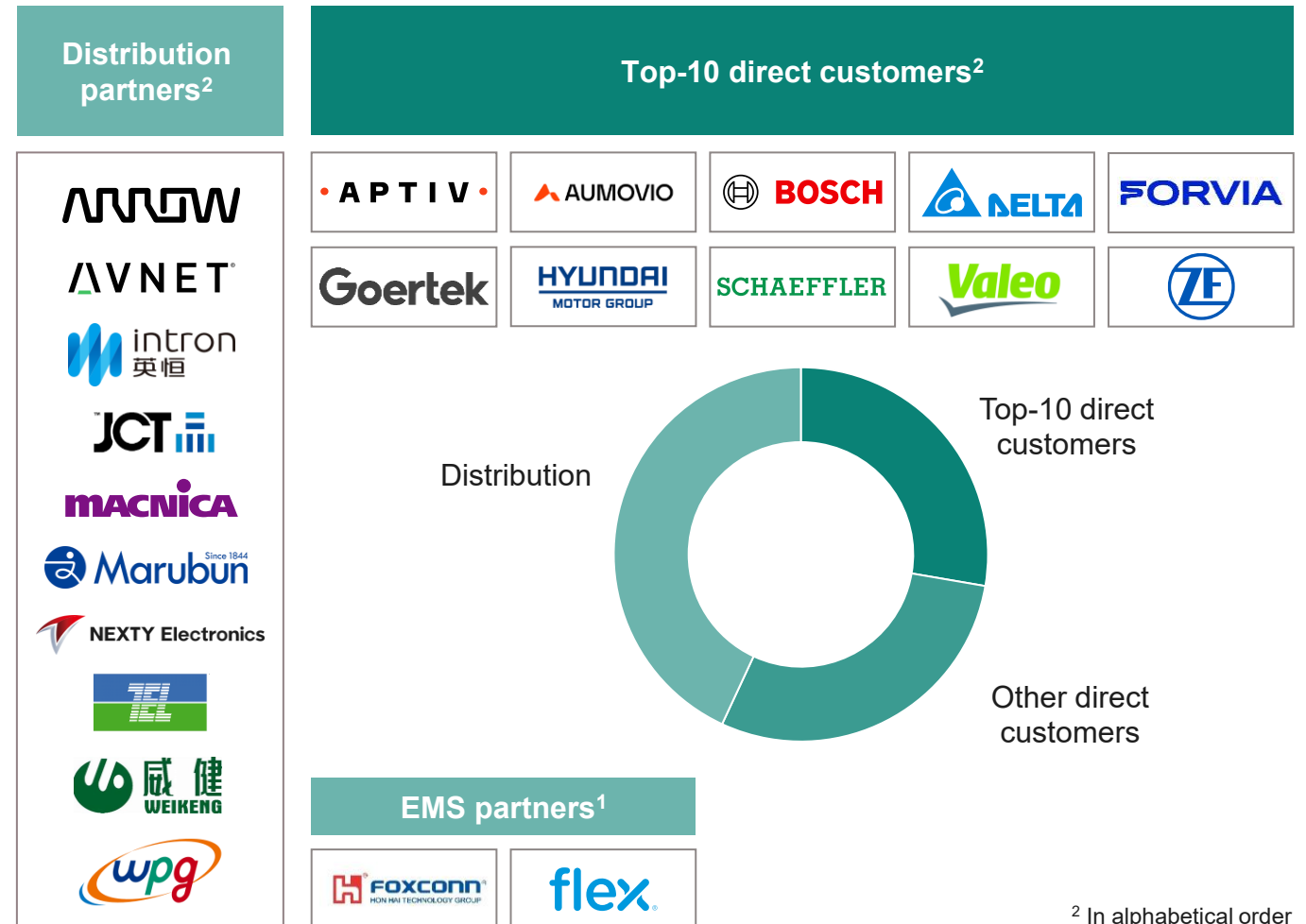


FY25 revenue by region¹



¹ Based on sold-to logic

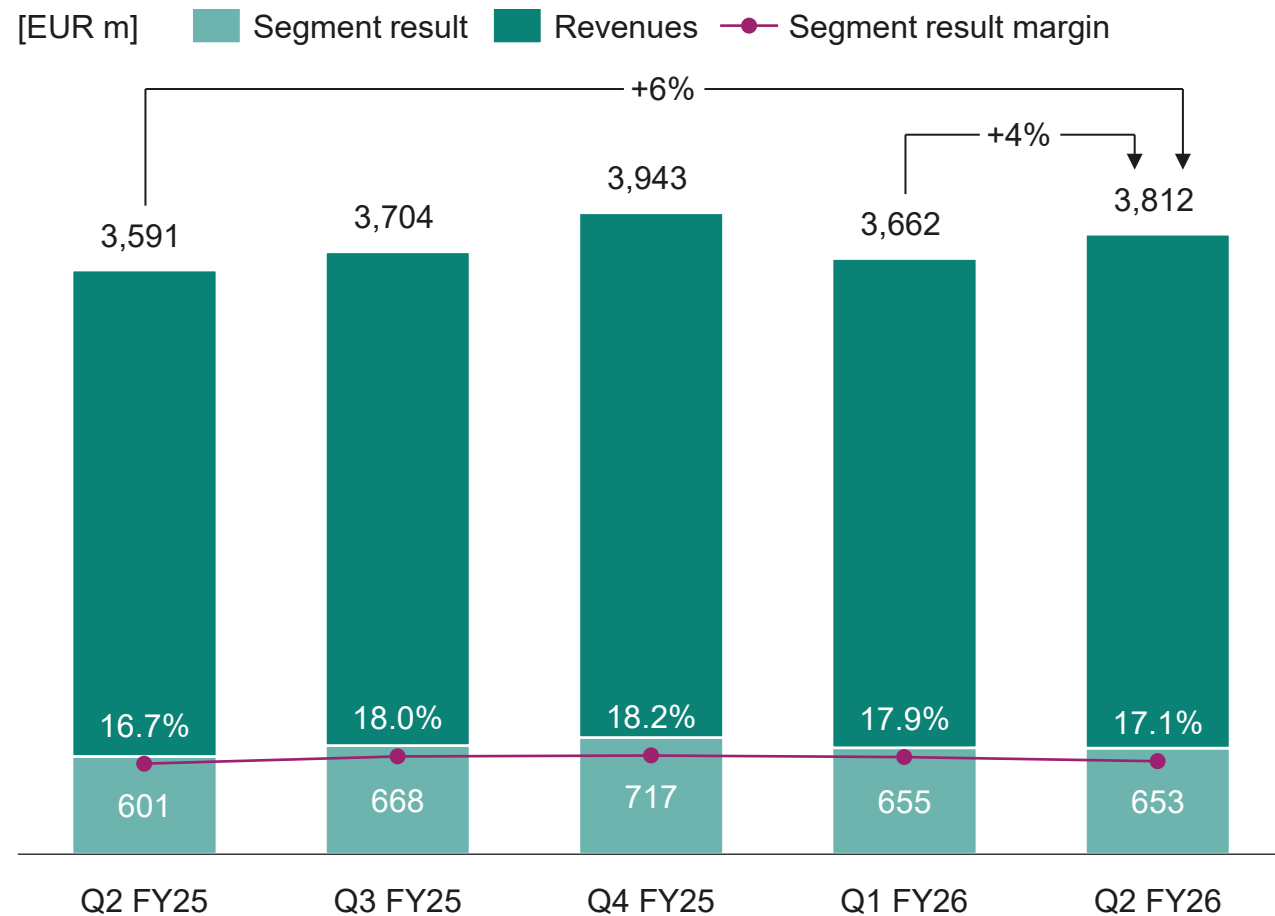
Revenue by sales channel



² In alphabetical order

Group financial performance

Revenues and Segment Result

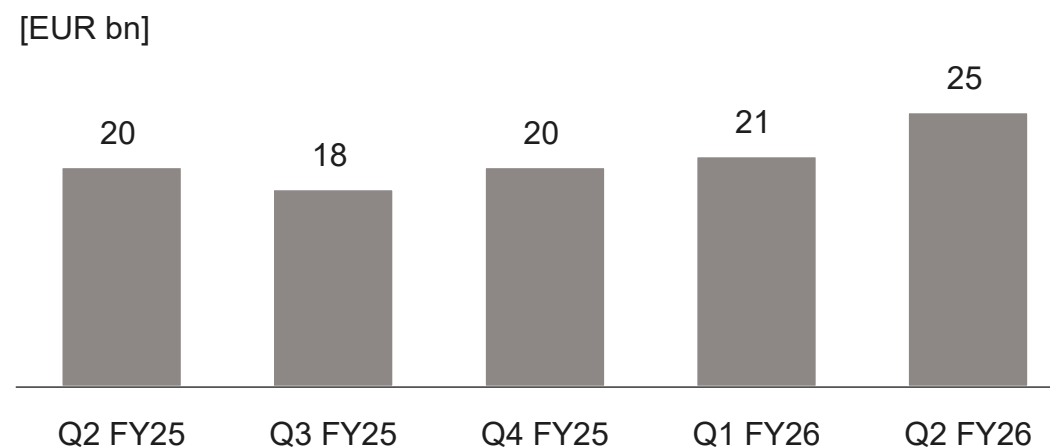


USD exchange rate

Average revenue exchange rate

	Q2 FY25	Q1 FY26	Q2 FY26
∅ USD/EUR	1.05	1.16	1.17

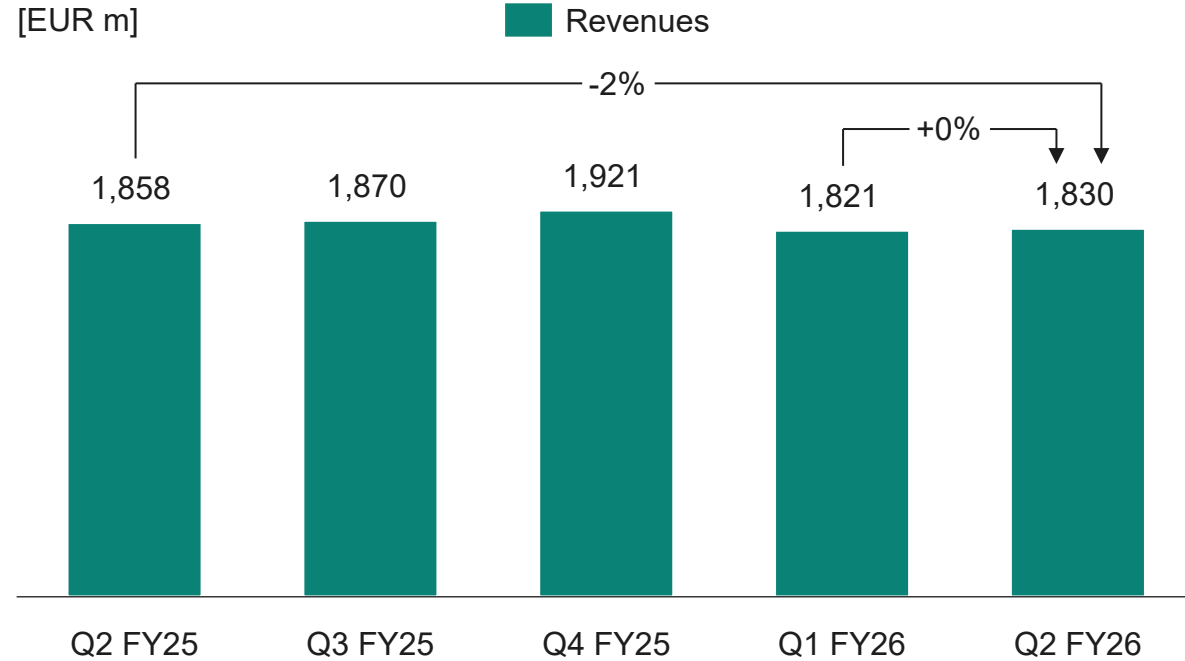
Order backlog¹



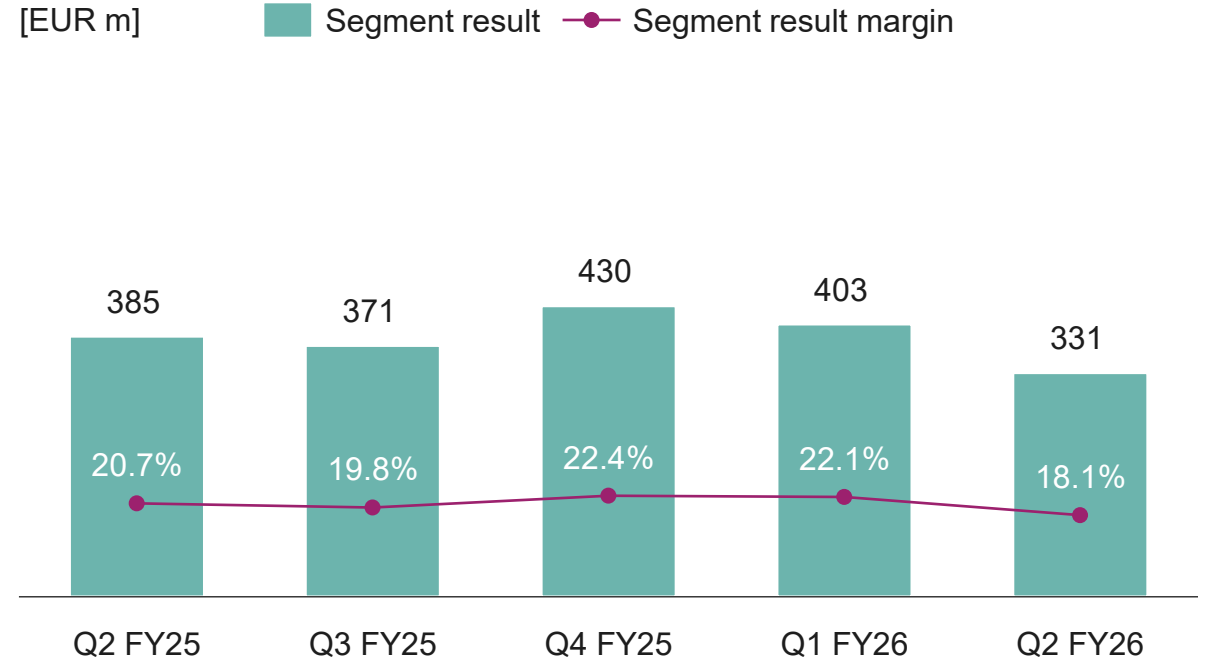
¹ See notes for definition

Automotive (ATV)

Revenues



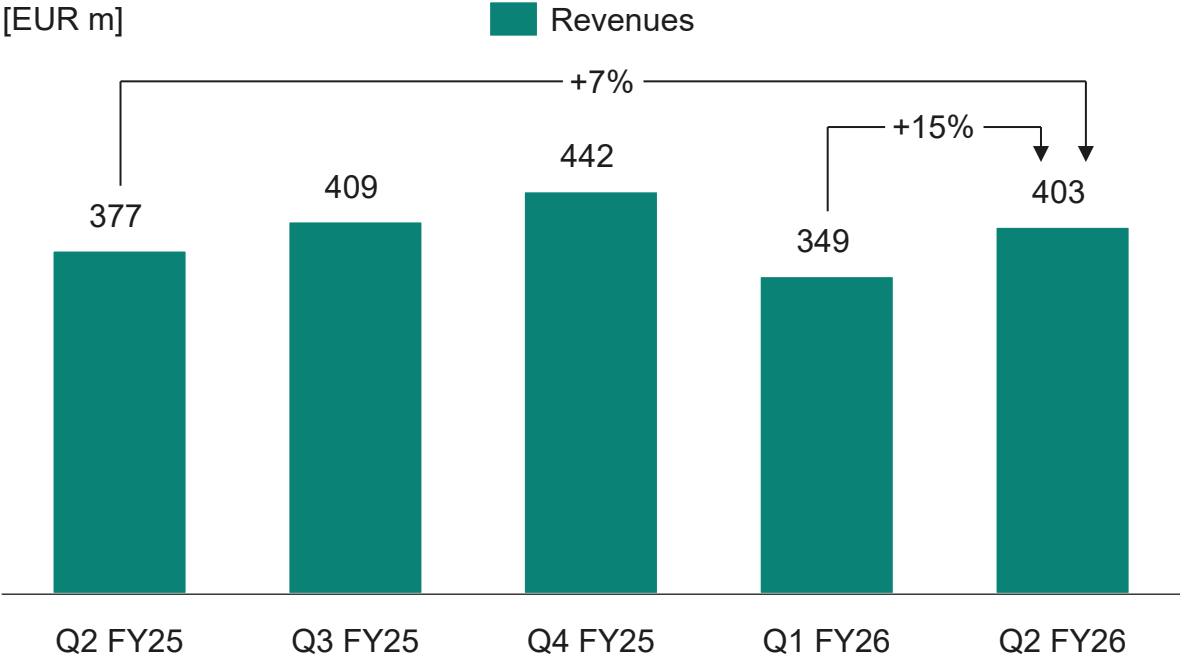
Segment Result



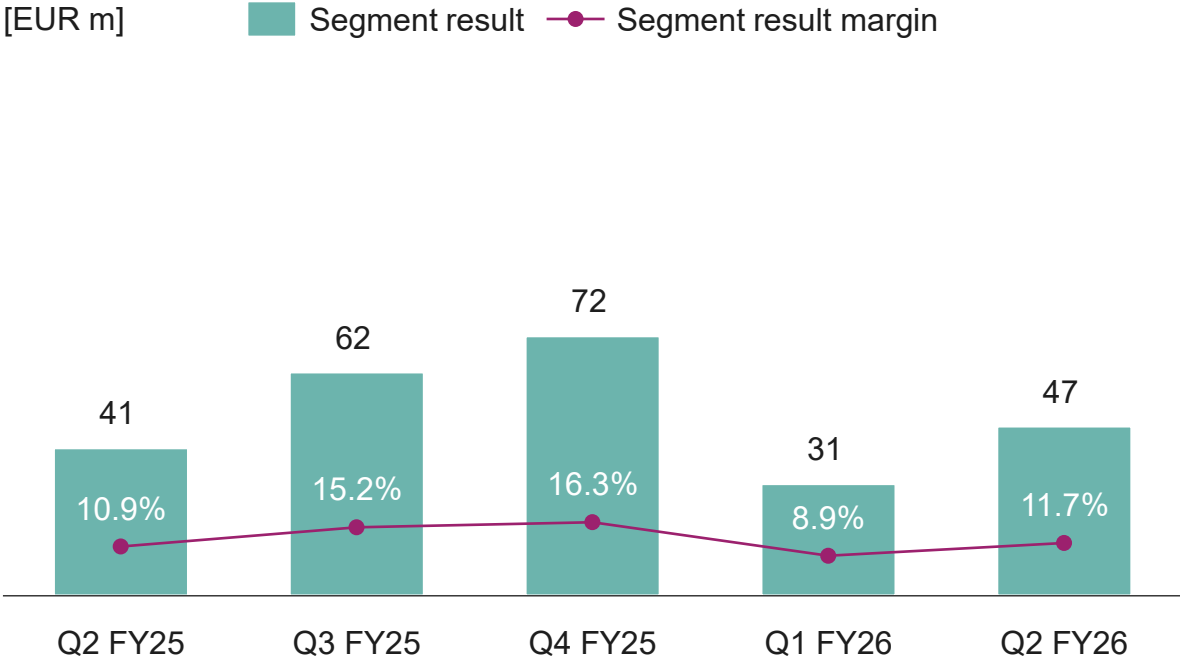
- Constant revenue q-o-q; volume growth offset by low single-digit price declines.
- Segment result margin down sequentially, driven by negative impacts of high-voltage business for electric drivetrains and price adjustments.
- Structural content growth of automotive semis continuing: SDV proliferation accelerating; e-mobility trend intact, yet slower growth than anticipated
- High-voltage power components business for electric drivetrains a drag on growth and margins – refocusing underway

Green Industrial Power (GIP)

Revenues¹



Segment Result¹

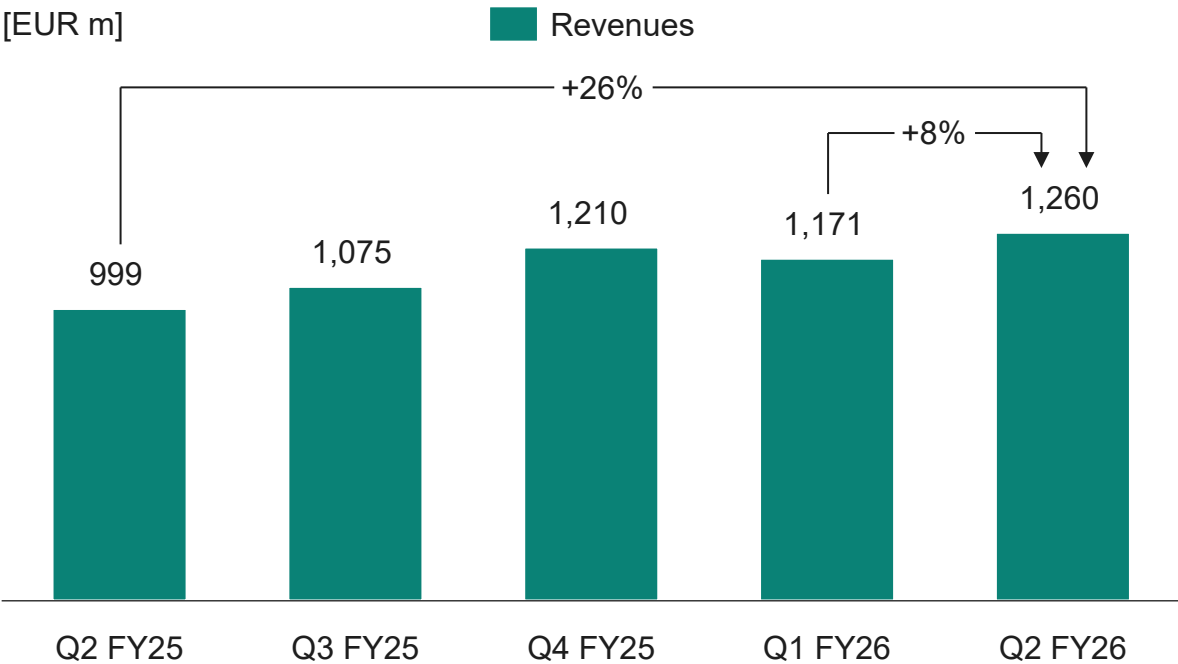


- Revenue growth mainly driven by power infrastructure, HVAC and home appliances.
- Segment result improved, driven by volume fall-through and lower idle costs, outweighing price adjustments.
- Improving industrial market sentiment. Strong structural growth drivers, including grid modernization, AI data center build-outs, support mid-term outlook.

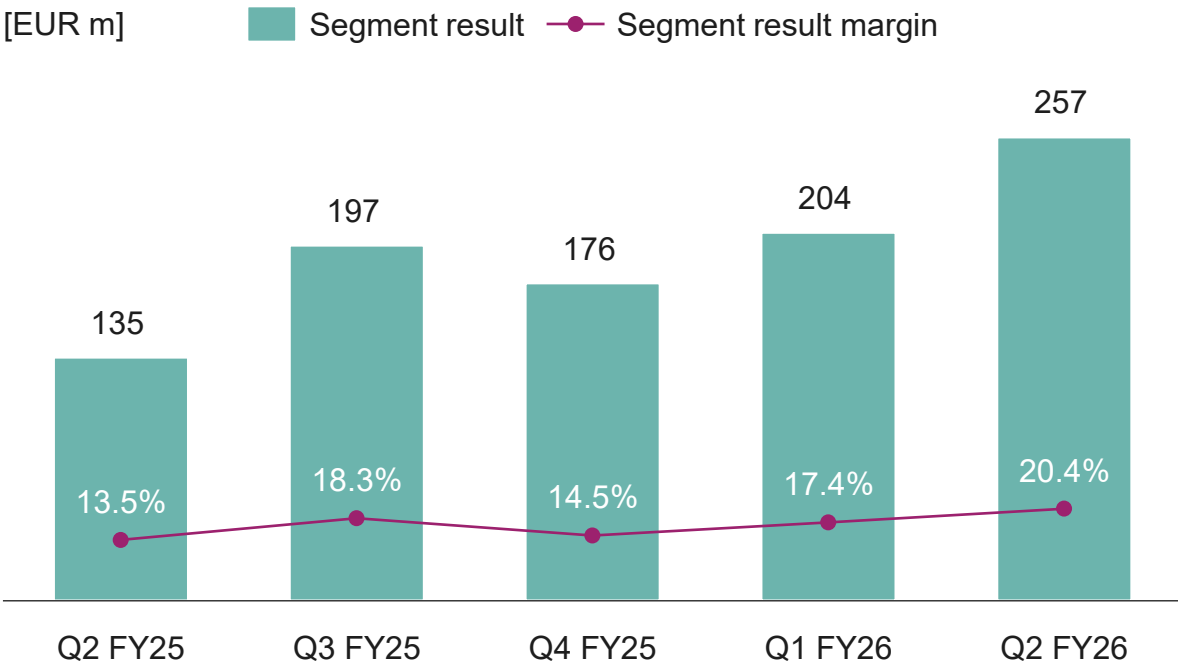
¹ Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

Power & Sensor Systems (PSS)

Revenues¹



Segment Result¹

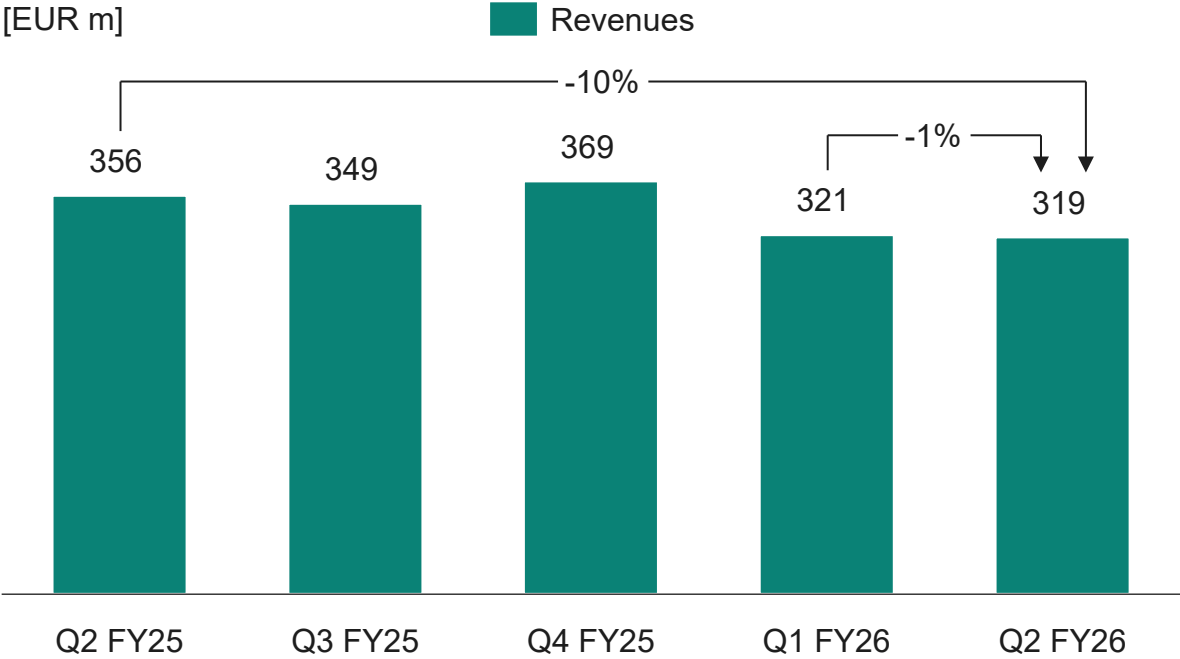


- Strong revenue growth driven by AI power as well as radar sensor business.
- Further segment result margin expansion reflecting profitable growth path of PSS, driven by AI and adjacent areas.
- We reconfirm our FY26 AI revenue target of around €1.5bn and project AI revenues of around €2.5bn in FY27 (irrespective of adverse fx).
- AI power content per kilowatt in the range of \$100–250, with the avg. today of \$175, reflecting broad platform representation and more complex AI rack configurations.

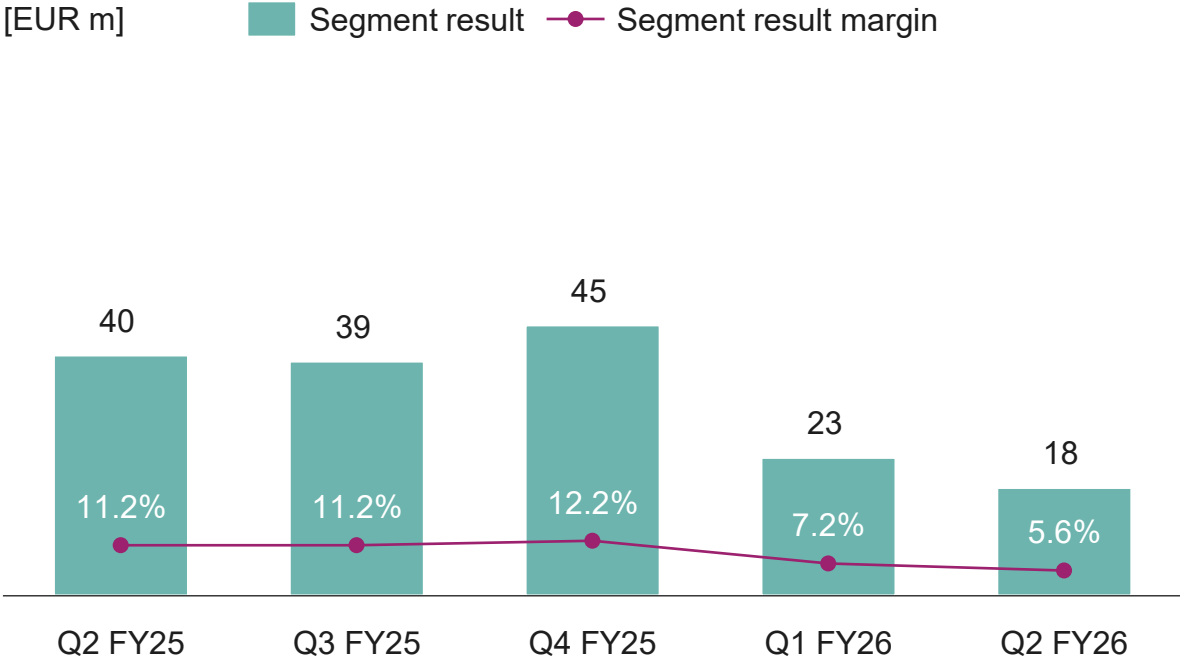
¹ Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

Connected Secure Systems (CSS)

Revenues



Segment Result

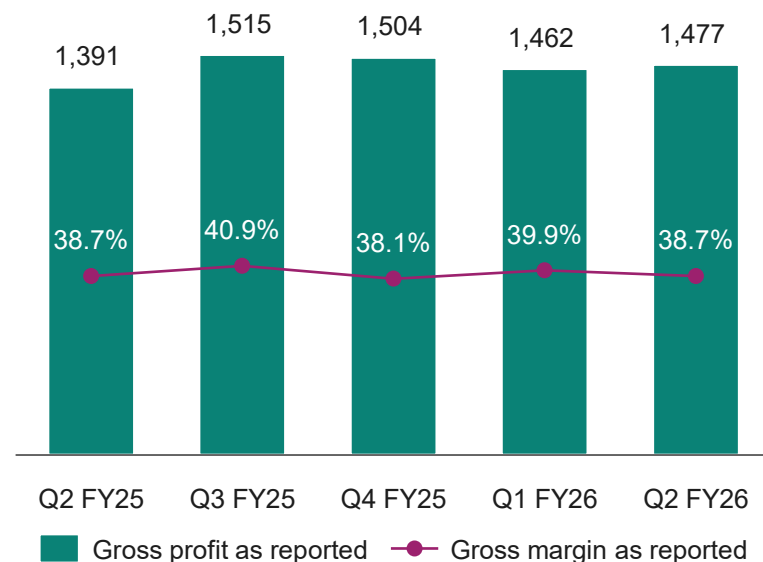


- Rising volumes in IoT-related microcontroller and connectivity solutions, offset by negative effects from identification solutions.
- IoT markets are in the early innings of a gradual recovery, with improving momentum across consumer and industrial applications.
- Growing design-win momentum for edge AI-enabling microcontrollers and secure elements.

Gross margin and Opex

Gross profit

[EUR m]



Therein Non-Segment Result charges

[EUR m]

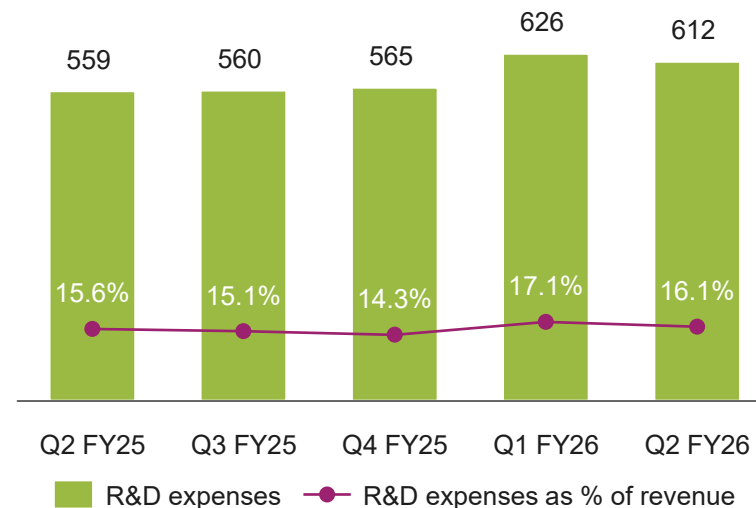
76	76	99	113	85
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Adjusted gross margin

40.9%	43.0%	40.7%	43.0%	41.0%
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R&D

[EUR m]



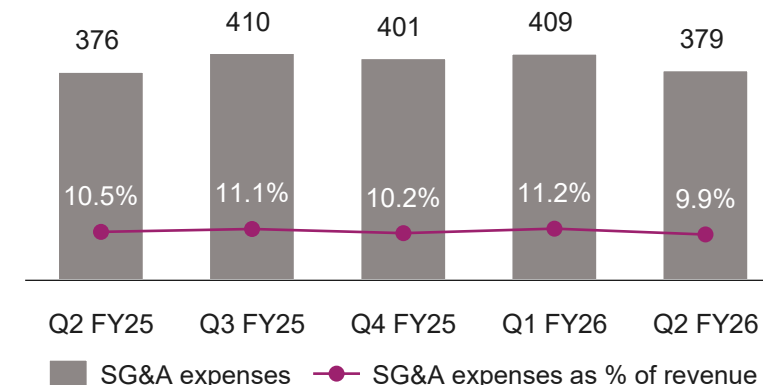
Therein Non-Segment Result charges

[EUR m]

14	18	17	35	29
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SG&A

[EUR m]



Therein Non-Segment Result charges

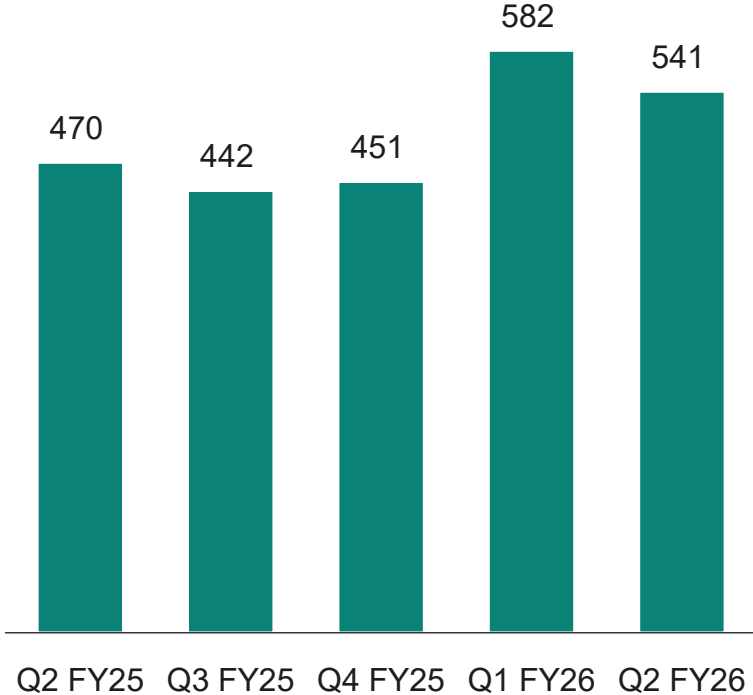
[EUR m]

53	50	67	77	52
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Investments, Depreciation & Amortization and Free Cash Flow

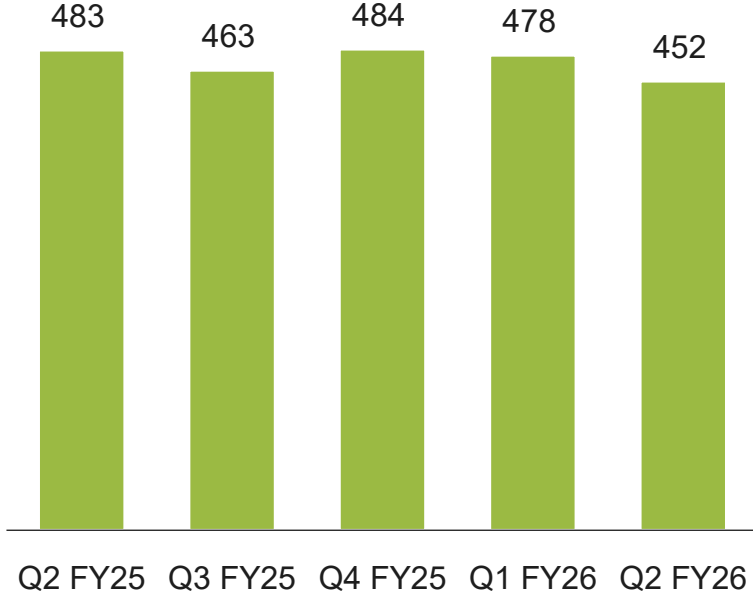
Investments

[EUR m]



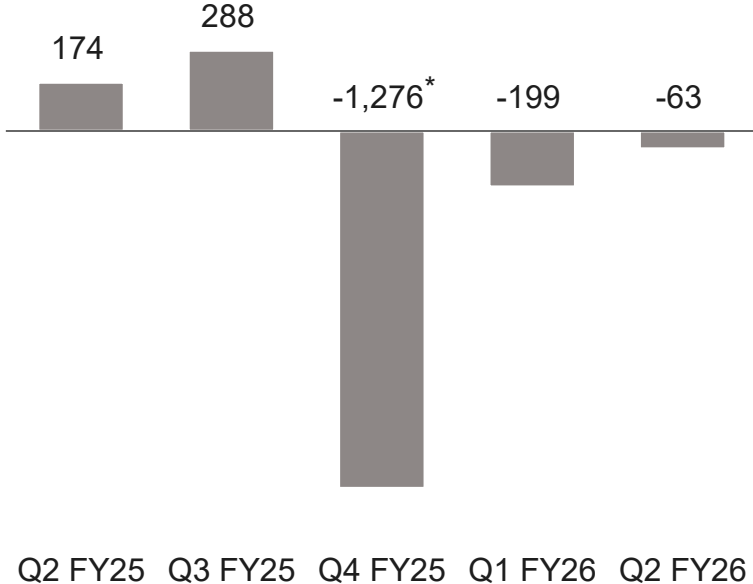
Depreciation & Amortization

[EUR m]



Free Cash Flow

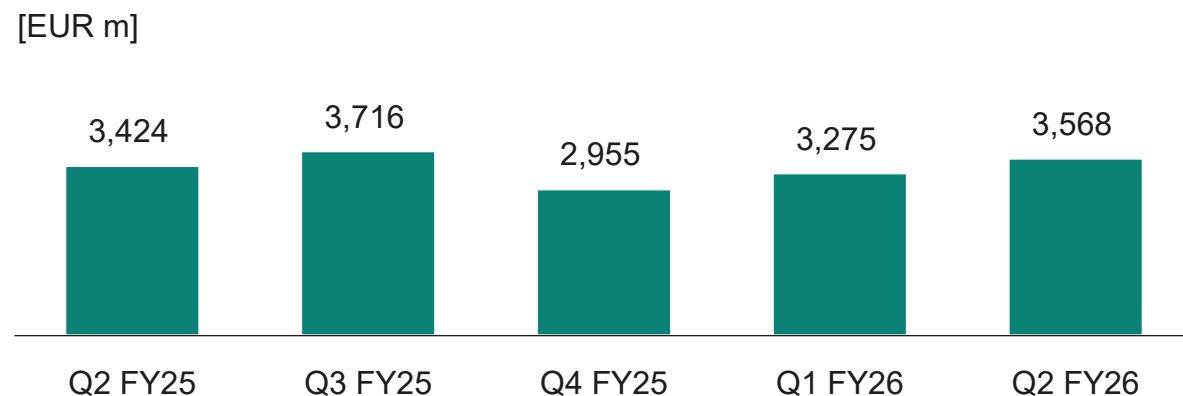
[EUR m]



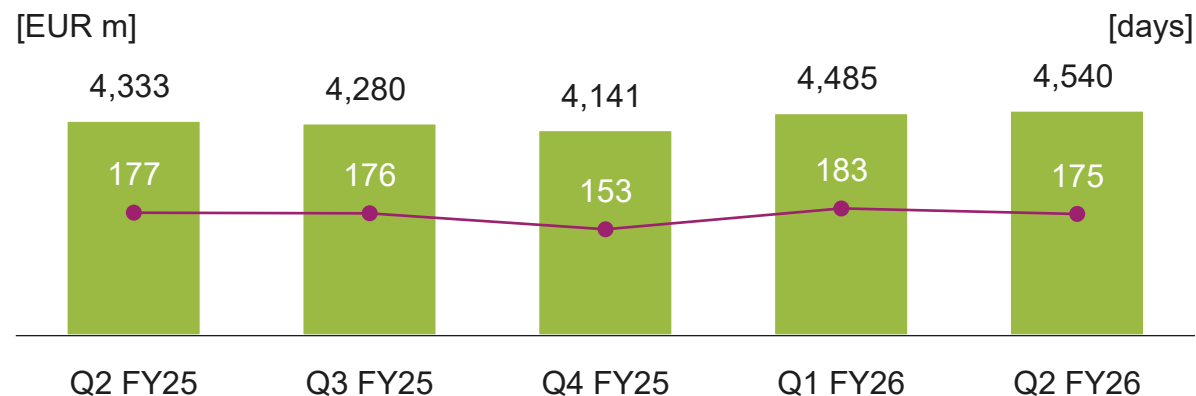
*FCF incl. 2,180m acquisition related outflows for Marvell's automotive Ethernet business

Working capital, in particular trade working capital components

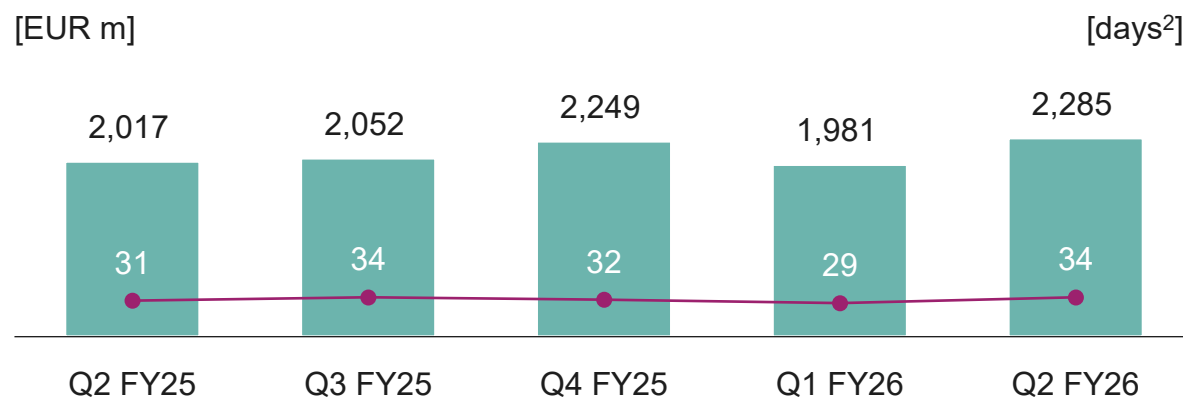
Working capital¹



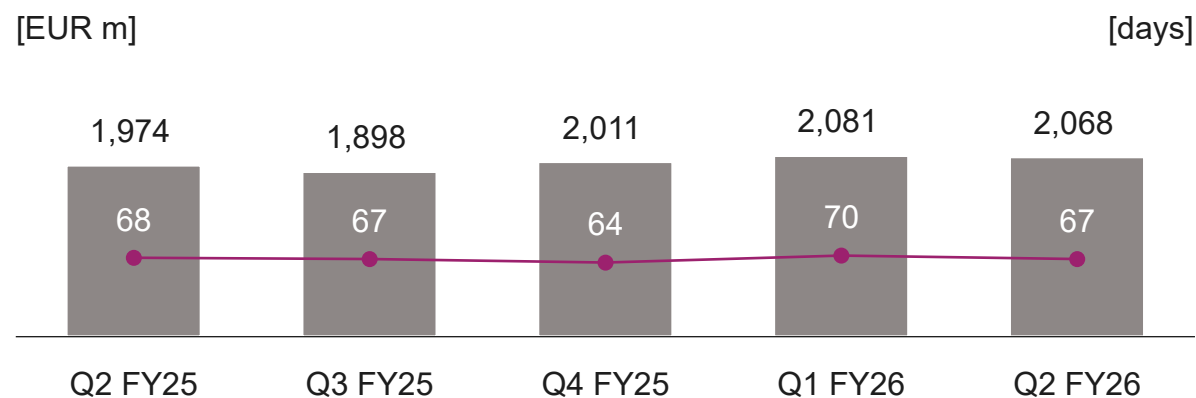
Inventories



Trade receivables



Trade payables

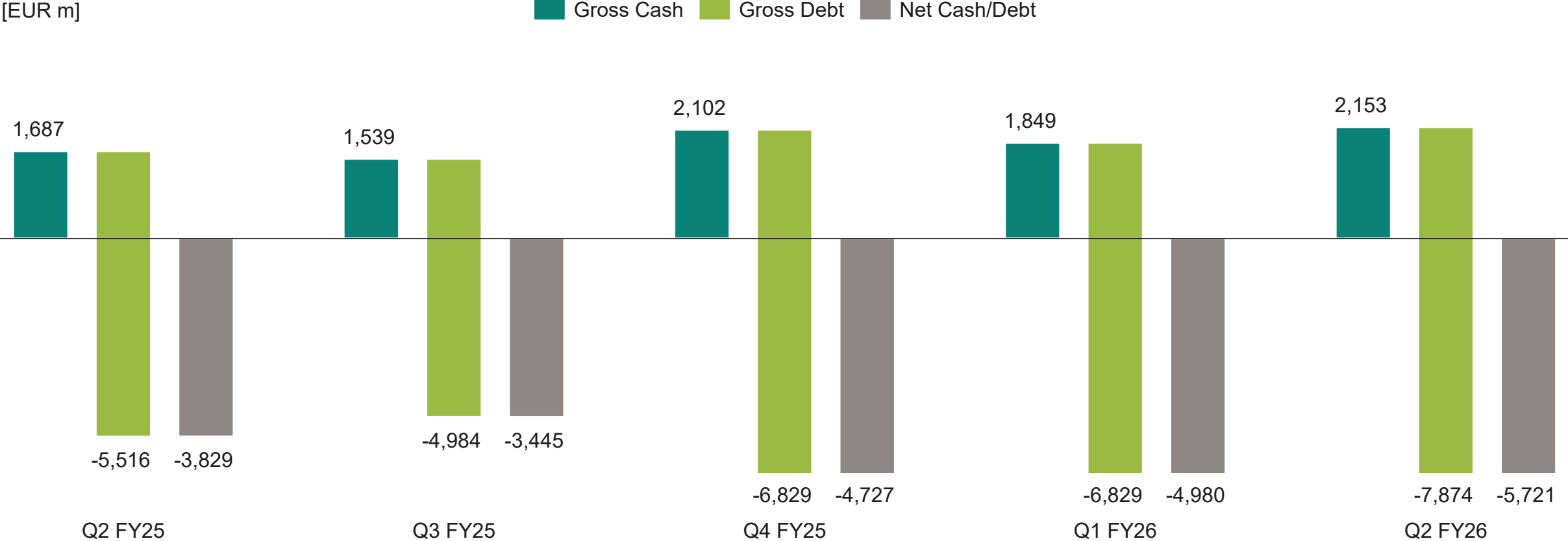


¹ See notes for definition

² The calculation of DSO was adjusted effective 1 October 2025. The adjustment increases the transparency and informative value of the key figure and improves its comparability. The figures for the comparative periods have been adjusted accordingly.

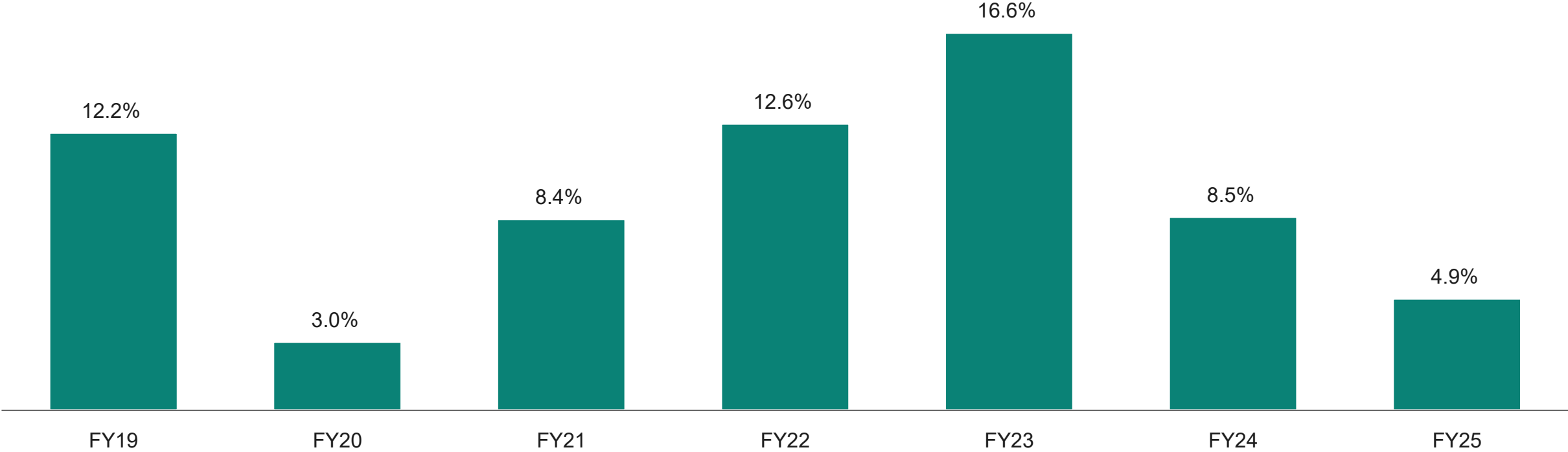
Development of liquidity and debt

Capital structure



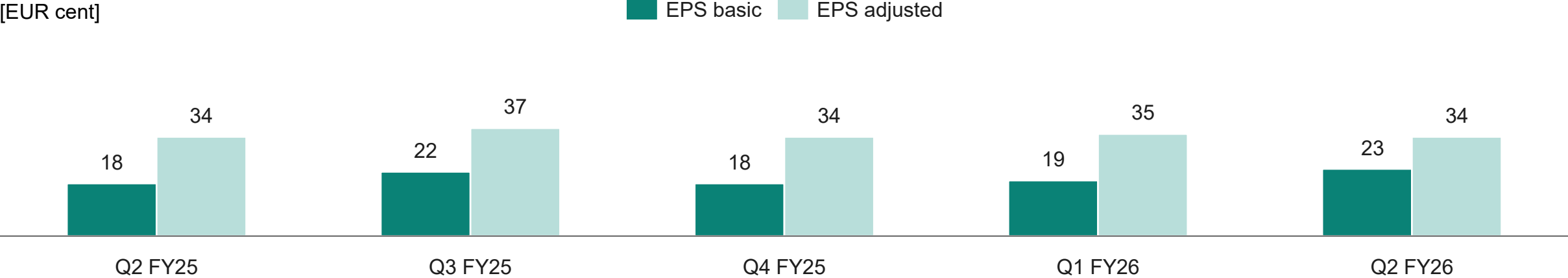
Return on capital employed

Historical development

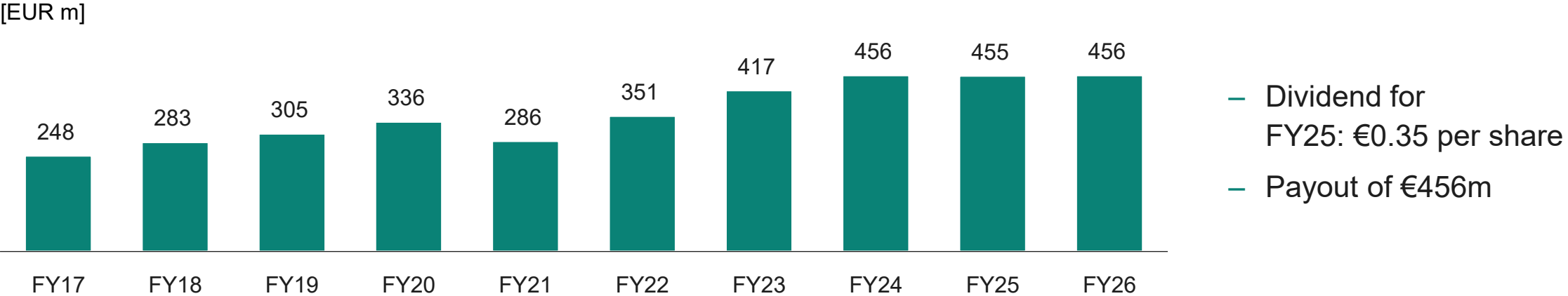


Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations



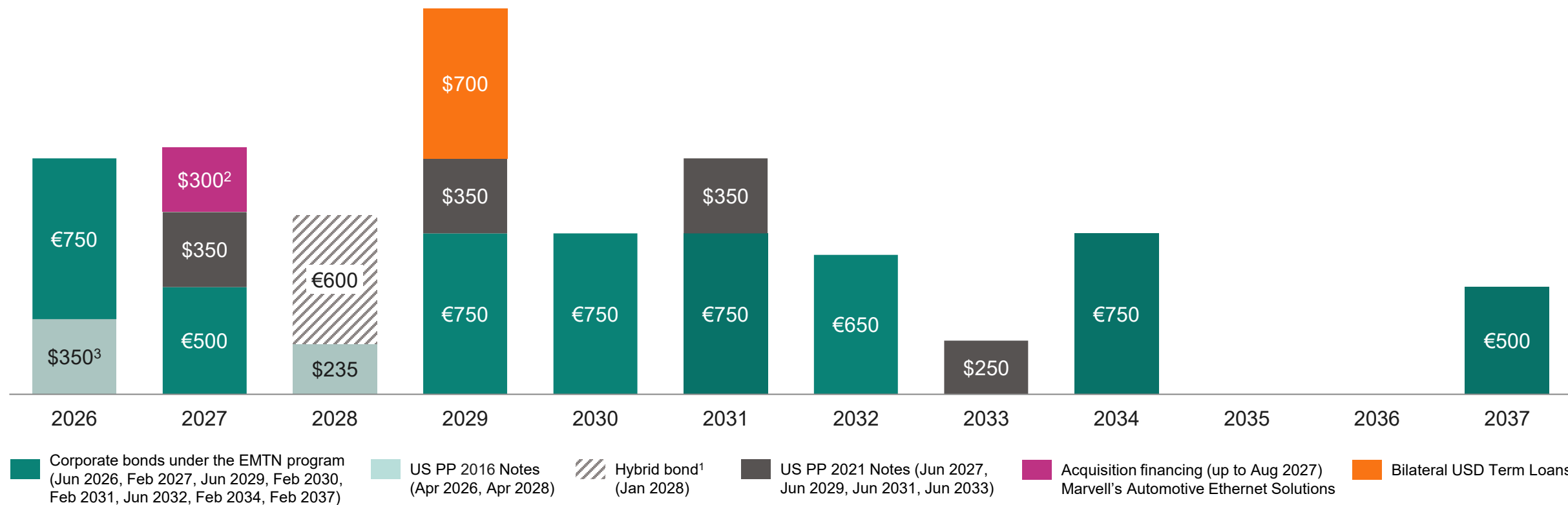
Total cash return to shareholders via dividends



Maturity profile

Calendar years 2026 to 2037

[EUR m; USD m; nominal values]



¹ On 1 Oct 2019, Infineon issued a €600m perpetual hybrid bond with first call date in 2028; the hybrid bond is accounted as equity under IFRS.

² Repaid on April 2nd, 2026 with proceeds from new USD300m USPP with a maturity in 2030, issued on April 1st, 2026.

³ Repaid on April 7th, 2026 with existing cash.

Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility



	Financial Policy Targets	Status Quo (LTM 31 March 2026)
Gross Cash¹	At least 10% of revenue ³	14% of revenue → €2.2bn
Gross Debt²	≤ 2.0x EBITDA	2.2x EBITDA
Comfortable liquidity position	– Flexibility for financing operating activities and investments through the cycle	
Balanced debt position	– Gross debt target commensurate with investment-grade rating	
Rating	Investment grade	BBB+ stable outlook (by S&P Global Ratings)

¹ Gross cash position is defined as cash and cash equivalents plus financial investments | ² Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization | ³ Gross cash target: At least 10 percent of revenue on average throughout the fiscal year



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Disclaimer

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Glossary

AC	alternating current
AD	automated driving
ADAS	advanced driver assistance system
AI	artificial intelligence
BBU	battery back-up unit
BEV	battery electric vehicle
BLE	Bluetooth low energy
BMS	battery management system
BoM	bill of materials
BVM	backside vertical module
DC	direct current
DSC/SSC	double/single sided cooling
E/E	electrical/electronic architecture
ECPD	electronic circuit protection device
ECU	electronic control unit
EMS	electronics manufacturing service
ESS	energy storage system
EV	electric vehicle
FCEV	fuel cell electric vehicle
FHEV/MHEV	full/mild hybrid electric vehicle
GaN	gallium nitride
GPU	graphic processing unit
HEMT	high-electron-mobility transistor
HFT	high-frequency transformation
HV	high voltage
HVAC	heating, ventilation, air conditioning
HVDC	high-voltage direct current
IBC	intermediate bus converter
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	internet of things
LED	light-emitting diode
LLC	resonant tank converter

MCU	microcontroller unit
LV	low voltage
MEMS	micro electro-mechanical system
MOSFET	metal-oxide silicon field-effect transistor
MPU	micro processing unit
MV	medium voltage
NFC	near-field communication
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PCS	power capacitor system
PFC	power factor correction
PDN	power delivery network
PHEV	plug-in hybrid electric vehicle
PHY	physical layer transceiver
PMIC	power management integrated circuits
PSU	power supply unit
RAM	random access memory
RF	radio frequency
SAE	Society of Automotive Engineers
SAM	serviceable available market
SDK	software development kit
Si	silicon
SiC	silicon carbide
SiVR	substrate integrated voltage regulator
SoC	system-on-chip / state of charge
SSCB	solid-state circuit breaker
SST	solid-state transformer
ToF	time-of-flight
UPS-ESS	uninterruptable power supply energy storage solution
UWB	ultra-wideband
VRM	voltage regulator module
xSC	different switched capacitor topologies

Notes and ESG footnotes

Investments =	'Investments in property, plant and equipment' + 'Investments in other intangible assets and capitalized developments costs'
Adjusted Free Cash Flow Margin =	Adjusted for large investments in frontend buildings and major M&A transactions, for full definition see chapter "Internal management system" in the annual report
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale' – ('Total Current liabilities' – 'Short-term financial debt and current maturities of long-term financial debt' – 'Liabilities classified as held for sale')
RoCE =	'Operating profit from continuing operations'/'Capital Employed' = 'Profit (loss) from continuing operations adjusted for interest result'/'Capital Employed'
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term financial debt and current portion of long-term financial debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories'/'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables'/'[Cost of goods sold' + 'Purchase of property, plant and equipment']') x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables' - 'reimbursement obligation' + 'contract assets') / 'revenue' x 90
Order backlog =	The total amount of orders received regardless of their current status

ESG footnotes:

- 1) This figure takes into account manufacturing, transportation, own vehicles, travel, raw materials and consumables, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. as well as direct and indirect energy-related emissions by manufacturing service providers. It is based on data collected internally and publicly available conversion factors and relates to the 2021 fiscal year.
- 2) This figure is based on internally established criteria, which are described in the explanatory notes. The figure relates to the 2020 calendar year and takes into account the following application areas: automotive, LED, induction cookers, servers, renewable energy (wind, photovoltaic) and cell phone chargers as well as drives. CO₂ savings are calculated based on the potential savings generated by technologies in which semiconductors are used. The CO₂ savings are allocated based on Infineon's market share, semiconductor share, and the lifetime of the technologies concerned, based on internal and external experts' estimations. Despite the fact that carbon footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.
- 3) Carbon neutrality is defined in terms of Scope 1 and Scope 2 emissions.

Financial calendar

Date	Event	Location
18 May 2026	JPM Global TMT Conference	Boston
20 May 2026	Berenberg European Conference	New York
20 May 2026	UBS Technology, Media and Internet Conference	London
21 May 2026	JPM TMT Conference	London
27 May 2026	DB Access Championship Conference	Frankfurt
2 June 2026	Bank Pekao Technology & Consumer Conference	virtual
2 June 2026	BofA Global Tech Conference	San Francisco
2-3 June 2026	BNP Paribas CEO Conference	Paris
8 June 2026	Barclays EMEA Technology Conference	London
9 June 2026	BofA C-Suite TMT Conference	London
9 June 2026	PCIM	Nürnberg
23 June 2026	Jefferies German & Swiss Corporate Conference	Baden-Baden
5 August 2026 ¹	Earnings release for the third quarter of the 2026 fiscal year	
10 November 2026 ¹	Earnings release for the fourth quarter and the 2026 fiscal year	

¹ Preliminary

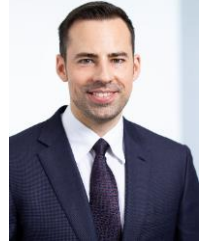
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